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**Yilmaz et al.**

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(54) **POLISHING SYSTEM HAVING A TRACK**

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(75) Inventors: **Alpay Yilmaz**, San Jose, CA (US); **Allen L. D'Ambra**, Burlingame, CA (US); **Jagan Rangarajan**, Fremont, CA (US); **Lakshmanan Karuppiah**, San Jose, CA (US)

(73) Assignee: **Applied Materials, Inc.**, Santa Clara, CA (US)

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**B24B 49/00** (2012.01)  
**B24B 5/00** (2006.01)

(52) **U.S. Cl.** ..... **451/11; 451/285; 451/6**

(58) **Field of Classification Search** ..... **451/9-11, 451/285-289, 5, 6**

See application file for complete search history.

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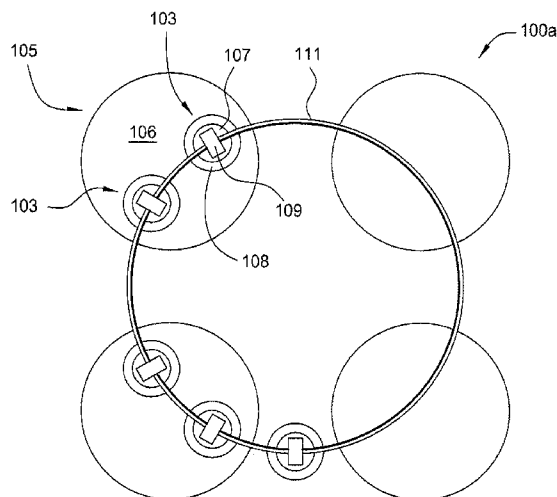
*Primary Examiner* — Dung Van Nguyen

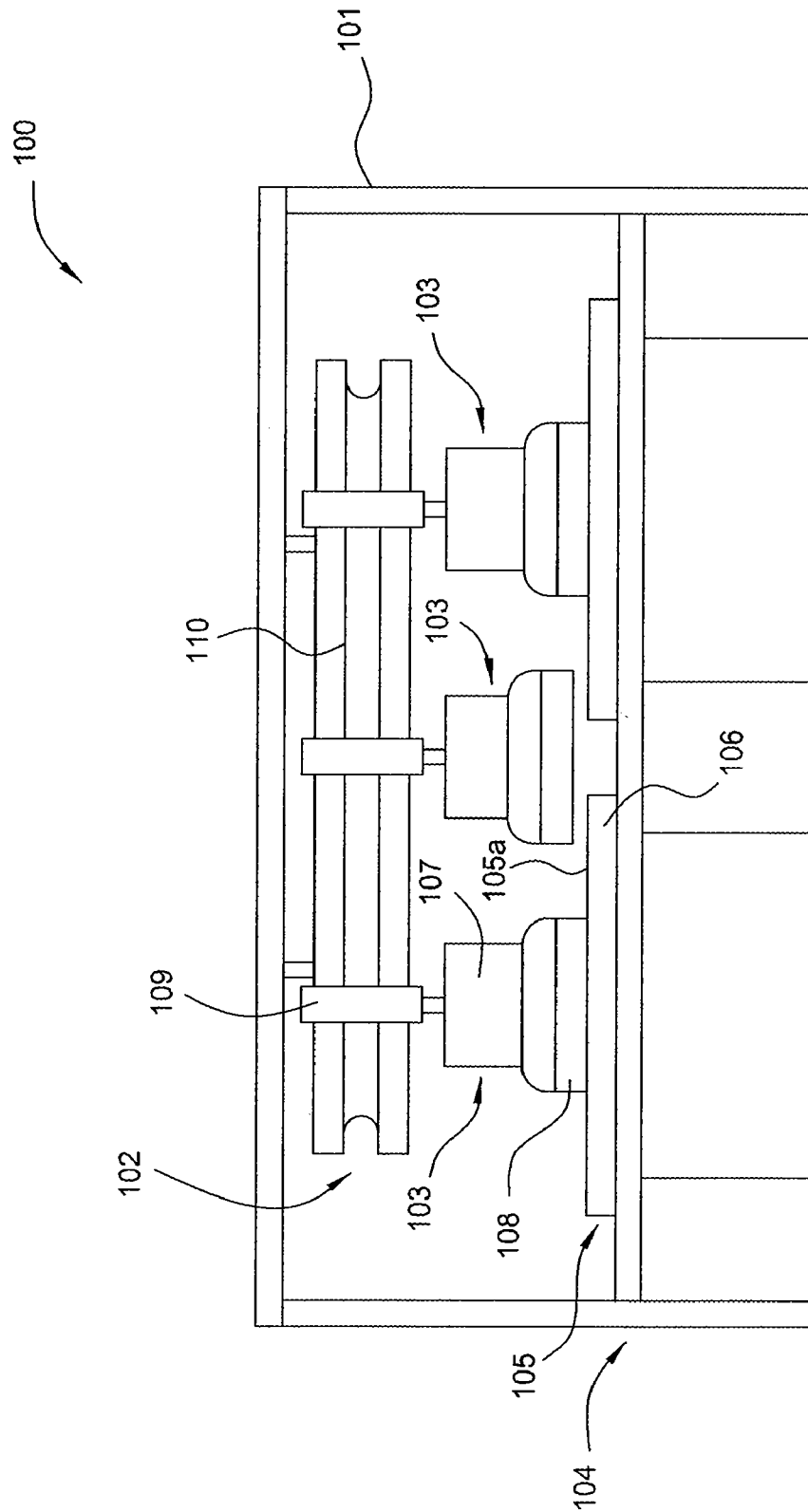
(74) *Attorney, Agent, or Firm* — Patterson & Sheridan, LLP

(57) **ABSTRACT**

Embodiments described herein relate to a track system in a polishing system. One embodiment described herein provides a track system configured to transfer polishing heads in a polishing system. The track system comprises a supporting frame, a track coupled to the supporting frame and defining a path along which the polishing heads are configured to move, and one or more carriages configured to carry at least one polishing head along the path defined by the track, wherein the one or more carriages are coupled to the track and independently movable along the track.

**21 Claims, 42 Drawing Sheets**



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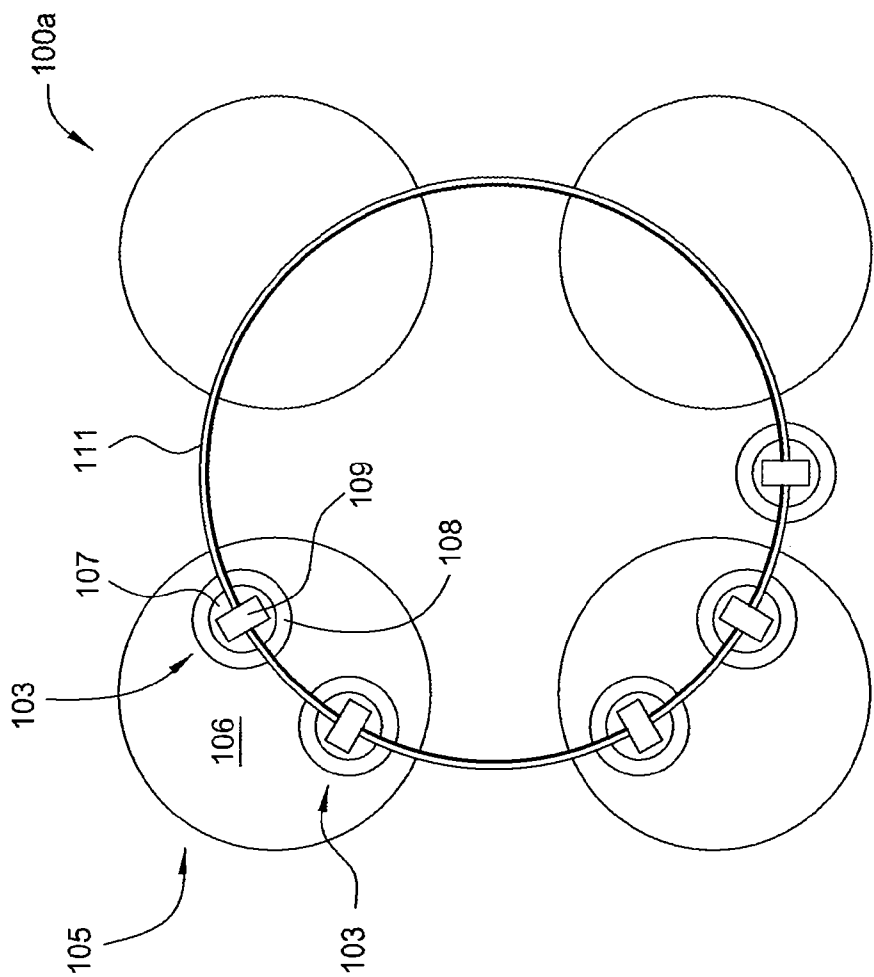


FIG. 2A

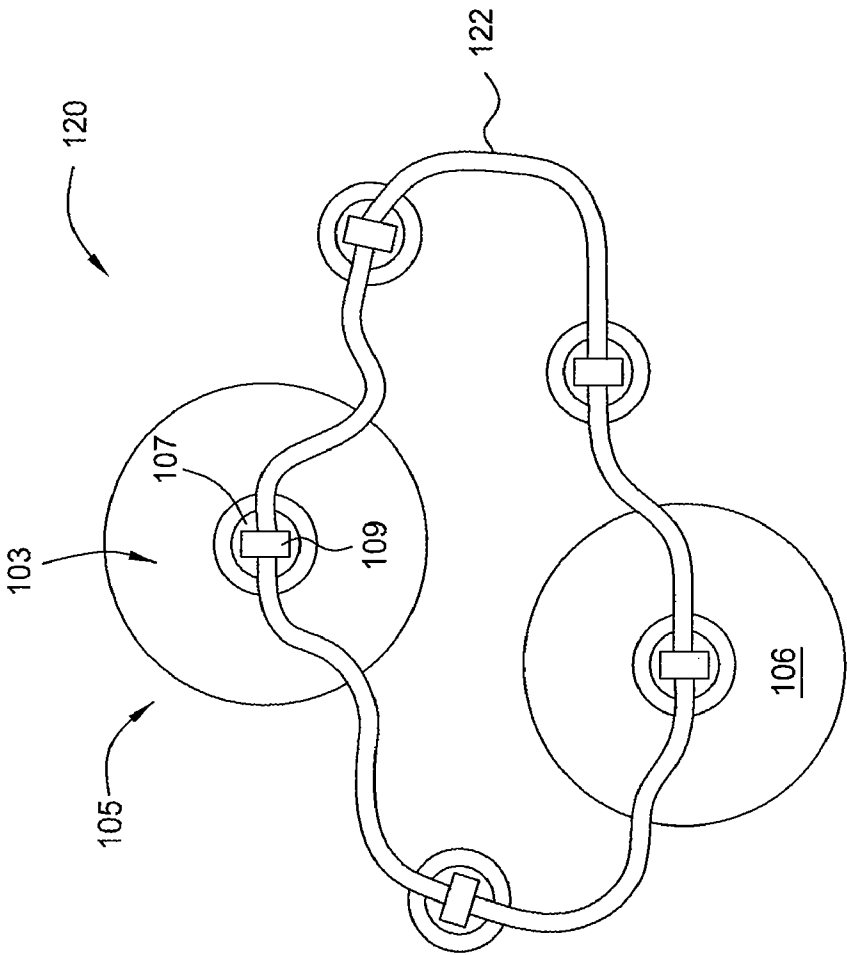


FIG. 2B

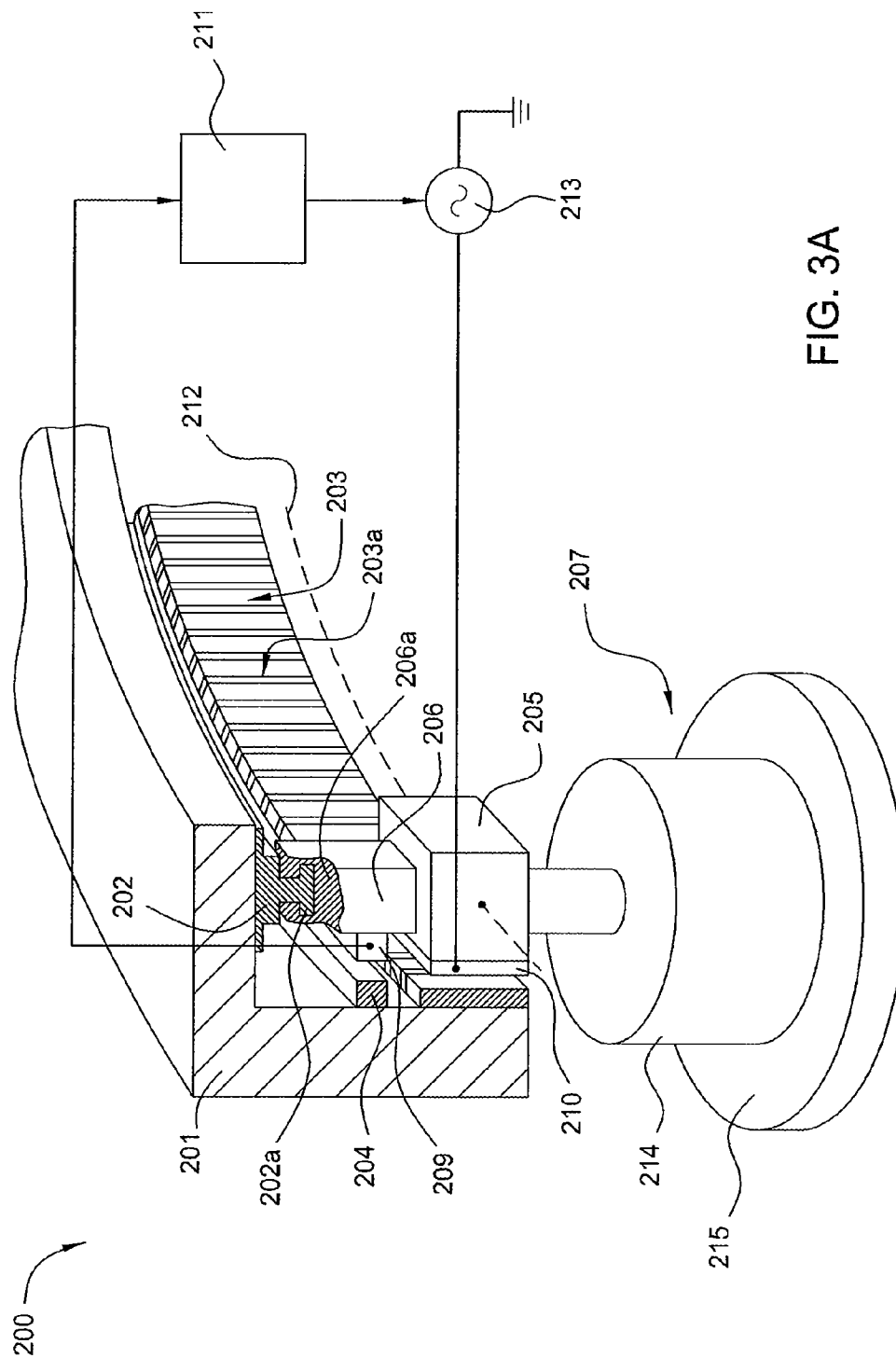


FIG. 3A

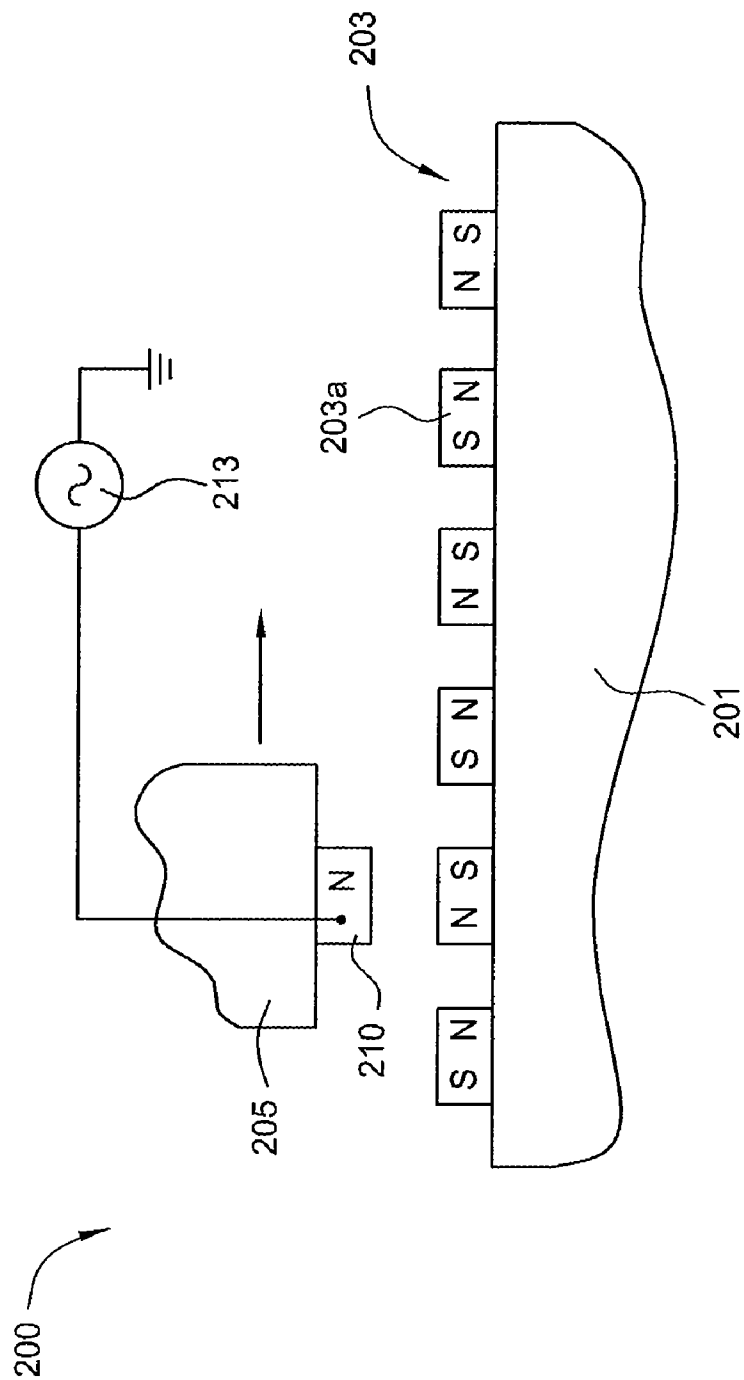


FIG. 3B

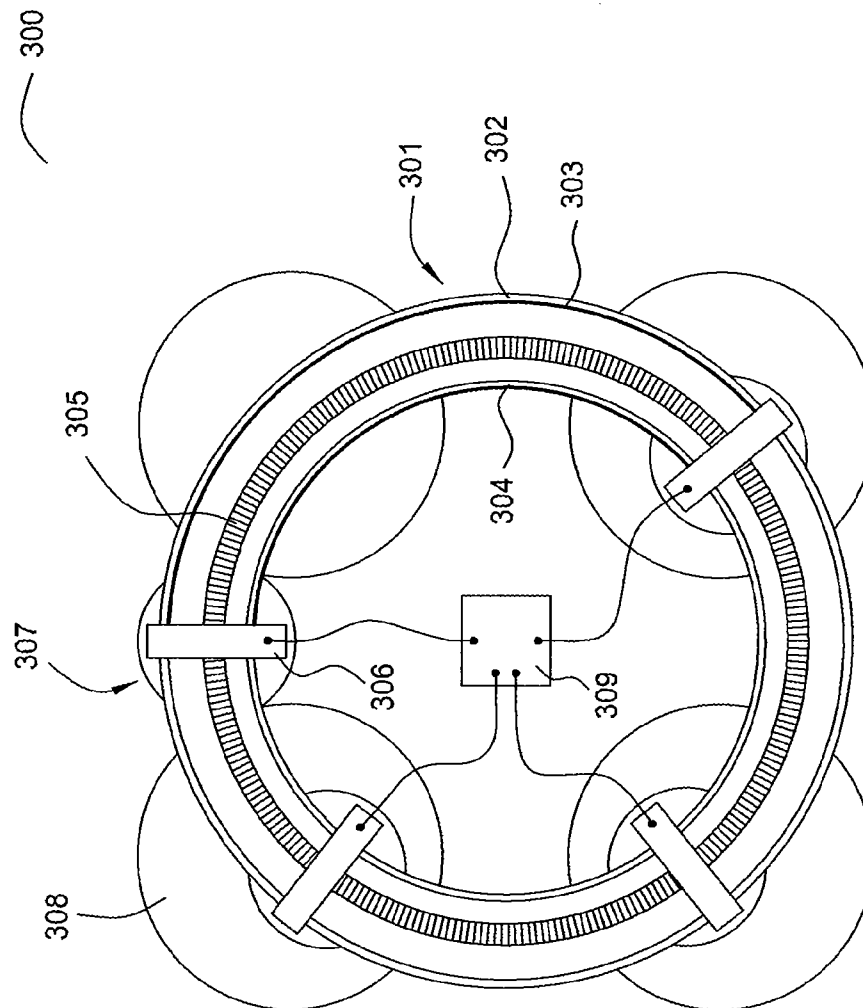
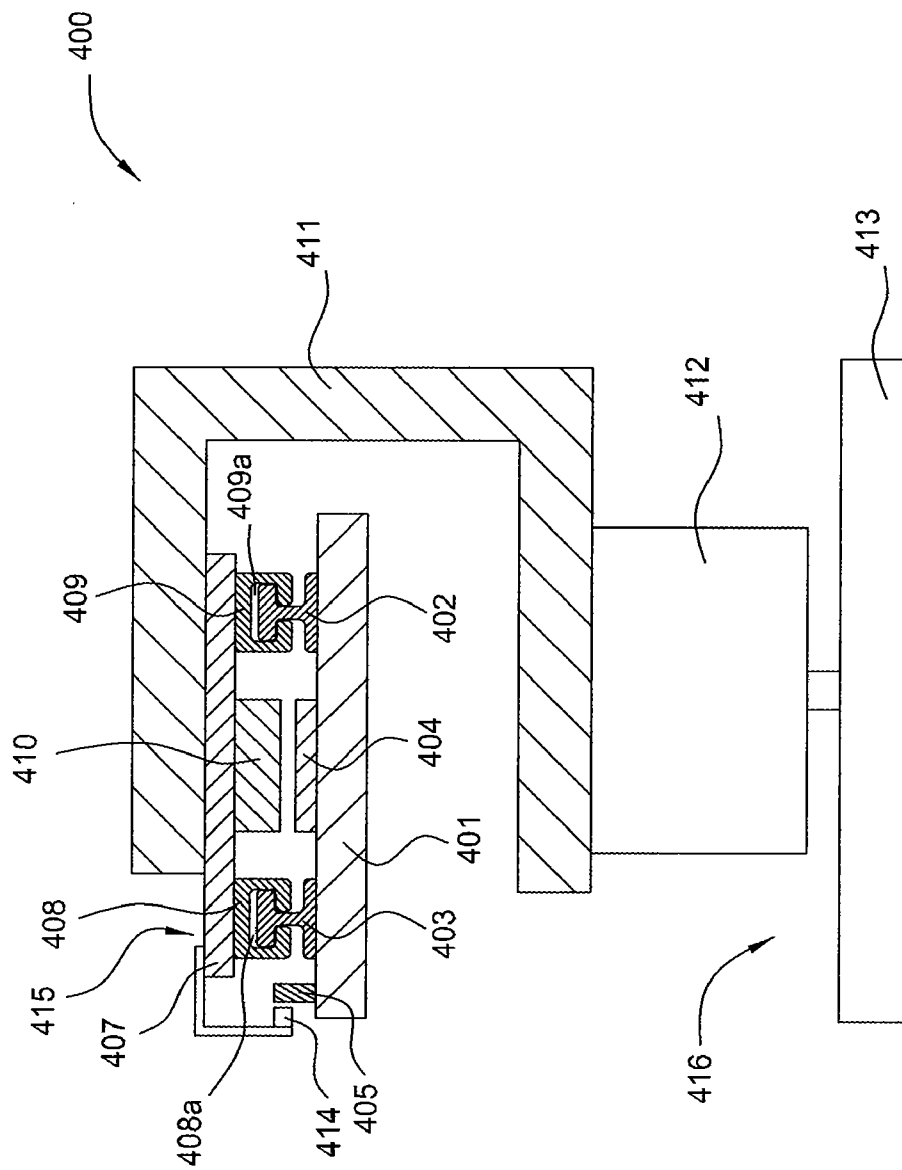


FIG. 4



**FIG. 5**



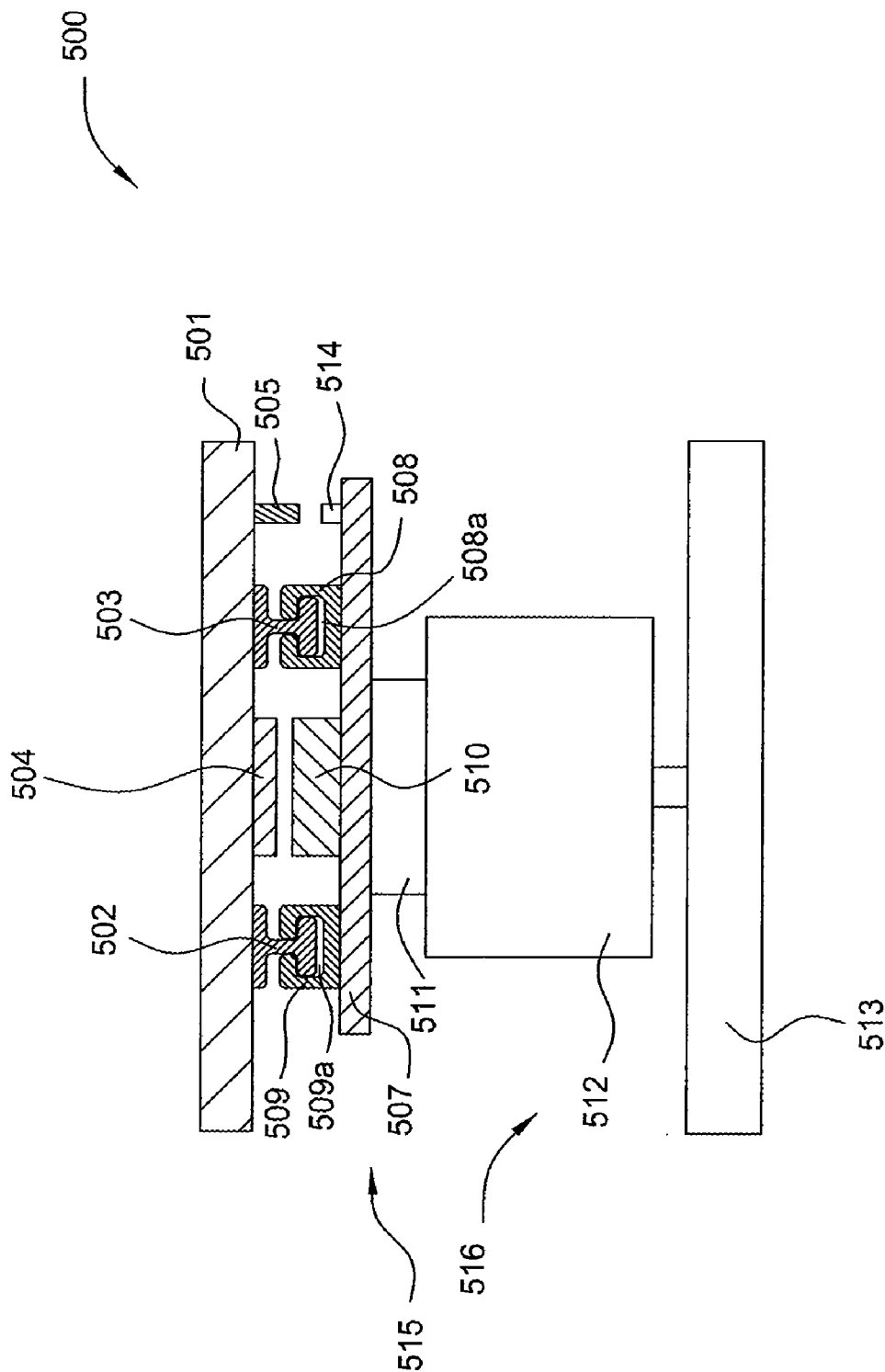


FIG. 6

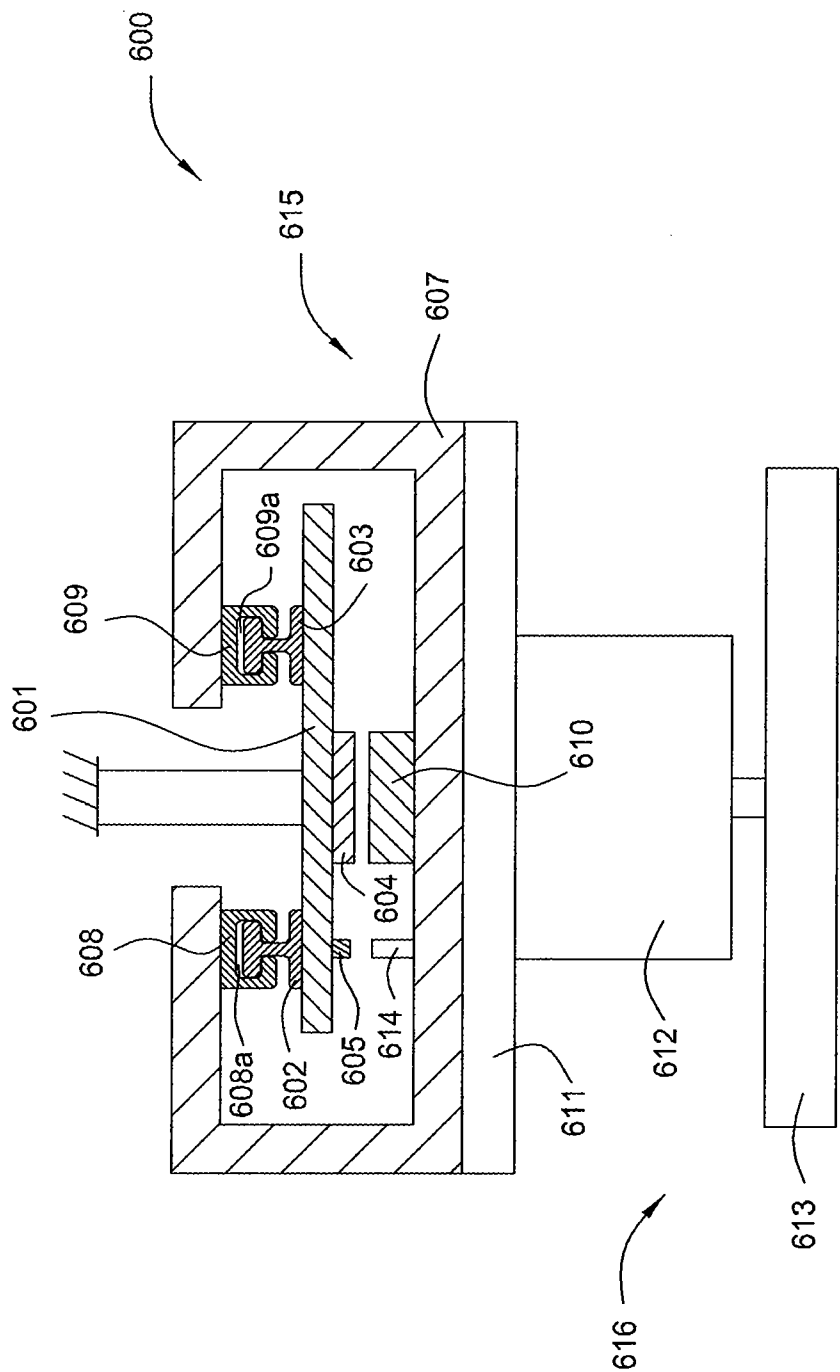
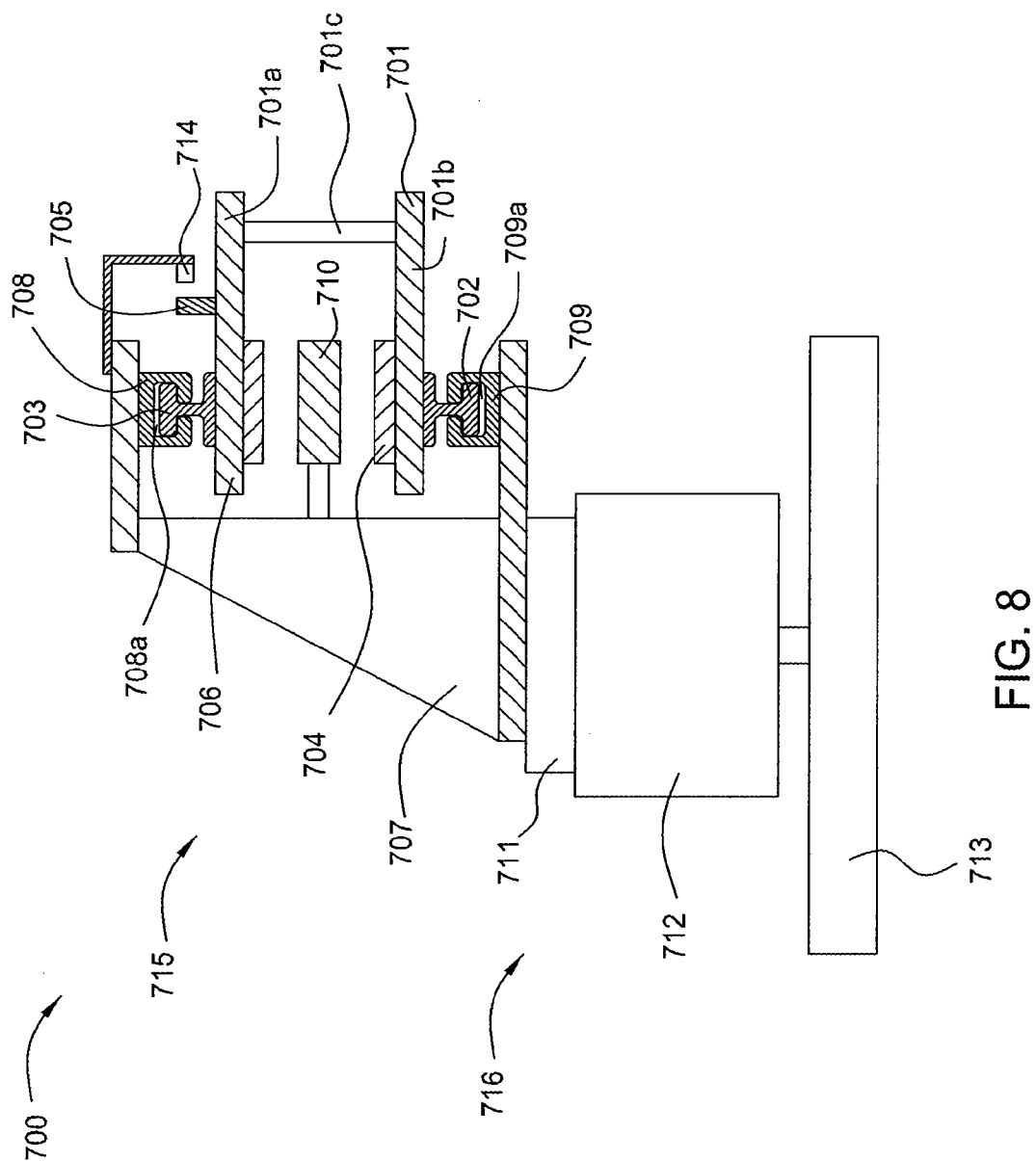


FIG. 7



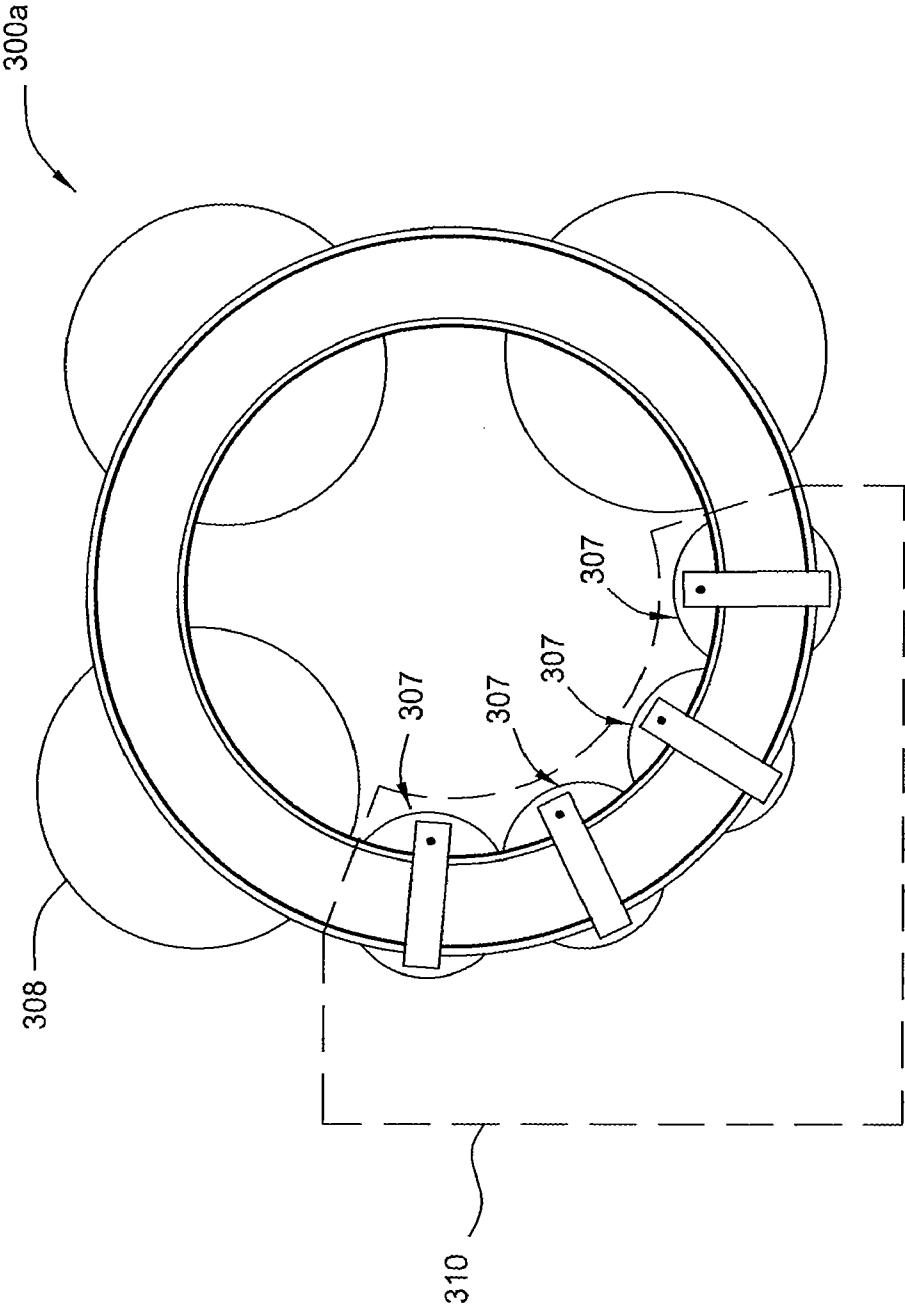


FIG. 9

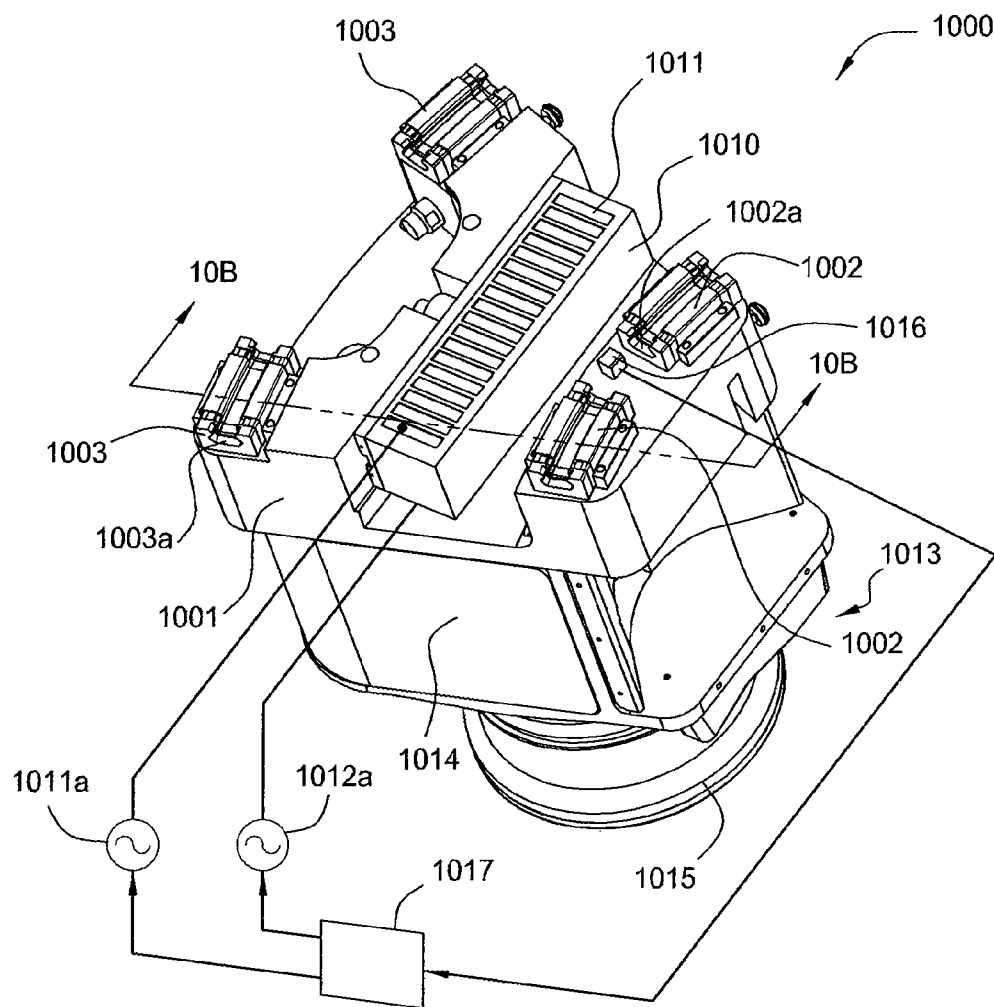


FIG. 10A

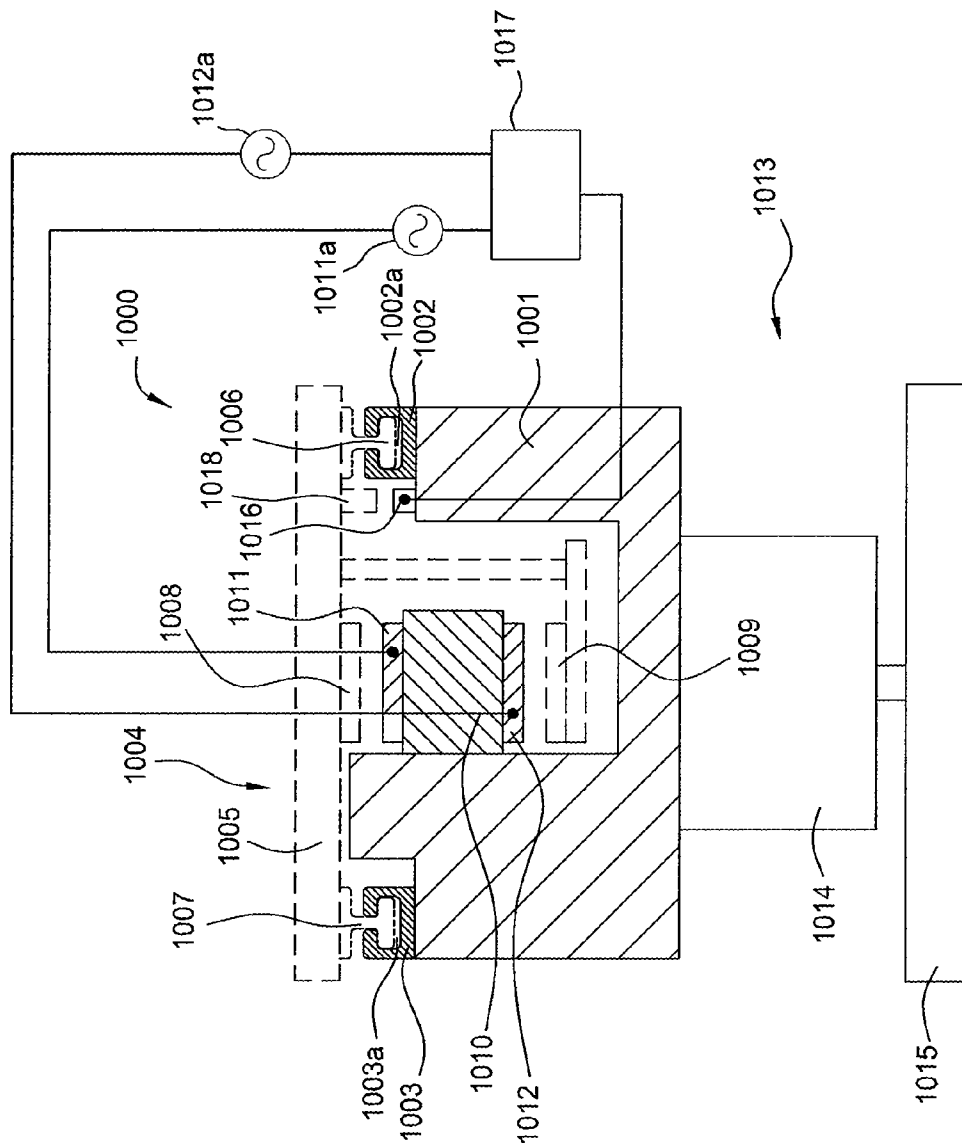


FIG. 10B

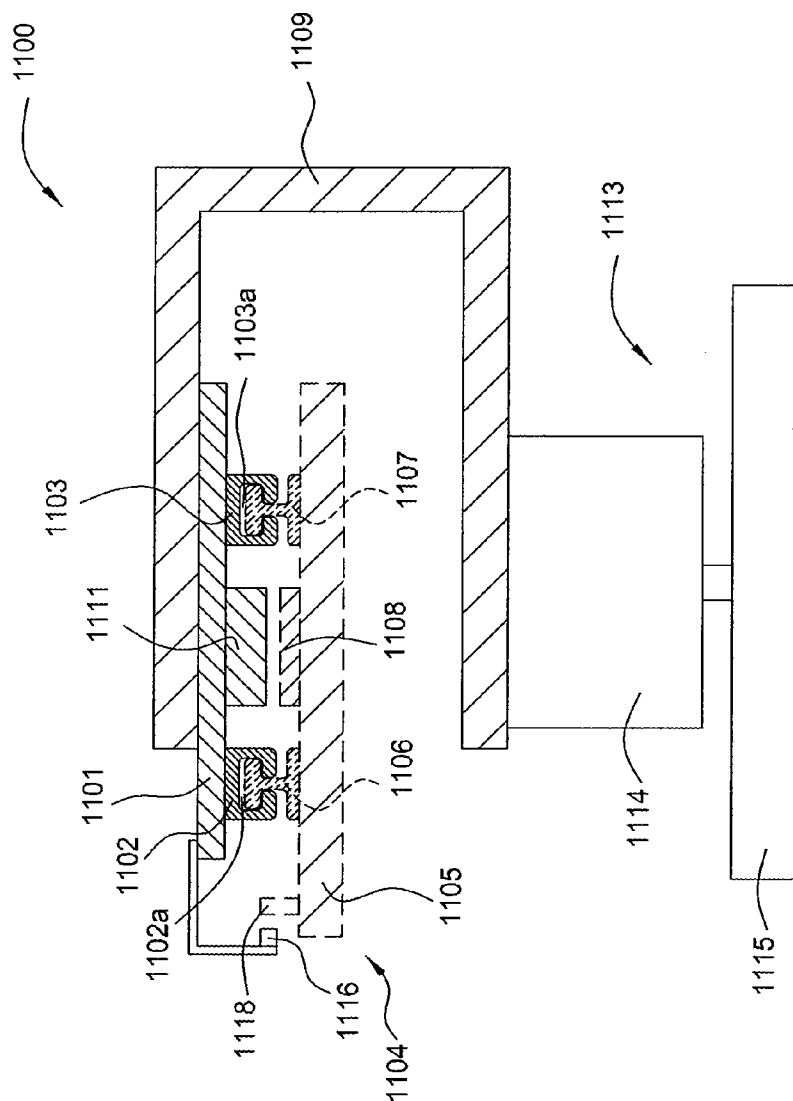


FIG. 11A

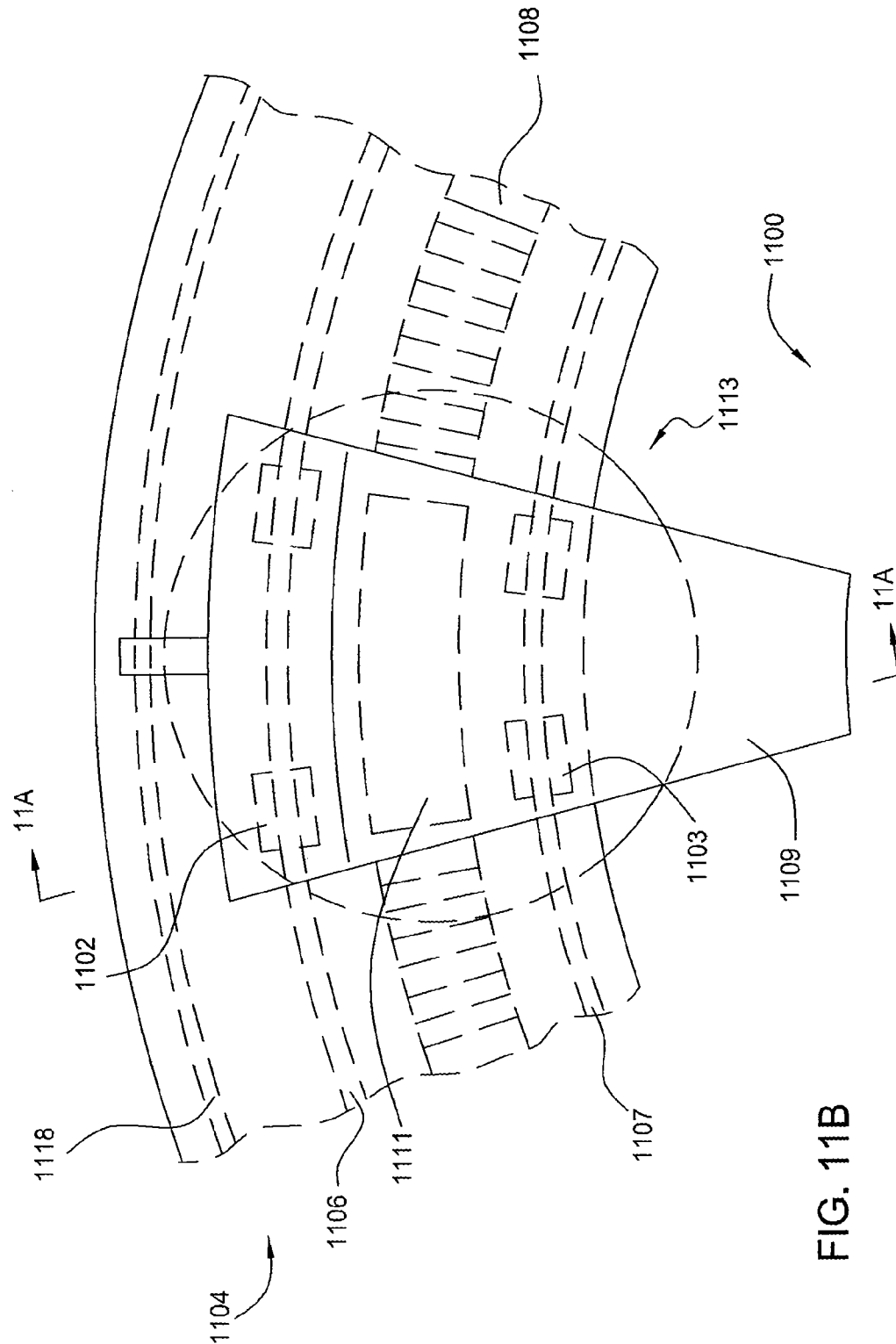


FIG. 11B



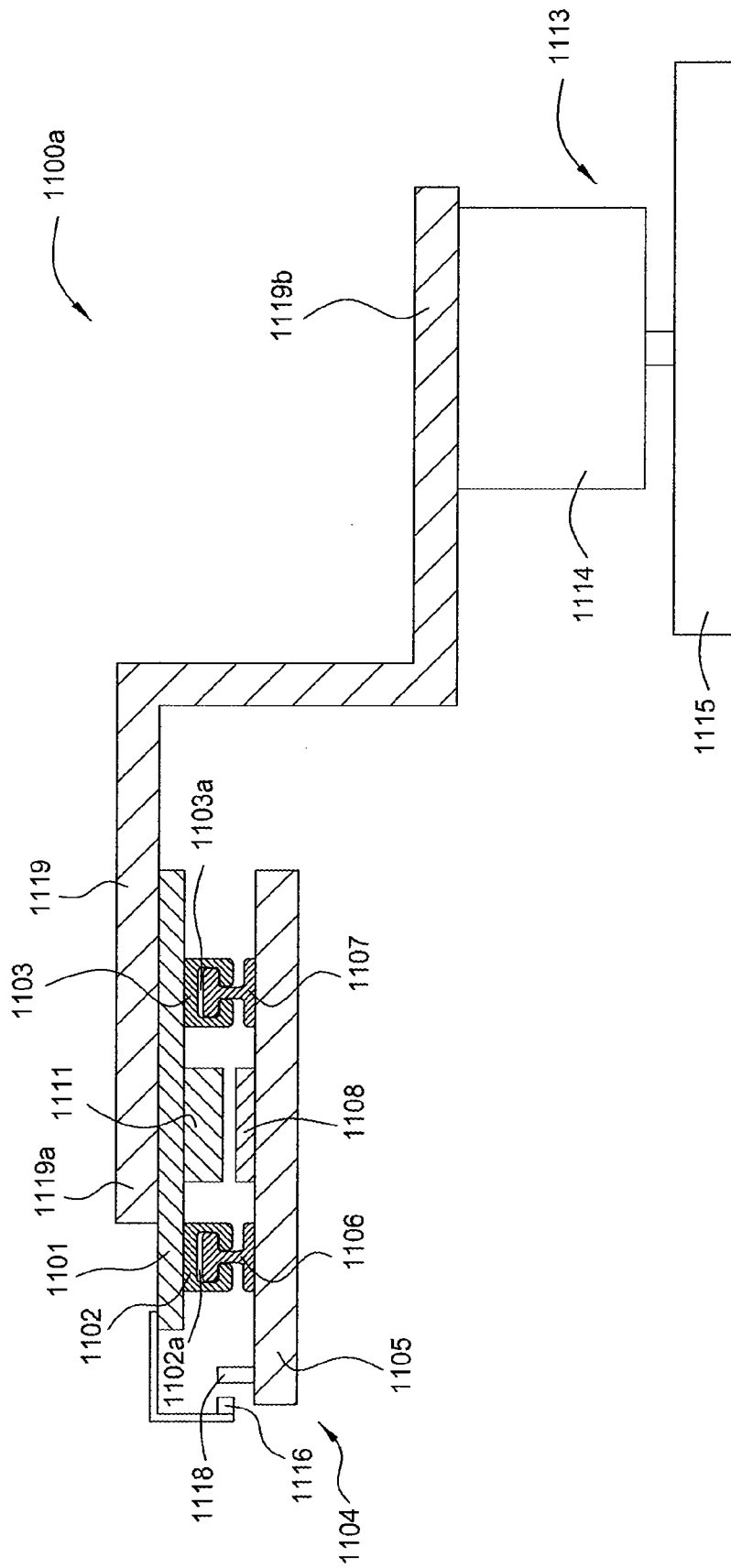


FIG. 12

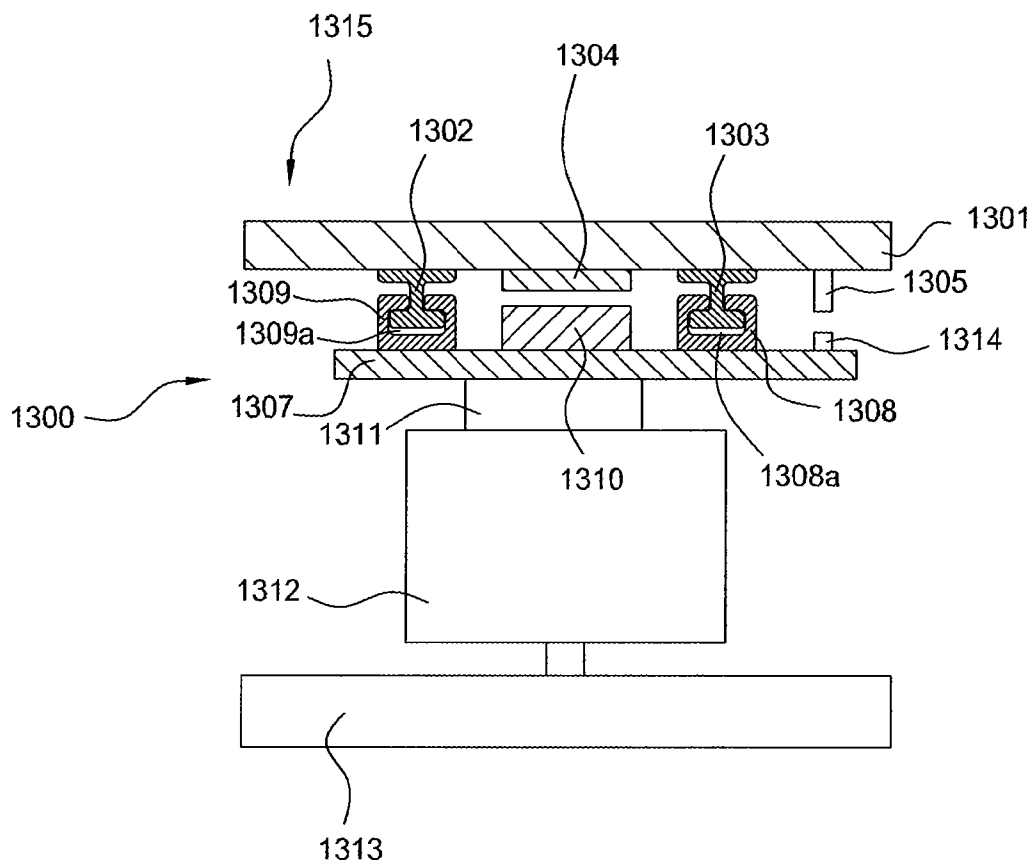


FIG. 13

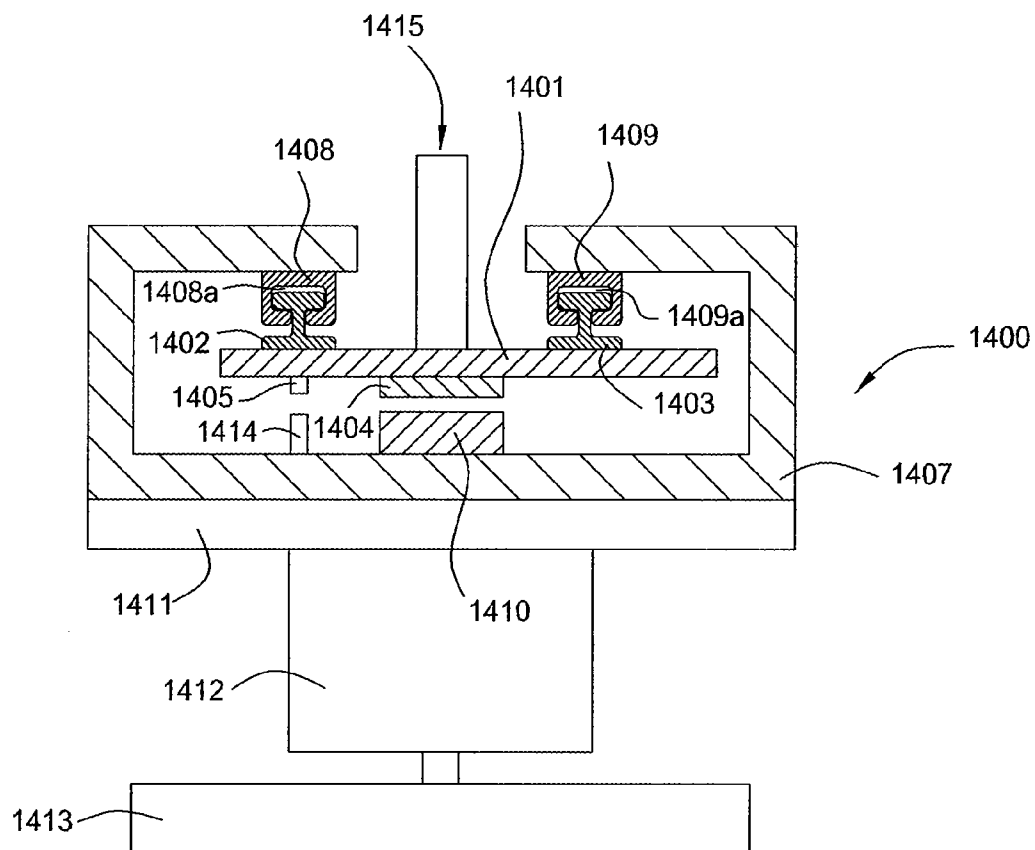
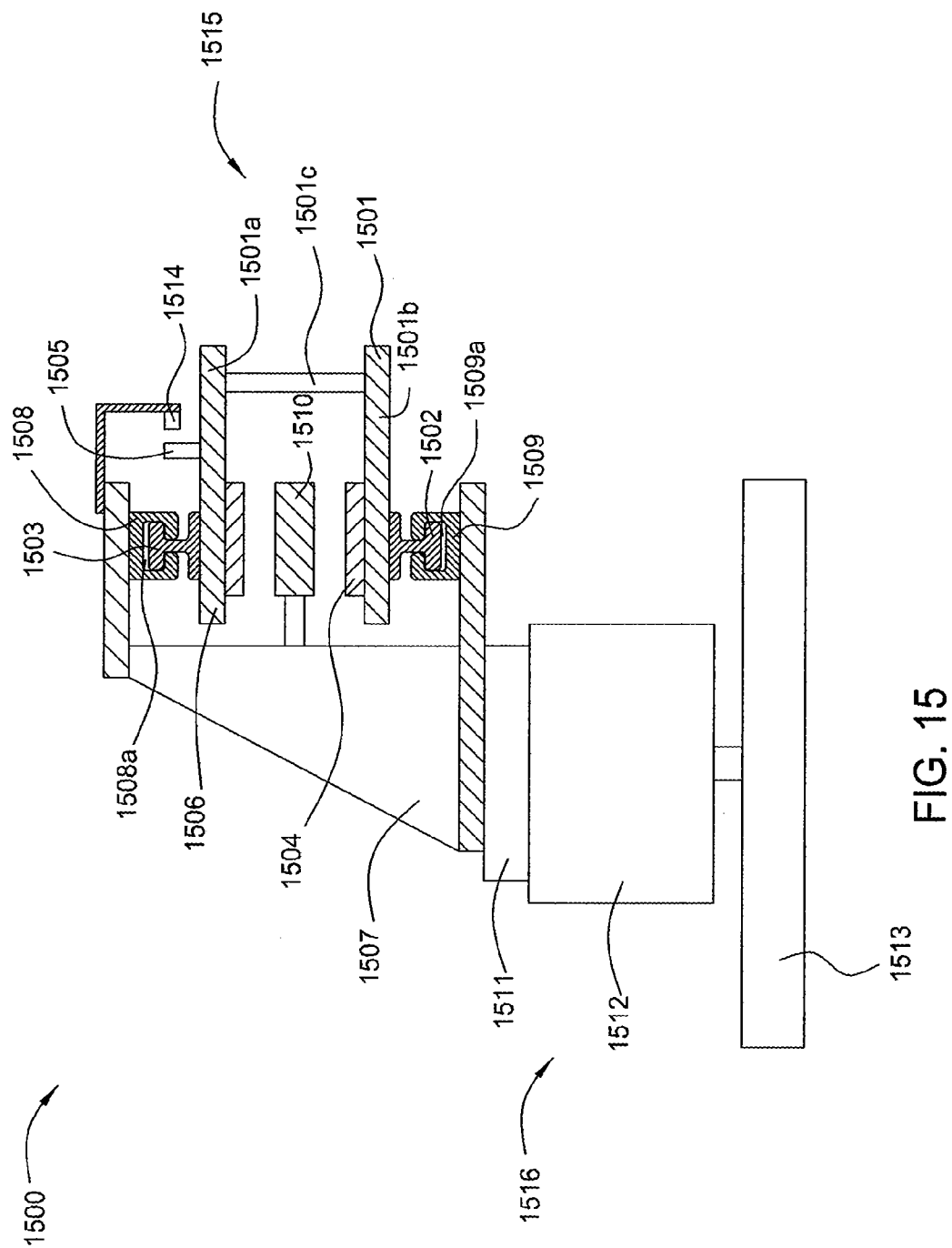


FIG. 14



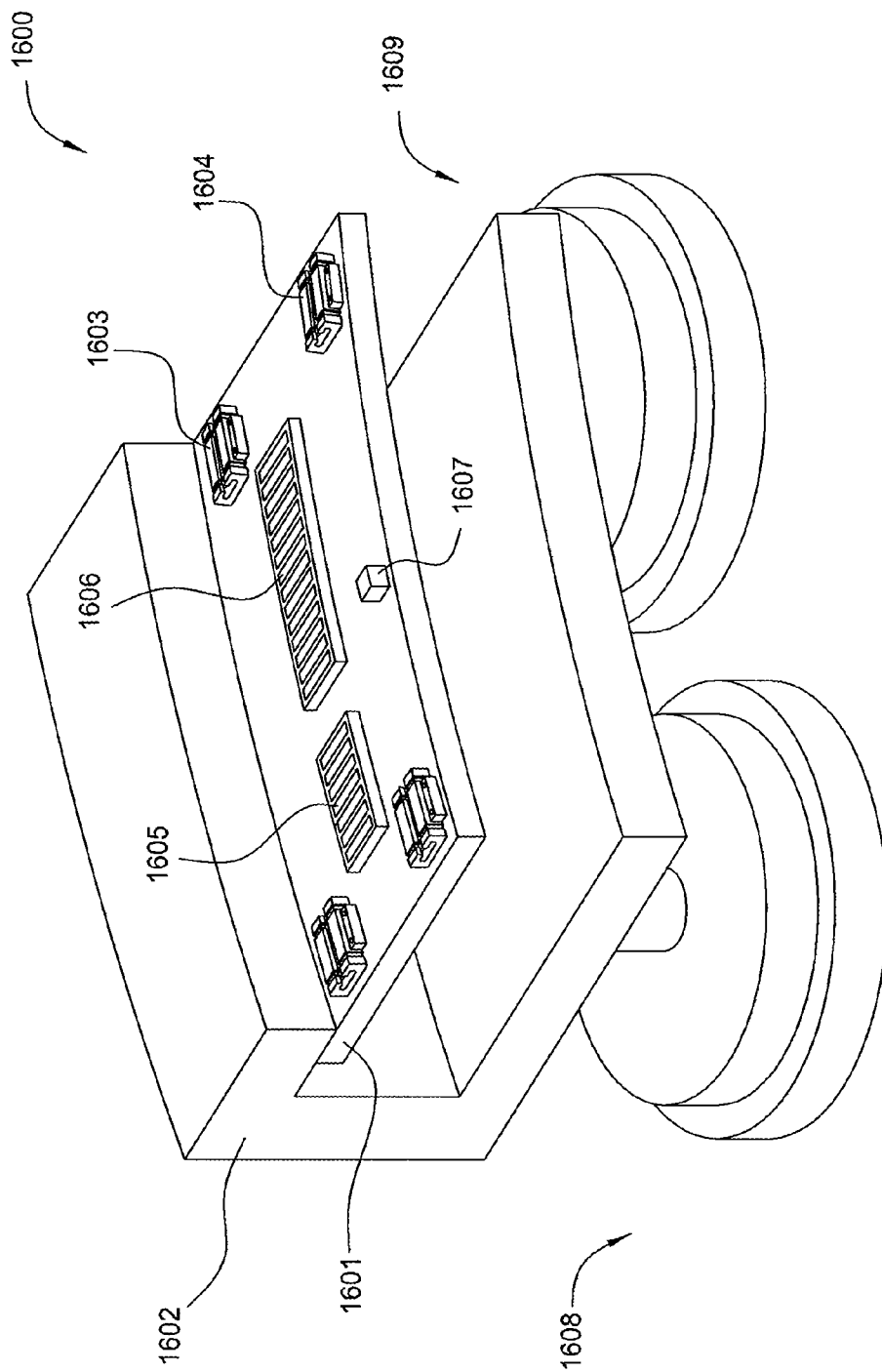


FIG. 16

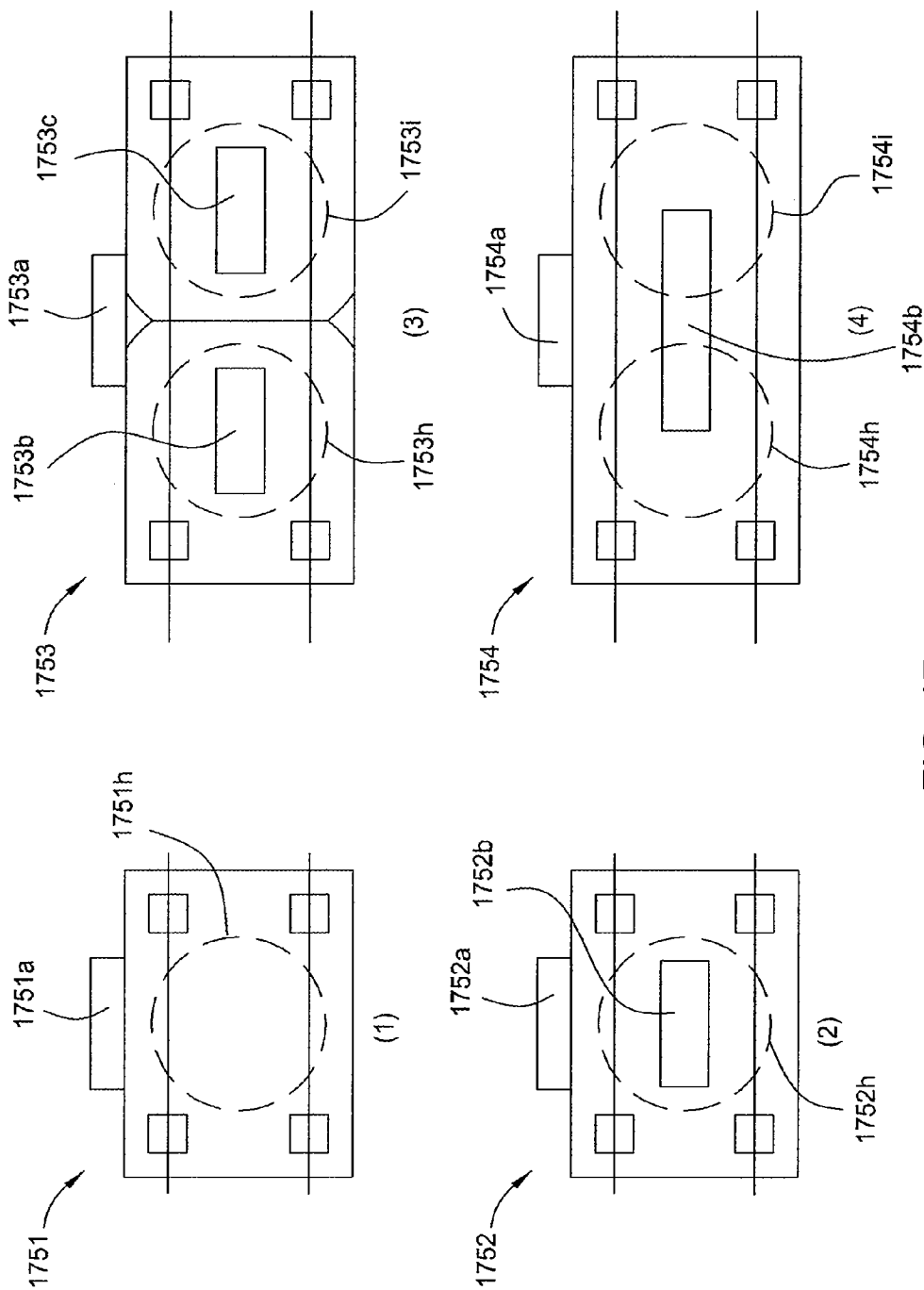


FIG. 17

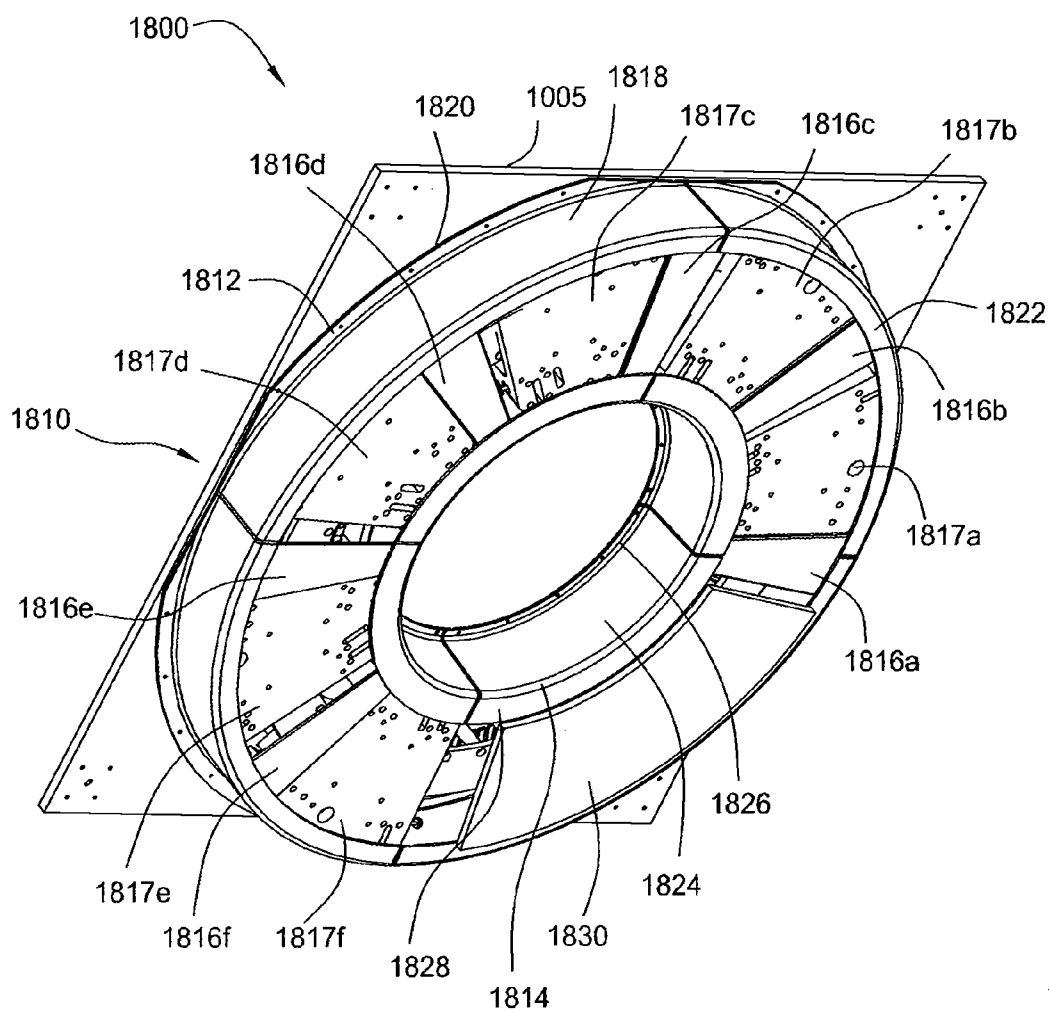


FIG. 18A

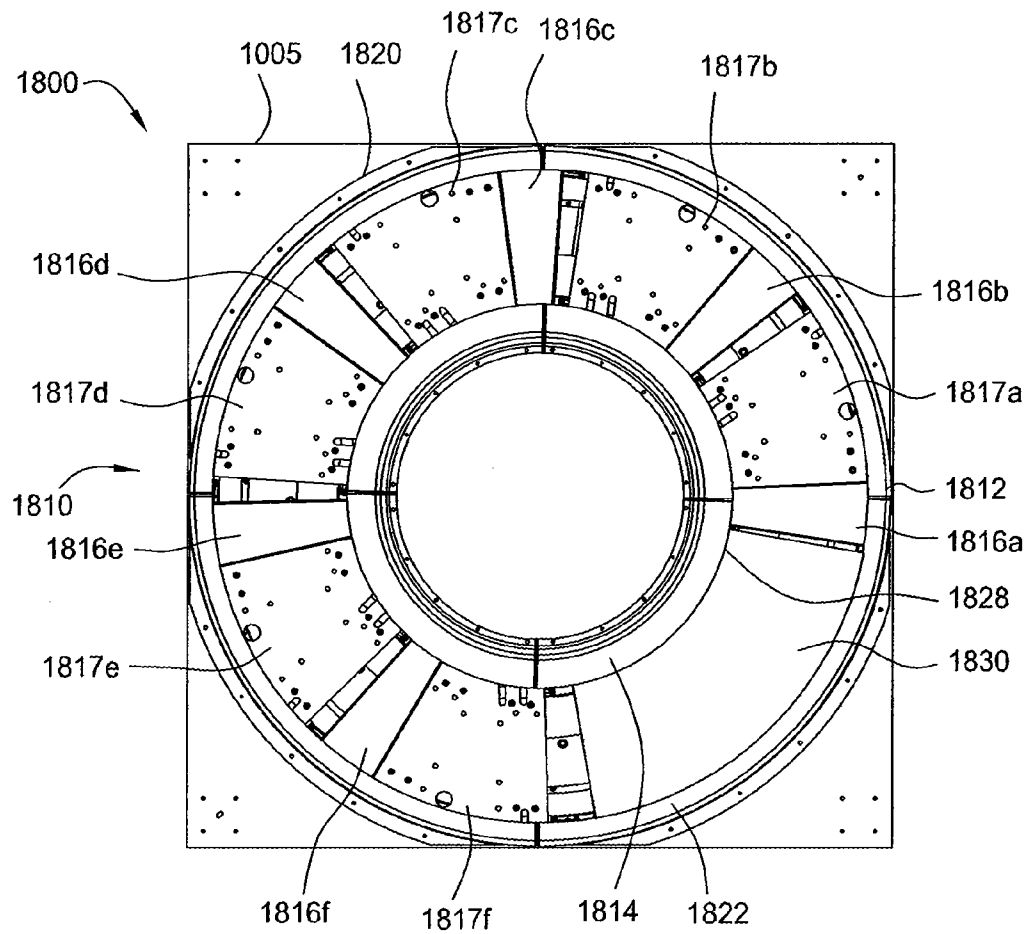


FIG. 18B



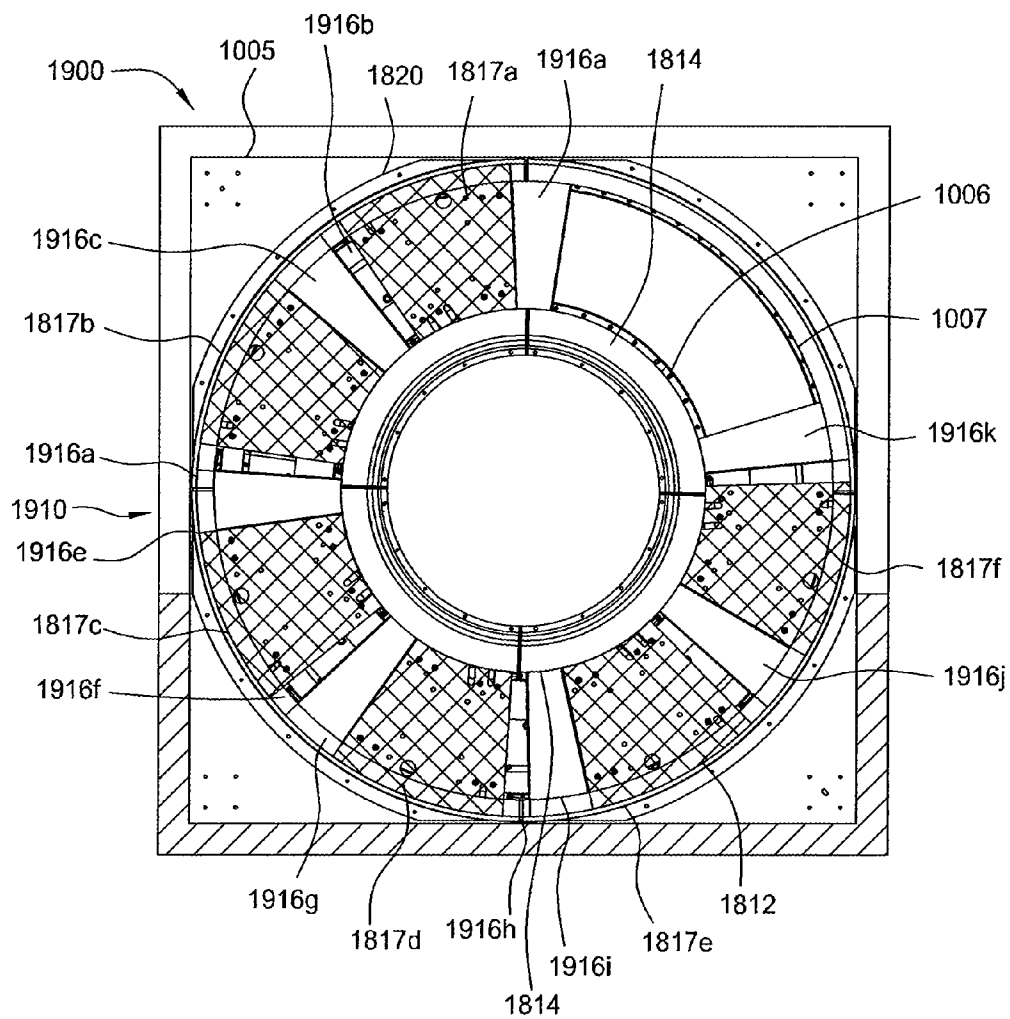
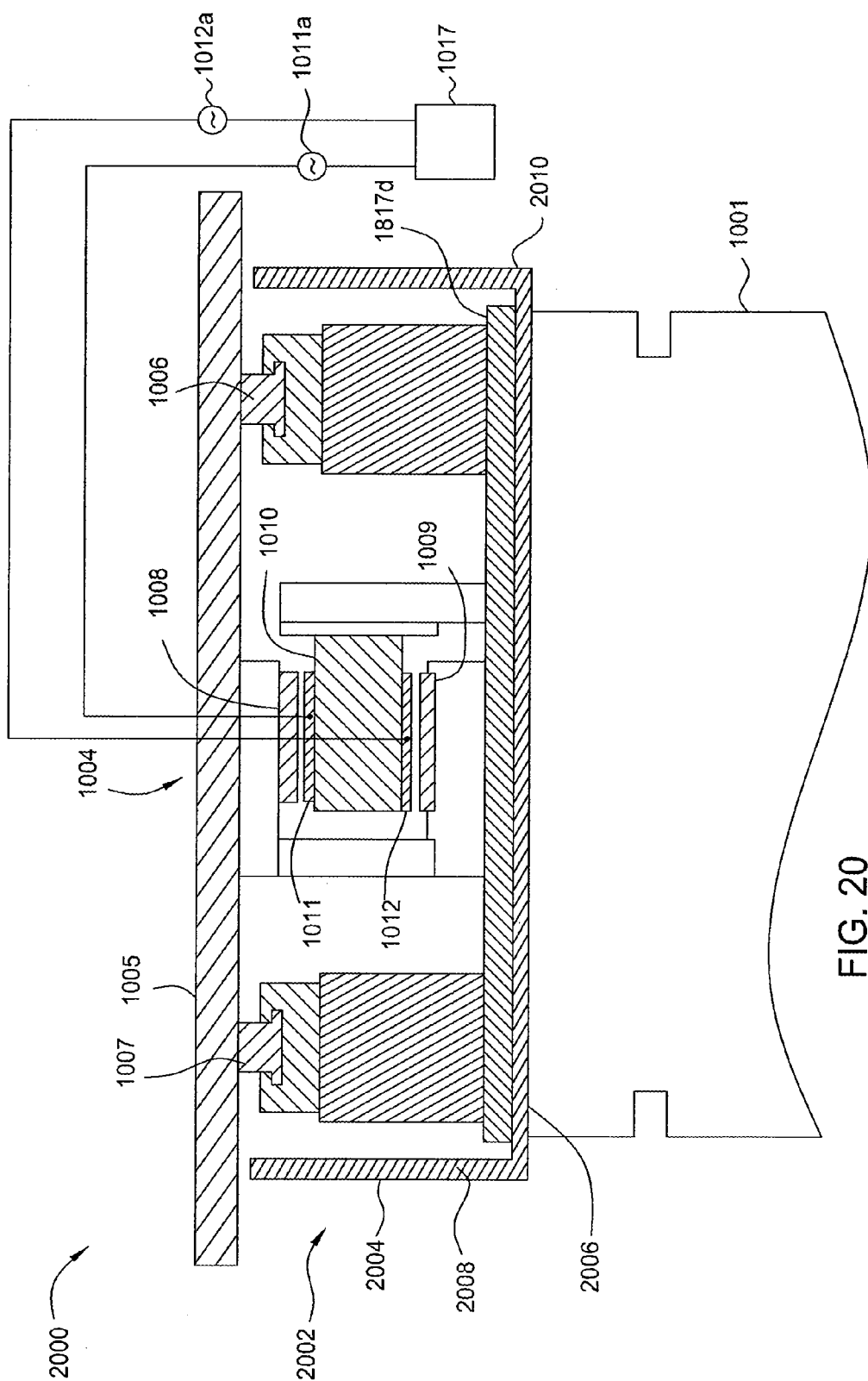
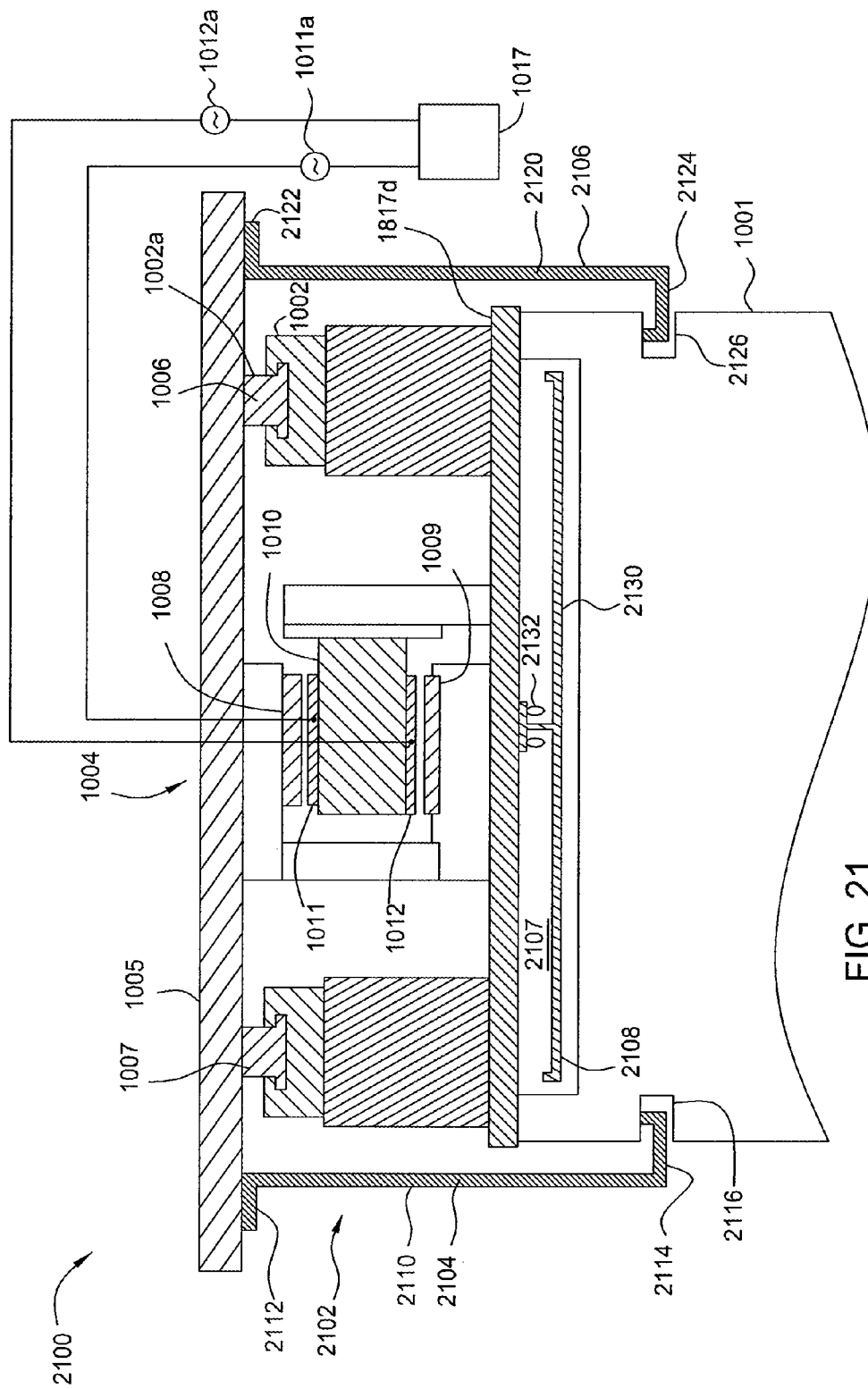
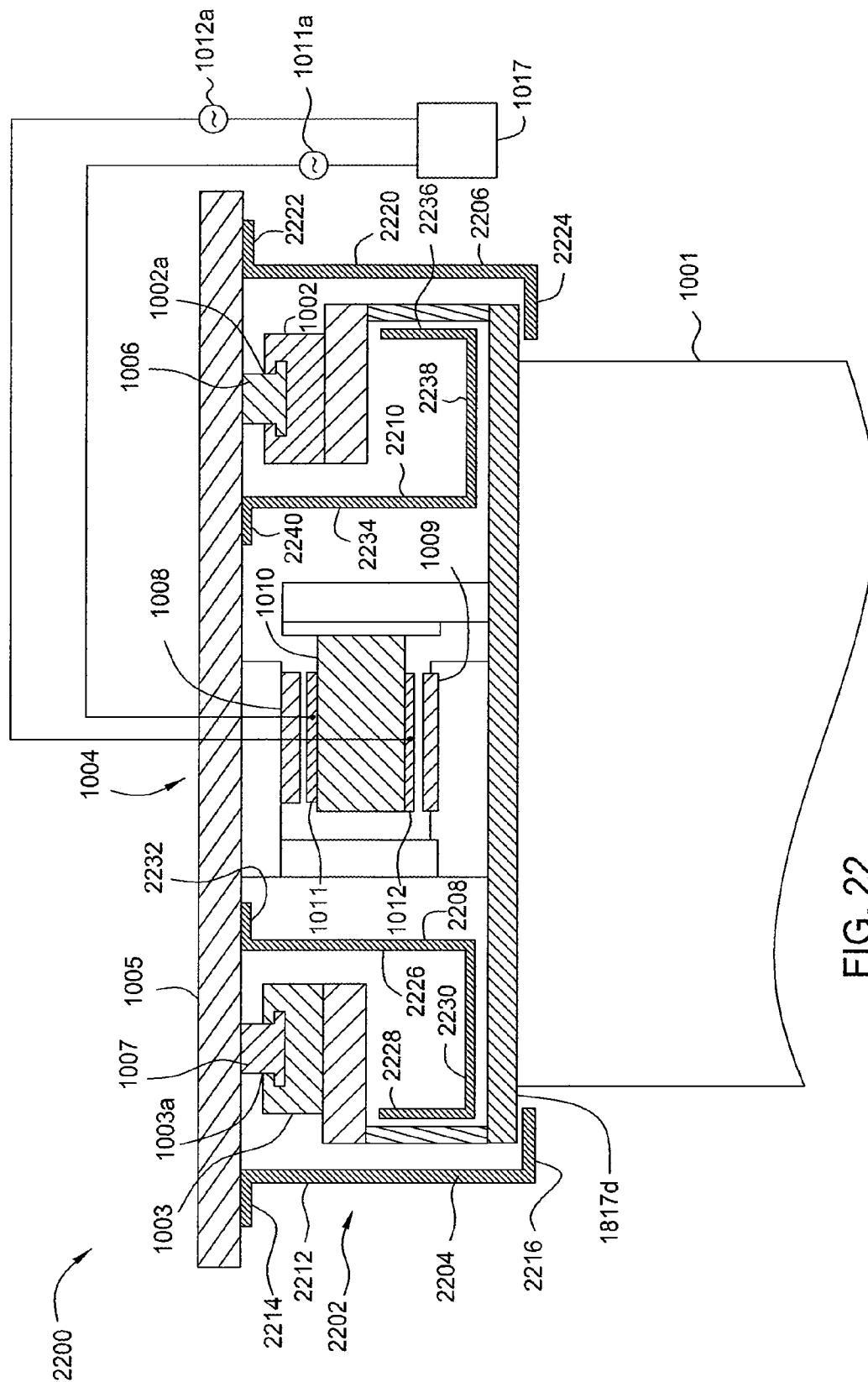


FIG. 19









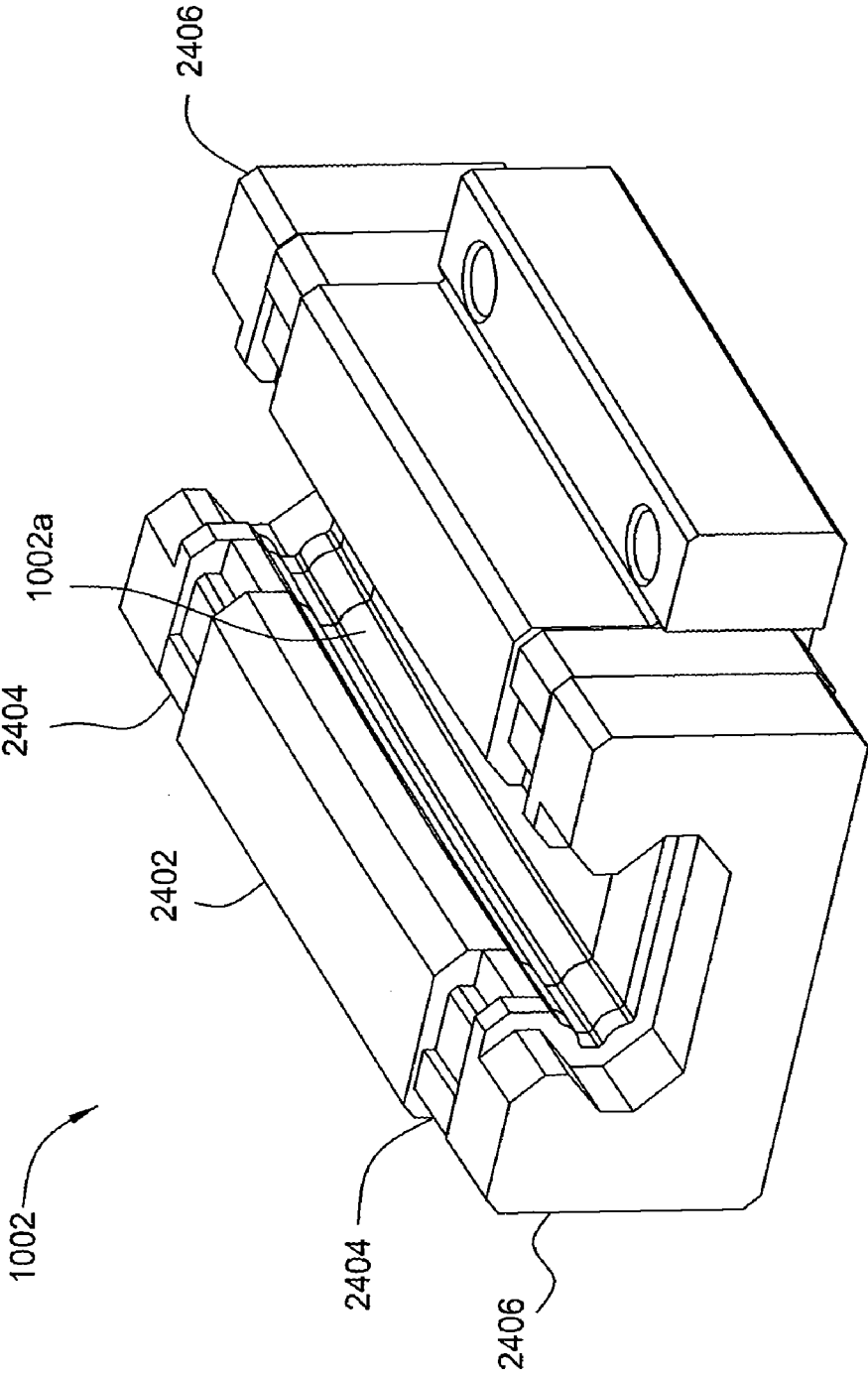


FIG. 24

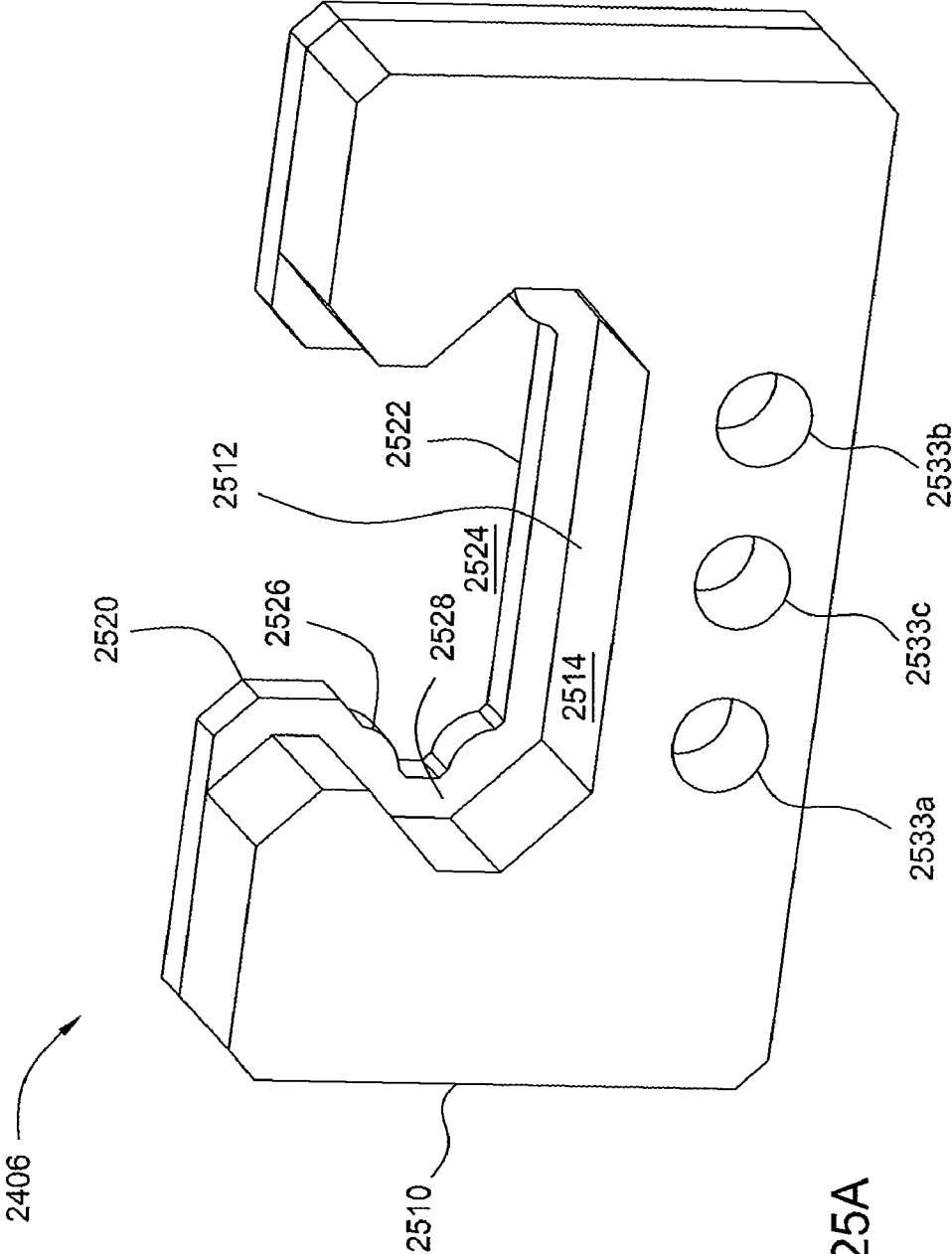
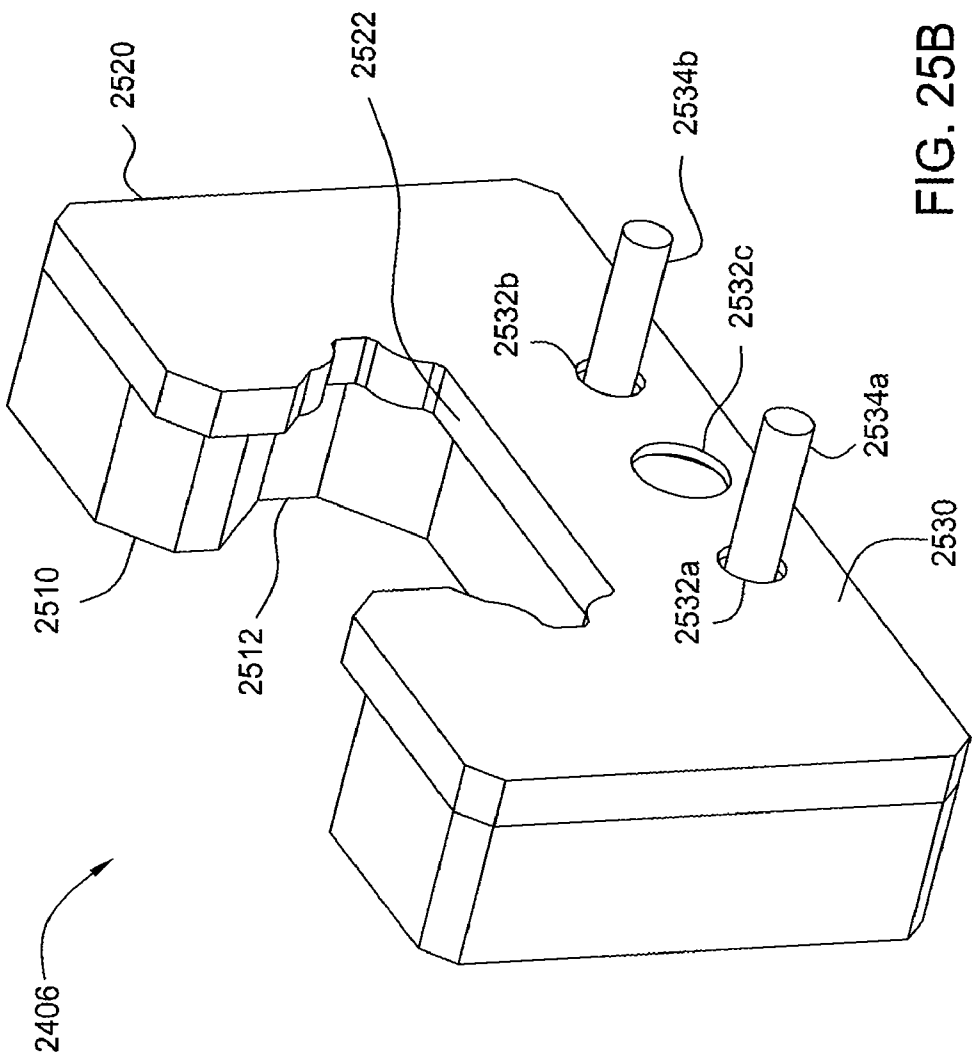


FIG. 25A





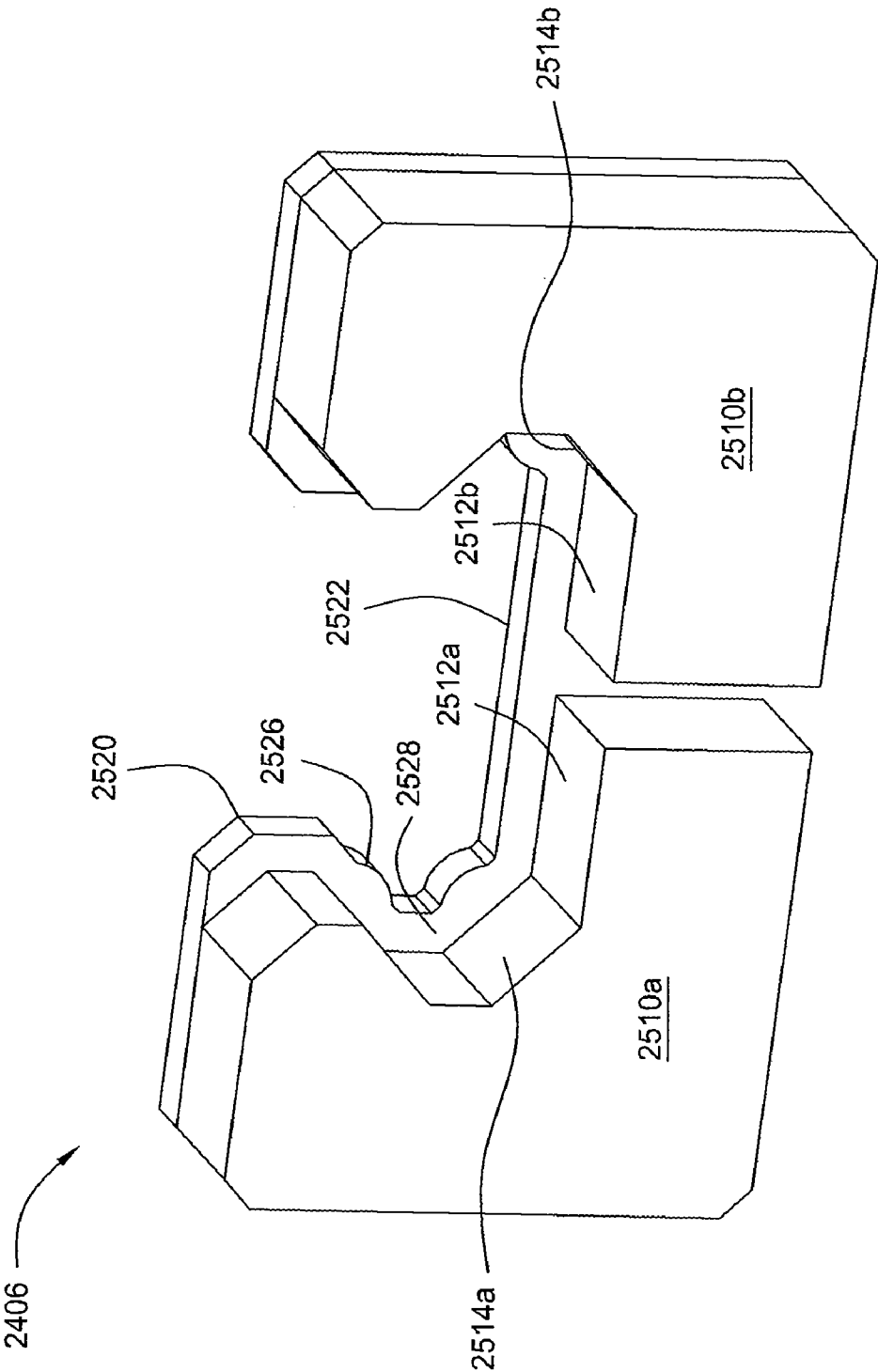


FIG. 26

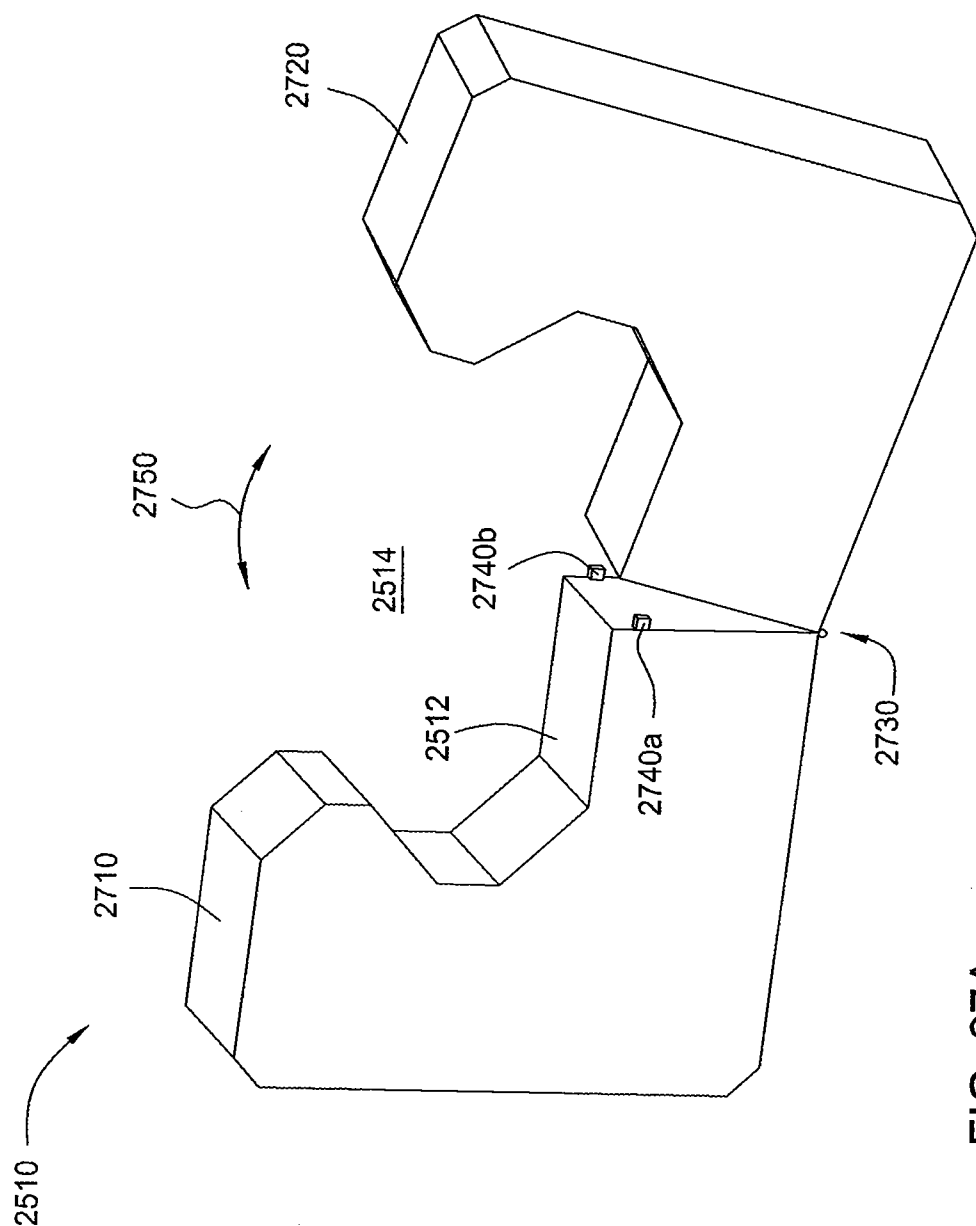


FIG. 27A

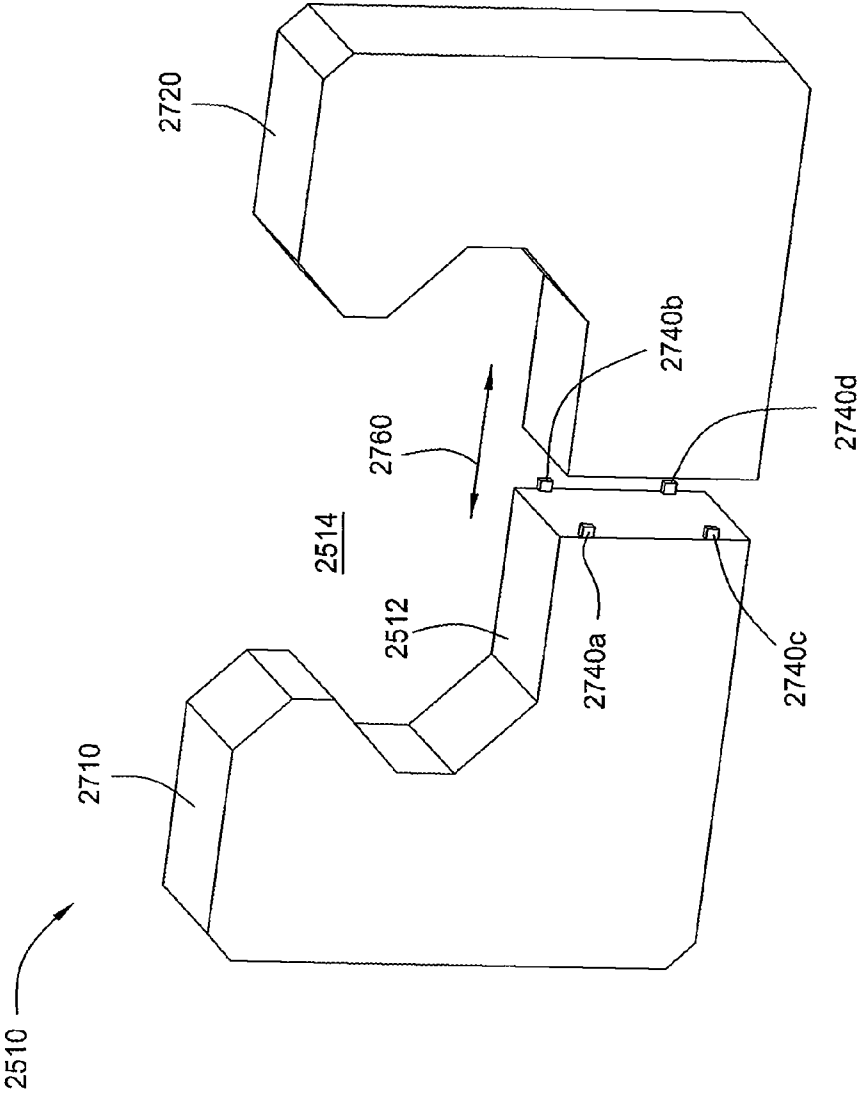


FIG. 27B

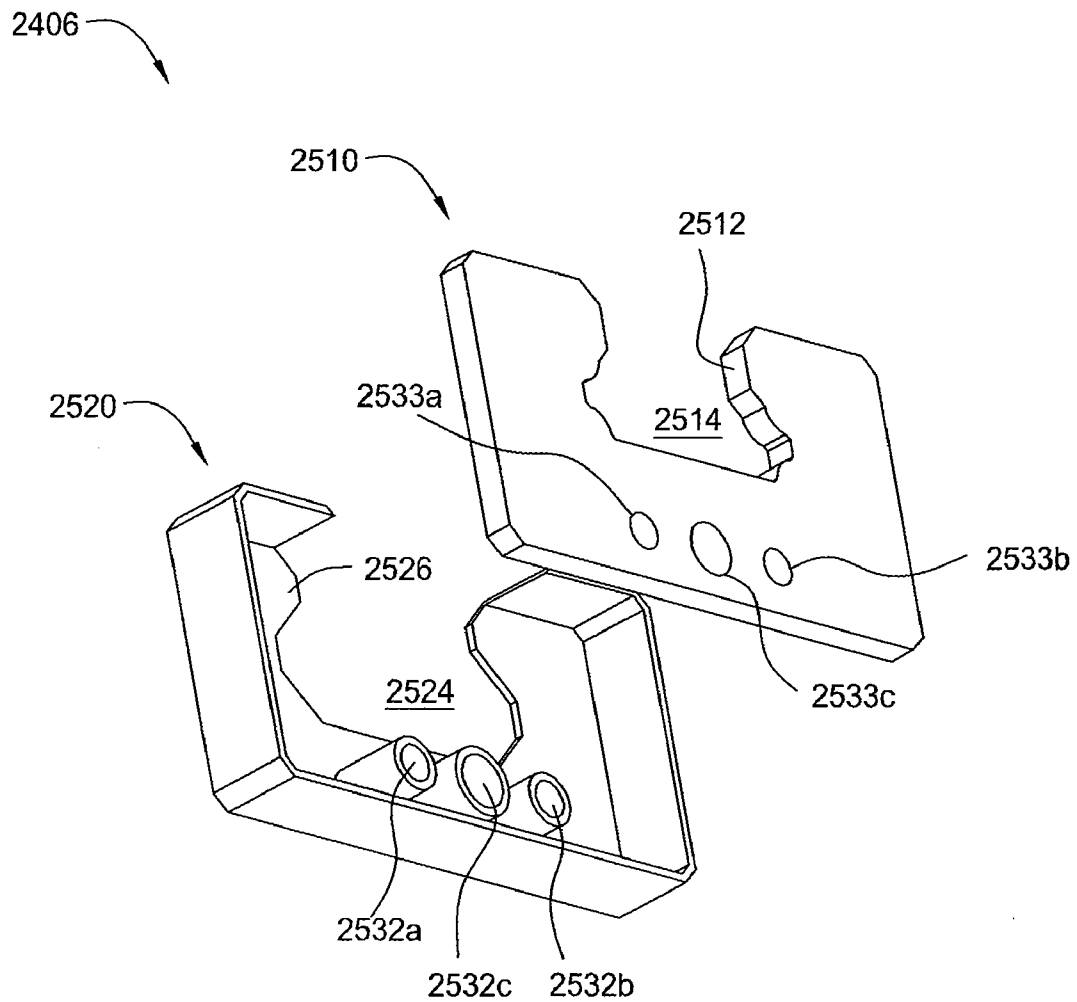


FIG. 28

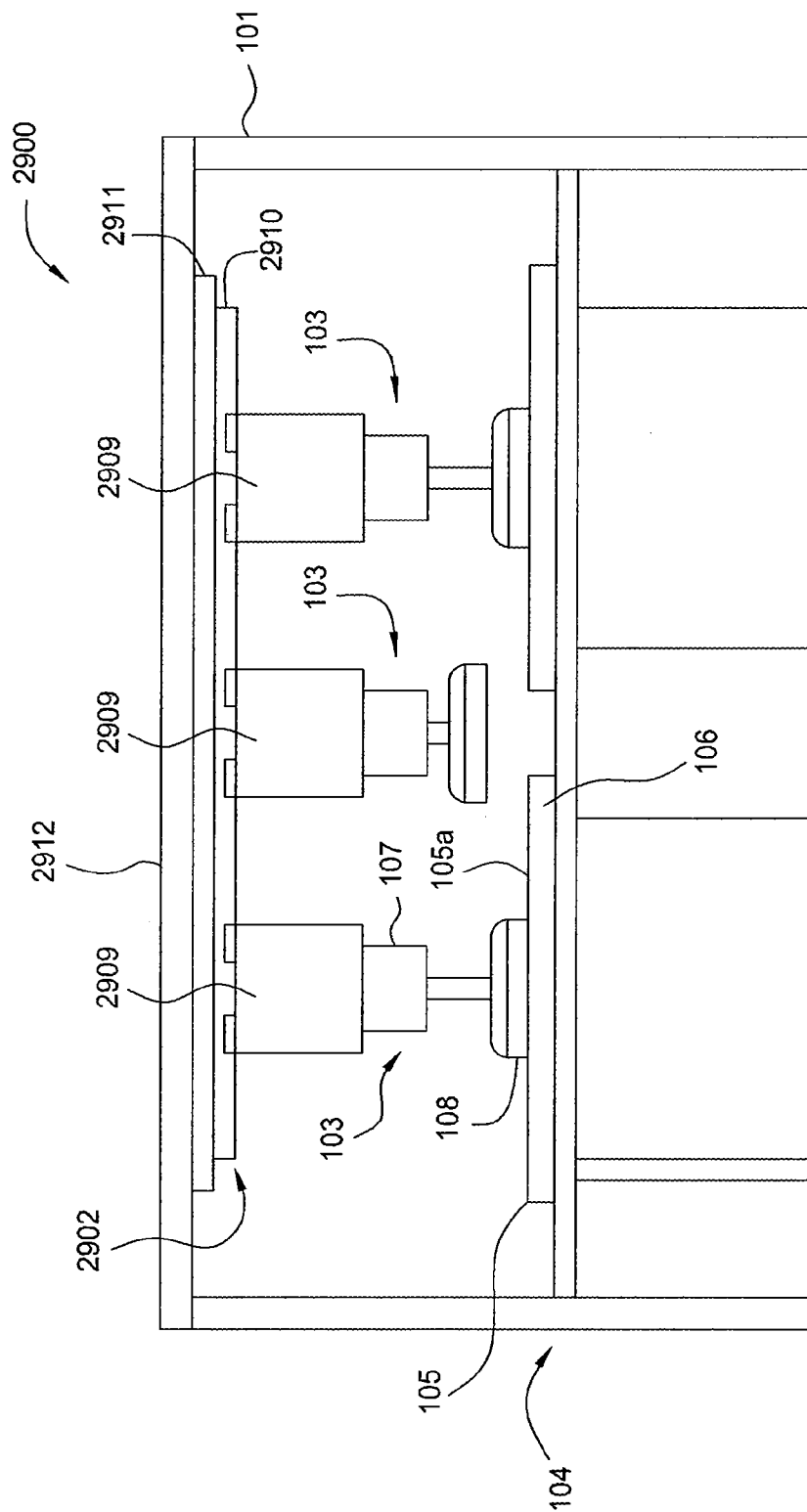


FIG. 29

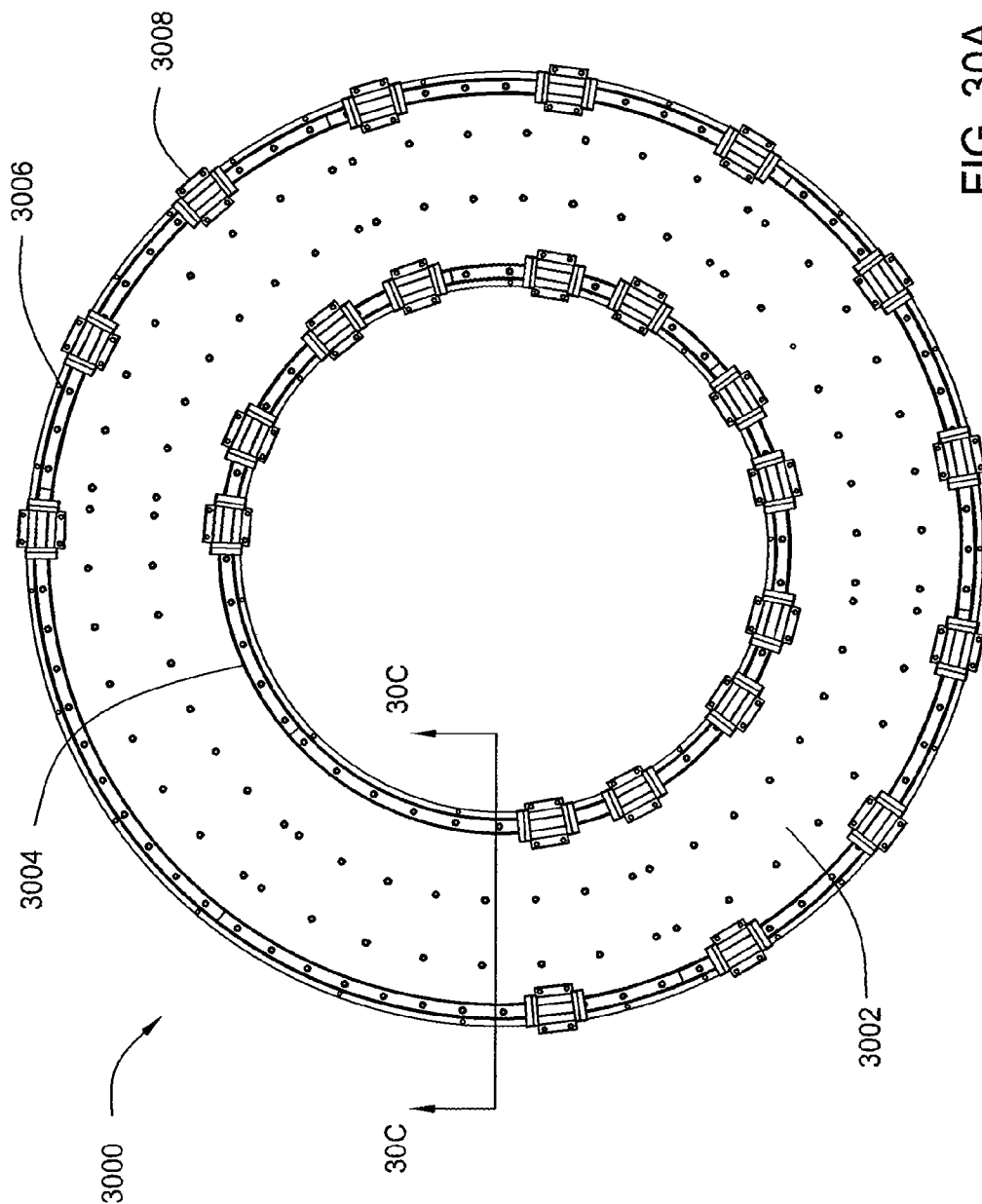


FIG. 30A

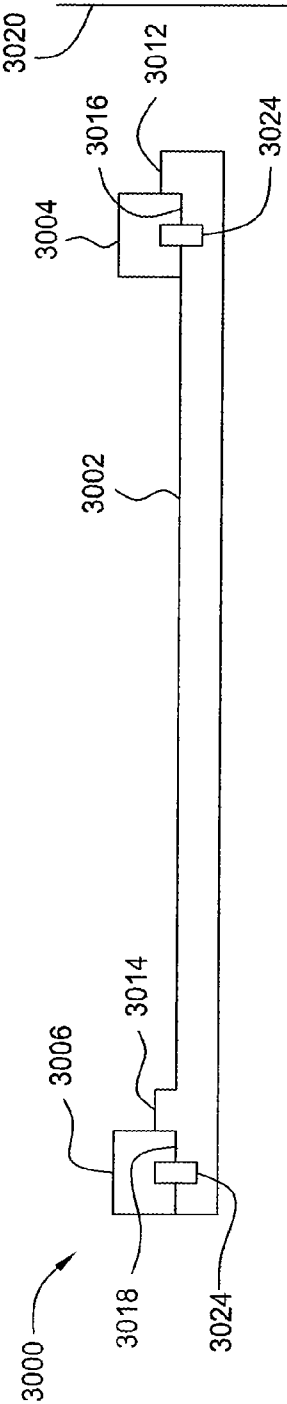


FIG. 30B

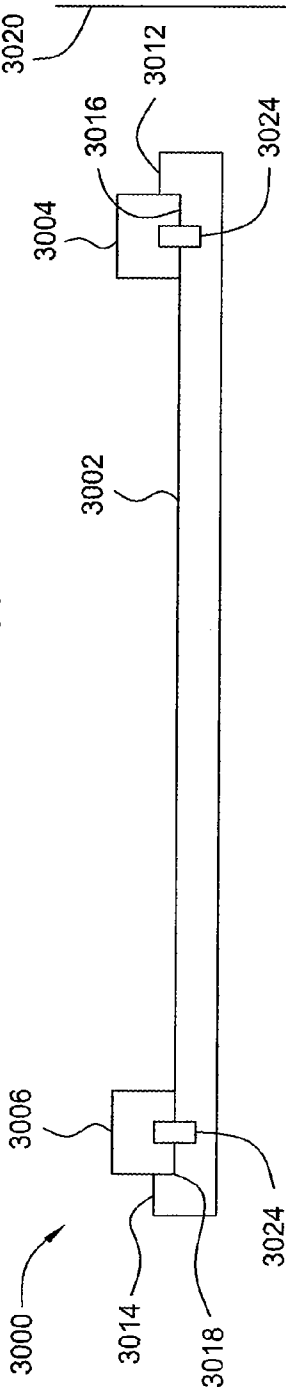


FIG. 30C

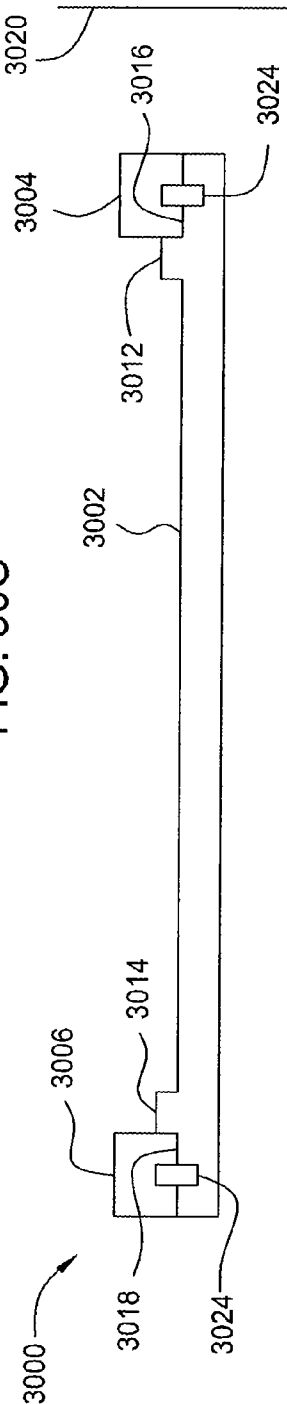


FIG. 30D

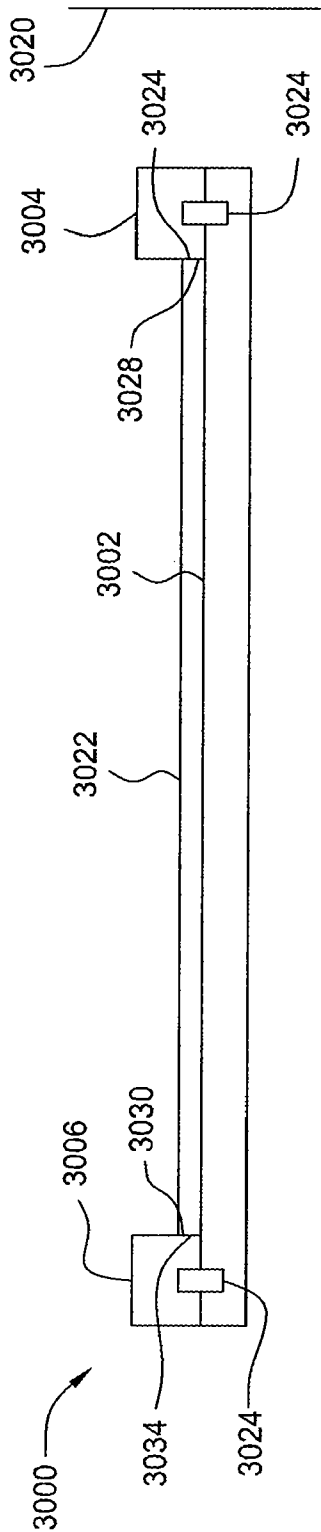


FIG. 30E

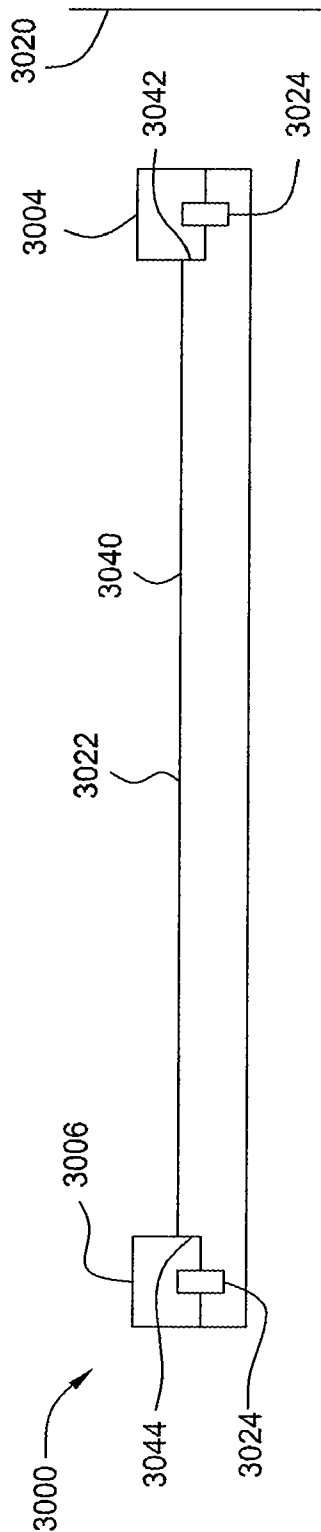


FIG. 30F



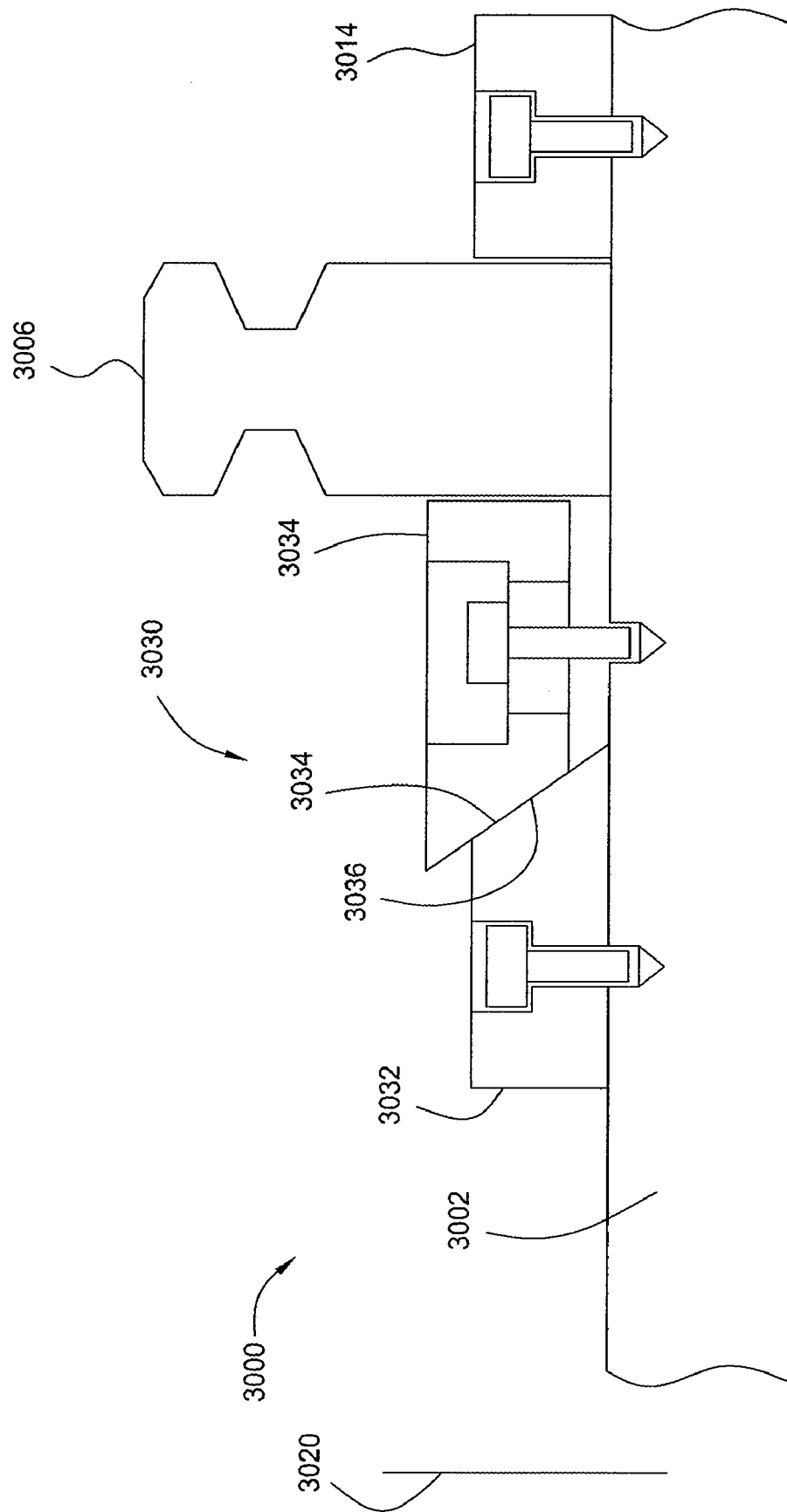


FIG. 30G

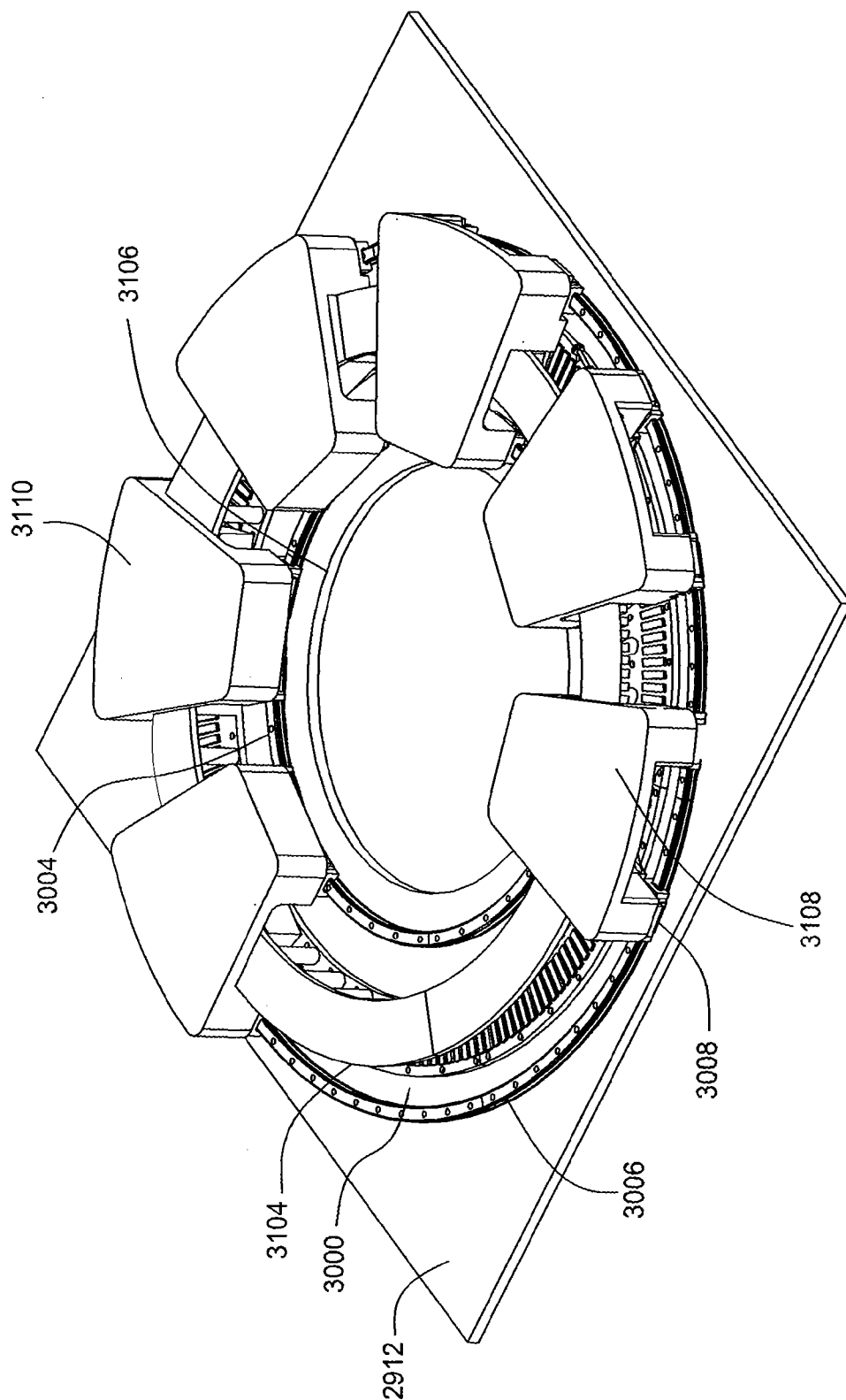


FIG. 31

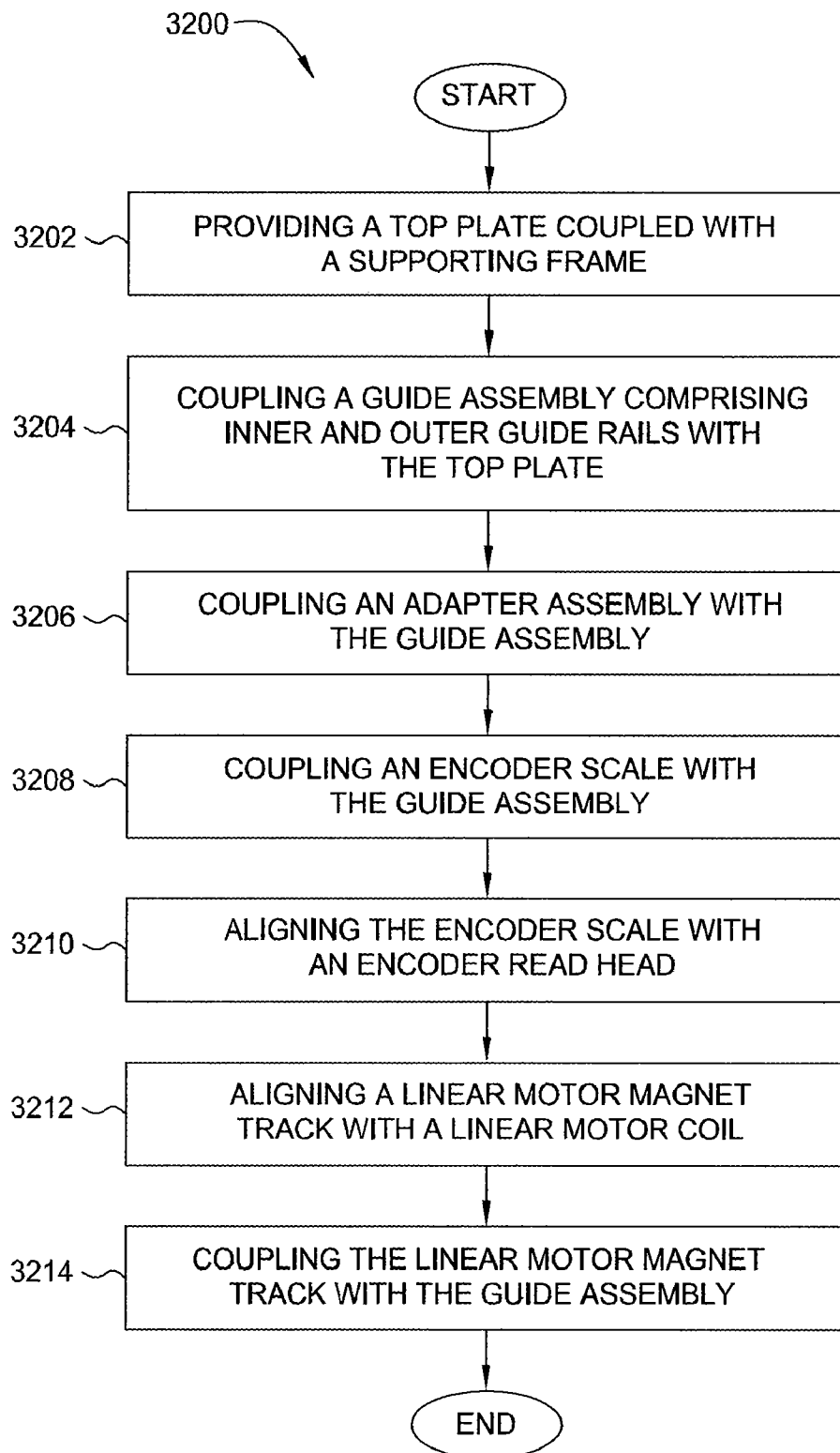


FIG. 32

**POLISHING SYSTEM HAVING A TRACK****CROSS-REFERENCE TO RELATED APPLICATIONS**

This application claims benefit of U.S. Provisional Patent Application Ser. No. 61/043,582, filed Apr. 9, 2008, U.S. Provisional Patent Application Ser. No. 61/043,600, filed Apr. 9, 2008, U.S. Provisional Patent Application Ser. No. 61/056,384, filed May 27, 2008, U.S. Provisional Patent Application Ser. No. 61/056,256, filed May 27, 2008, U.S. Provisional Patent Application Ser. No. 61/087,124, filed Aug. 7, 2008, and U.S. Provisional Patent Application Ser. No. 61/087,127, filed Aug. 7, 2008, all of which are herein incorporated by reference in their entirety.

**BACKGROUND****1. Field**

Embodiments described herein relate to an apparatus and a method for processing semiconductor substrates. More particularly, embodiments described herein provide apparatus and methods for transferring and actuating polishing heads during polishing.

**2. Description of the Related Art**

Sub-micron multi-level metallization is one of the key technologies for the next generation of ultra large-scale integration (ULSI). The multilevel interconnects that lie at the heart of this technology require planarization of interconnect features formed in high aspect ratio apertures, including contacts, vias, trenches and other features. Reliable formation of these interconnect features is very important to the success of ULSI and to the continued effort to increase circuit density and quality on individual substrates and die.

In the fabrication of integrated circuits and other electronic devices, multiple layers of conductive, semi-conductive, and dielectric materials are deposited on or removed from a surface of a substrate. Thin layers of conductive, semiconductive, and dielectric materials may be deposited by a number of deposition techniques. As layers of materials are sequentially deposited and removed, the uppermost surface of the substrate may become non-planar across its surface and require planarization.

Planarization may be performed using Chemical Mechanical Polishing (CMP) and/or Electro-Chemical Mechanical Deposition (ECMP). A planarization method typically requires that the substrate be mounted in a wafer head, with the surface of the substrate to be polished exposed. The substrate supported by the head is then placed against a rotating polishing pad. The head holding the substrate may also rotate, to provide additional motion between the substrate and the polishing pad surface. Further, a polishing slurry (typically including an abrasive and at least one chemically reactive agent therein, which are selected to enhance the polishing of the topmost film layer of the substrate) is supplied to the pad to provide an abrasive chemical solution at the interface between the pad and the substrate. The combination of polishing pad characteristics, the specific slurry mixture, and other polishing parameters can provide specific polishing characteristics.

Polishing may be performed in multiple steps, each having specific polishing characteristics, to achieve desired results. A polishing system typically has two or more polishing pads configured to perform different polishing steps, and a substrate transfer assembly configured to transfer the substrates among the two or more polishing pads.

However, it remains challenging to achieve high throughput and flexibility to meet process requirements in a polishing system.

Therefore, there is a need for a polishing apparatus which provides improved polishing throughput, quality, and flexibility.

**SUMMARY**

Embodiments described herein relate to a polishing system. More particularly, embodiments described herein relate to a track system configured to transfer and actuate polishing heads in a polishing system.

In one embodiment described herein a track system configured to transfer polishing heads in a polishing system comprising a supporting frame, a track coupled to the supporting frame and defining a path along which the polishing heads are configured to move, and one or more carriages configured to carry at least one polishing head along the path defined by the track, wherein the one or more carriages are coupled to the track and independently movable along the track is provided.

In another embodiment described herein a track system for transferring polishing heads in a polishing system comprising a supporting frame, a guiding rail coupled to the supporting frame, wherein the guiding rail defines a path along which the polishing head is configured to travel, a magnetic track disposed along the guiding rail, an encoder scale disposed along the guiding rail, and one or more sliding carriages movably coupled to the guiding rail and each configured to move a polishing head along the path, wherein each of the one or more sliding carriages comprises a segment motor configured to independently actuate the respective sliding carriage by interacting with the magnetic track, and an encoder sensor directed at the encoder scale and configured to measure a position of the respective sliding carriage along the path is provided.

In yet another embodiment described herein a method for polishing semiconductor substrates is provided. The method comprises loading a substrate onto a polishing head configured to transfer the substrate among loading, unloading and polishing stations, moving the polishing head along a track system to a first polishing station, wherein the system comprises a supporting frame, a track coupled to the supporting frame and defining a path along which the polishing heads have access to the loading, unloading and polishing stations, and one or more carriages configured to carry at least one polishing head along the path defined by the track, wherein the one or more carriages are coupled to the track and independently movable along the track, and polishing the substrate at the first polishing station.

In yet another embodiment described herein a polishing head for a polishing system having a track is provided. The polishing head comprises a carriage body, one or more guide blocks mounted on the carriage body, wherein the one or more guide blocks are configured to couple with a track and restrict movements of the carriage body to along the track, a sliding actuator connected to the carriage body and configured to move the carriage body along the track, a first polishing motor connected with the carriage body, wherein the first polishing motor is moved with the movement of the carriage body, and a first substrate carrier configured to secure a substrate during transferring and polishing, wherein the first substrate carrier is coupled to the first polishing motor and rotated by the first polishing motor during polishing.

In yet another embodiment described herein a polishing head for a track polishing system is provided. The polishing head comprises a carriage body, one or more guide blocks

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mounted on the carriage body, wherein the one or more guide blocks are configured to couple with a guiding rail of the track polishing system and restrict movements of the carriage body to along the guiding rail, a sliding motor mounted on the carriage body and configured to move the carriage body along the guiding rail by reacting to a magnetic track of the track polishing system, a sensor assembly disposed on the carriage body, wherein the sensor assembly is configured to measure a position of the polishing head, and a first polishing assembly attached to the carriage body, wherein the first polishing assembly comprises a first polishing motor, and a first substrate carrier configured to secure a substrate during transferring and polishing, wherein the first substrate carrier is coupled to the first polishing motor and rotated by the first polishing motor during polishing.

In yet another embodiment described herein a method for polishing semiconductor substrates is provided. The method comprises loading a first substrate onto a polishing head movably coupled to a track of a track polishing system, wherein the polishing head comprises a carriage body, one or more guide blocks mounted on the carriage body, wherein the one or more guide blocks are configured to couple with the track and restrict movements of the carriage body to along the track, a sliding actuator connected to the carriage body and configured to move the carriage body along the track, a first polishing assembly comprising a first polishing motor connected with the carriage body and a first substrate carrier configured to secure the first substrate during transferring and polishing, wherein the first substrate carrier is coupled to the first polishing motor and rotated by the first polishing motor during polishing, sliding the polishing head along the track to position the first substrate over the first polishing station, and polishing the first substrate at the first polishing station by pushing the first substrate against a platen of the first polishing station and rotating the first substrate using the first polishing motor.

Embodiments described herein further relate to an apparatus for isolating a substrate processing environment from substrate transferring mechanisms. More particularly, certain embodiments described herein further relate to a shield assembly for isolating a substrate processing environment from substrate transferring mechanisms in an overhead track system.

In yet another embodiment, a track system configured to transfer polishing heads in a polishing system is provided. The track system comprises a supporting frame, a track coupled with the supporting frame and defining a path along which the polishing heads are configured to move, one or more carriages configured to carry at least one of the polishing heads along the path defined by the track, wherein the one or more carriages are coupled with the track and independently movable along the track, and a shield assembly coupled with the supporting frame and isolating the circular track from a processing environment. In one embodiment, the track is a circular track. In one embodiment, the shield assembly comprises an outer stationary shield encircling the outer periphery of the circular track, an inner stationary shield dimensioned to fit within the inner diameter of the circular track, and a plurality of movable shields positioned to overlap with the outer stationary shield and the inner stationary shield.

In yet another embodiment a track system configured to transfer polishing heads in a polishing system is provided. The track system comprises a supporting frame, a track coupled with the supporting frame and defining a path along which the polishing heads are configured to move, one or more carriages configured to carry at least one polishing head

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along the path defined by the track, wherein the one or more carriages are coupled with the track and independently movable along the track, and a unshaped shield assembly coupled with the carriage, wherein the u-shaped shield assembly is dimensioned to isolate the circular track from a processing environment. In one embodiment, the track is a circular track.

Embodiments described herein further provide a replaceable seal device that is easily removed or installed from a circular track system with minimal system downtime.

In yet another embodiment, the replaceable seal comprises a backing plate and a seal member removably coupled with the backing plate. The backing plate may comprise an inner circumferential face forming a recessed portion for accommodating a rail of a circular track. The seal member may comprise an inner circumferential face forming a recessed portion for accommodating the rail of the circular track.

In yet another embodiment, the replaceable seal comprises a seal member coupled to two or more backing plates. In one embodiment, the seal member may be coupled with the backing plate by molding the seal member on the backing plate. The seal member comprises an inner circumferential face forming a recessed portion for accommodating the rail of a track assembly. The backing plate is made such that it provides rigidity to the seal member while allowing the replaceable seal assembly to be removed or installed without compromising the seal assembly.

In yet another embodiment, the replaceable seal is fixed to an end portion of a guide block which is fixed to an end portion of a slider of the guide block to prevent foreign objects such as dirt and dust from entering the guide block and slider, the slider straddling a rail of a circular track.

In yet another embodiment a polishing head for a polishing system having a circular track is provided. The polishing head comprises a carriage body, one or more guide blocks mounted on the carriage body, wherein the one or more guide blocks are configured to couple with a track and restrict movements of the carriage body along the track, and a replaceable seal coupled with the guide block, wherein the replaceable seal straddles the track. In one embodiment, the polishing head further comprises a sliding actuator coupled with the carriage body and configured to move the carriage along the track and a first substrate carrier configured to secure a substrate during transferring and polishing, wherein the first substrate carrier is couple with the carriage body.

In yet another embodiment, a circular track system configured to transfer polishing heads in a polishing system is provided. The circular track system comprises a supporting frame, a track coupled to the supporting frame and defining a path along which the polishing heads are configured to move, and one or more carriages configured to carry at least one polishing head along the path defined by the track, wherein the track comprises a guide rail and each of the one or more carriages comprises one or more guide blocks with a replaceable seal which movably couple each respective carriage to the guide rail and restrict movements of the respective carriage within the path.

Embodiments described herein further relate to a circular track polishing system and methods for installing a circular track polishing system. In one embodiment a method for installing a circular track assembly is provided. The method comprises coupling a top plate with a supporting frame, coupling a guide assembly comprising inner and outer guide rails with the top plate, coupling an adapter assembly with the guide assembly, aligning an encoder scale with a sensor assembly, aligning a stator strip with an actuator, and coupling the stator strip with the guide assembly.

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In another embodiment a track system configured to transfer polishing heads in a polishing system is provided. The track system comprises a supporting frame, a guide assembly coupled with the supporting frame, and one or more carriages configured to carry at least one polishing head along the path defined by the track, wherein the one or more carriages are coupled with the track and independently movable along the track. The guide assembly comprises a plate and a track coupled with the plate and defining a path along which the polishing heads are configured to move.

In yet another embodiment a track system for polishing heads is provided. The track system comprising a supporting frame, a guide assembly coupled with the supporting frame, a guiding rail coupled with the guide assembly, a magnetic track disposed along the guiding rail, an encoder scale disposed along the guiding rail, and one or more sliding carriages movably coupled to the guiding rail and each configured to move a polishing head along the path. Each of the one or more sliding carriages comprises a segment motor configured to independently actuate the respective sliding carriage by interacting with the magnetic track and an encoder sensor directed at the encoder scale and configured to measure a position of the respective sliding carriage along the path.

In yet another embodiment a guide assembly configured for coupling with a system support frame is provided. The guide assembly comprises a plate and a track coupled with the plate and defining a path along which polishing heads are configured to move.

#### BRIEF DESCRIPTION OF THE DRAWINGS

So that the manner in which the above recited features described herein can be understood in detail, a more particular description of the invention, briefly summarized above, may be had by reference to embodiments, some of which are illustrated in the appended drawings. It is to be noted, however, that the appended drawings illustrate only typical embodiments of this invention and are therefore not to be considered limiting of its scope, for the invention may admit to other equally effective embodiments.

FIG. 1 is a schematic side view of a track polishing system in accordance with one embodiment described herein;

FIG. 2A is a schematic top view of a track polishing system in accordance with one embodiment described herein;

FIG. 2B is a schematic top view of a track polishing system in accordance with another embodiment described herein;

FIG. 3A is a schematic perspective sectional view of a track assembly in accordance with one embodiment described herein;

FIG. 3B is a schematic partial view of a stator strip used the track assembly of FIG. 3A;

FIG. 4 is a schematic top view of a track polishing system in accordance with one embodiment described herein;

FIG. 5 is a schematic sectional side view of a track assembly in accordance with one embodiment described herein;

FIG. 6 is a schematic sectional side view of a track assembly in accordance with one embodiment described herein;

FIG. 7 is a schematic sectional side view of a track assembly in accordance with one embodiment described herein;

FIG. 8 is a schematic sectional side view of a track assembly in accordance with one embodiment described herein;

FIG. 9 is a schematic top view of a track polishing system described herein in a maintenance state;

FIG. 10A is a schematic perspective view of a polishing head in accordance with one embodiment described herein;

FIG. 10B is a schematic sectional side view of the polishing head of FIG. 10A;

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FIG. 11A is a schematic sectional side view of a polishing head and a track assembly in accordance with one embodiment described herein;

FIG. 11B is a schematic top view of the polishing head and the track assembly of FIG. 11A;

FIG. 12 is a schematic sectional side view of a polishing head and a track assembly in accordance with one embodiment described herein;

FIG. 13 is a schematic sectional side view of a polishing head and a track assembly in accordance with one embodiment described herein;

FIG. 14 is a schematic sectional side view of a polishing head and a track assembly in accordance with one embodiment described herein;

FIG. 15 is a schematic sectional side view of a polishing head and a track assembly in accordance with one embodiment described herein;

FIG. 16 is a schematic perspective view of a polishing head having two substrate carriers in accordance with one embodiment described herein;

FIG. 17 schematically illustrates different configurations of actuators for transportation and sweeping in accordance with embodiments described herein;

FIG. 18A is a perspective view of a track system with a shield assembly in accordance with one embodiment described herein;

FIG. 18B is a bottom view of the track system with the shield assembly of FIG. 18A;

FIG. 19 is a bottom view of the track system with a shield assembly in accordance with one embodiment described herein;

FIG. 20 is a schematic partial cross-sectional view of a track system with a shield assembly in accordance with one embodiment described herein;

FIG. 21 is a schematic partial cross-sectional view of a track system with a shield assembly in accordance with another embodiment described herein;

FIG. 22 is a schematic partial cross-sectional view of a track system with a shield assembly in accordance with yet another embodiment described herein;

FIG. 23 is a schematic partial cross-sectional view of a track system with a shield assembly in accordance with yet another embodiment described herein;

FIG. 24 is a perspective view of a guide block with a replaceable seal according to one embodiment described herein;

FIG. 25A is a perspective view of a replaceable seal according to one embodiment described herein;

FIG. 25B is a perspective rear view of the replaceable seal of FIG. 25A according to one embodiment described herein;

FIG. 26 is a perspective view of another replaceable seal according to one embodiment described herein;

FIG. 27A is a perspective view of one embodiment of a backing plate according to one embodiment described herein;

FIG. 27B is a perspective view of another embodiment of a backing plate according to one embodiment described herein;

FIG. 28 is an exploded perspective view of a replaceable seal according to another embodiment described herein;

FIG. 29 illustrates a schematic side view of a track polishing system with a guide assembly in accordance with one embodiment described herein;

FIG. 30A illustrates a schematic bottom view of a guide assembly in accordance with one embodiment described herein;

FIG. 30B illustrates a schematic partial cross-sectional view of a guide assembly in accordance with one embodiment described herein;

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FIG. 30C illustrates a schematic partial cross-sectional view of a guide assembly in accordance with another embodiment described herein;

FIG. 30D illustrates a schematic partial cross-sectional view of a guide assembly in accordance with another embodiment described herein;

FIG. 30E illustrates a schematic partial cross-sectional view of a guide assembly in accordance with another embodiment described herein;

FIG. 30F illustrates a schematic partial cross-sectional view of a guide assembly in accordance with another embodiment described herein;

FIG. 30G illustrates a schematic cross-sectional view of a guide assembly in accordance with another embodiment described herein;

FIG. 31 illustrates a perspective view a guide assembly in accordance with one embodiment described herein; and

FIG. 32 illustrates a process sequence for the installation of a guide assembly into a track polishing system described herein.

To facilitate understanding, identical reference numerals have been used, where possible, to designate identical elements that are common to the figures. It is contemplated that elements disclosed in one embodiment may be beneficially utilized on other embodiments without specific recitation.

#### DETAILED DESCRIPTION

Embodiments described herein relate to an apparatus and a method for transferring and supporting a substrate in a chemical mechanical polishing (CMP) system or electrochemical mechanical polishing (ECMP) system. In one embodiment described herein, a track system is used to transfer one or more polishing heads independently among polishing stations, loading/unloading station, and/or cleaning stations. In one embodiment, the track system comprises a stator strip defining a path along which one or more polishing heads may be moved by interactions between a rotor in each of the one or more polishing heads and the stator strip. In one embodiment, the stator strip comprises a plurality of permanent magnets, the rotor is a segment motor, and the polishing head is moved or stopped by interaction between magnetic fields of the permanent magnets and magnetic fields generated by the segment motor from electronic power provided to the segment motor. In one embodiment, one or more guide rails are disposed along the path defined by the stator strip and each of the one or more polishing heads are coupled to the one or more guide rails by one or more guide blocks. In one embodiment, the track is circular.

Track System:

FIG. 1 is a schematic side view of a track polishing system 100 in accordance with one embodiment described herein. The track polishing system 100 comprises a system frame 101 configured to provide support for apparatus using in a polishing process.

A track assembly 102 is mounted on an upper portion of the system frame 101 and a processing platform 104 is installed on a lower portion of the system frame 101. In one embodiment, the processing platform 104 may comprise a combination of modulated tools, such as polishing stations, load cups, and cleaning stations according to process requirements. As shown in FIG. 1, the processing platform 104 comprises one or more polishing stations 105.

A plurality of polishing heads 103 are movably coupled to the track assembly 102. Each of the plurality of polishing heads 103 is independently movable along the track assembly

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102 and is capable of travelling among the one or more polishing stations 105 positioned below.

In one embodiment, the track assembly 102 comprises a track body 110 defining a path along which the polishing heads 103 may move. The track assembly 102 further comprises one or more carriages 109 movably connected to the track body 110. Each of the one or more carriages 109 is configured to carry at least one polishing heads 103.

In one embodiment, the polishing head 103 comprises a polishing motor 107 mounted on one of the carriages 109, and a substrate carrier 108 connected to the polishing motor 107. The substrate carrier 108 is configured to secure a substrate during polishing. The polishing motor 107 is configured to rotate the substrate carrier 108, thus the substrate secured thereon, against a polishing surface 105a of the polishing station 105. A detailed description of a polishing head may be found in U.S. Pat. No. 6,183,354, entitled "Carrier Head with a Flexible Membrane for a Chemical Mechanical Polishing", and co-pending U.S. Pat. No. 7,001,257, entitled "Multi-chamber Carrier Head with a Flexible Membrane".

Each of the polishing stations 105 may comprise a platen 106 configured to support and rotate a polishing pad thereon. Each polishing station 105 may further comprise a polishing solution dispenser, and a conditioner head. A detailed description of a platen and a polishing pad may be found in co-pending U.S. patent application Ser. No. 10/880,752, filed on Jun. 30, 2004, published as United States Patent Publication 2005/0000801, entitled "Method and Apparatus for Electrochemical Mechanical Processing". A detailed description for the polishing pad may be found in co-pending U.S. patent application Ser. No. 10/455,895, filed on Jun. 6, 2003, published as United States Patent Publication 2004/0020789, entitled "Conductive Polishing Article for Electrochemical Mechanical Polishing".

To perform a typical polishing process, one or more polishing stations 105 may be arranged in the track polishing system 100 to perform different polishing steps. At least one load cup for loading and unloading substrates is also arranged in the track polishing system 100 so that each of the polishing heads 103 may be loaded and unloaded. A detailed description of a load cup may be found in co-pending U.S. Pat. No. 7,044,832, entitled "Load Cup for Chemical Mechanical Polishing".

For a typical polishing process, one of the polishing heads 103 may be moved to a load cup that is positioned within the system frame 101 and accessible to each of the polishing heads 103 to perform a first polishing step, for example a bulk polish. A substrate may be loaded onto the substrate carrier 108 of the polishing head 103. The polishing head 103 may then move along the track assembly 102 by the carriage 109. A substrate may be loaded on a substrate carrier 108 at a loading station accessible to a first of the one or more polishing stations 105. The substrate is then lowered to be in contact with the platen 106 of the polishing station 105. The polishing head 103 may then press the substrate against the platen 106 and rotate the substrate using the polishing motor 107 to generate relative motion for polishing. The platen 106 is usually rotated during polishing. In one embodiment, the polishing head 103 may be oscillated about a position in the track assembly 102 providing a sweeping motion between the platen 106 and the substrate to improve polishing uniformity.

After polishing is complete in the first polishing station 105, the polishing head 103 may raise the substrate from the polishing station 105 and transfer the substrate along the track assembly 102 to the next polishing station 105 configured for a second polishing step, such as buffing.

The track polishing system **100** may be arranged according to a process recipe to have different arrangement of polishing stations, load cups, and cleaning stations. The track assembly **102** may define a path to allow each of the polishing heads to access the polishing stations, load cups and cleaning stations. The track assembly **102** may be linear, non-linear, curved, close looped, circular, non-circular, non-uniform curved path or with a shape of combinations thereof.

FIG. 2A is a schematic partial top view of a track polishing system **100a** having a circular track. The track polishing system **100a** comprises a circular track **111** disposed above four polishing stations **105**. A plurality of polishing heads **103** are independently movable along the circular track **111**. In one embodiment, two polishing heads **103** have access to one polishing station **105** simultaneously.

FIG. 2B is a schematic partial top view of a track polishing system **120** having a non-uniform curved track. The track polishing system **120** comprises a non-uniform curved track **122** disposed above two polishing stations **105**.

FIG. 3A is a schematic perspective sectional view of a track assembly **200** in accordance with one embodiment described herein. The track assembly **200** may be used in track polishing systems, similar to the track polishing system **100** described above. The track assembly **200** comprises a supporting frame **201**, which may be secured to a system frame of a polishing system.

A guiding rail **202** is attached to the supporting frame **201**. At least one carriage **205** is movably connected with the guiding rail **202**. In one embodiment, the carriage **205** may be connected with the guiding rail **202** via a guide block **206**. The guiding rail **202** is configured to restrain movement of the at least one carriage **205** to within a path **212**. In one embodiment, the guide block **206** has a channel **206a** configured to receive and secure a shoulder portion **202a** of the guiding rail **202**.

The track assembly **200** further comprises a stator strip **203** attached to the supporting frame **201**. Each of the carriages **205** comprises a rotor **210** facing the stator strip **203**. The stator strip **203** and the rotor **210** of each carriage **205** form a linear motor that propels the carriage **205** along the path **212**. Each of the carriages **205** is configured to attach and carry one or more polishing heads **207**. As shown in FIG. 3A, the polishing heads **207** may comprise a polishing motor **214** mounted on the carriage **205**, and a substrate carrier **215** connected to the polishing motor **214**.

In one embodiment, the stator strip **203** comprises a plurality of permanent magnets **203a** and the rotor **210** comprises a segment motor connected to a power supply **213**. The plurality of permanent magnets **203a** may be arranged next to one another in a single line. In one embodiment, each of the permanent magnets **203a** may be positioned such that neighboring permanent magnets **203a** having opposite magnetic fields, as shown in FIG. 3B. Variation of the electromagnetic field of the segment motor is used to actuate the carriage **205** to move along opposite directions or station at one point.

In one embodiment, an encoder scale **204** is attached to the supporting frame **201** along the path **212**. In another embodiment, the encoder scale **204** may be coupled with the stator strip **203**. A sensor assembly **209** may be facilitated on each carriage **205**. The sensor assembly **209** is configured to measure the encoder scale **204** to determine a location of the carriage **205** along the path **212** and/or velocity of the carriage **205**. The encoder scale **204** and the sensor assembly **209** may be selected from any suitable length measure system. In one embodiment, the encoder scale **204** comprises a magnetic

tape and the sensor assembly **209** comprises a read head configured to read the magnetic tape.

The sensor assembly **209** is connected to a system controller **211**, which is configured to independently control each carriage **205**. During processing, the system controller **211** acquires location and/or velocity of each carriage **205** according to measurements sent to the system controller **211** from the sensor assembly **209** of the corresponding carriage **205**. The system controller **211** then sends control signal to the power supply **213** to position the carriage **205** to a desired position.

Compared with traditional method for supporting and transporting polishing heads, the track system described herein has several advantages.

First, the track system has increased flexibility. Unlike the traditional carousel structure wherein a fixed number of polishing heads are transferred simultaneously by a carousel, the track system is not limited by number of polishing heads and each polishing head attached to the track system is actuated independently. Therefore, the track system provides increased flexibility in both arrangement of the whole polishing system and execution of polishing recipes.

Second, the track system has improved throughput. In the traditional carousel structure, movement of the polishing heads is slow because all of the polishing heads attached to the carousel need to move and stop at the same time. In the track system described herein, the track system and supporting structures remain stationary during operation, and actuators only need to slide one carriage and the polishing head attached to the carriage at each move. Thus, the track system can move polishing heads at much faster pace and increase system throughput.

Third, the track system has low maintenance requirement. Because parts of a system level, such as the track, the guiding rail and the supporting frame, are not movable, the large structures are less susceptible to failure. The moving parts, such as carriages, polishing heads, are structurally independent, thus may be repaired on, replaced independently without affecting the rest of the system. Thus, the maintenance of the track system described herein is relatively simple and easy to carry out.

FIG. 4 is a schematic partial top view of a track polishing system **300** in accordance with one embodiment described herein. The track polishing system **300** is a circular track system having two guiding rails concentric to a track to provide structural sturdiness.

The track polishing system **300** comprises a circular track assembly **301** secured to a system frame (not shown). The circular track assembly **301** is configured to support and provide a circular path to a plurality of polishing heads **307**. A plurality of working stations **308** is disposed underneath the circular track assembly **301**. Each of the polishing head **307** has access to all the plurality of working stations **308** by moving along the circular track assembly **301**. Each of the working stations **308** may be a polishing station, a load cup, and cleaning station, or any suitable apparatus required for a process.

The circular track assembly **301** comprises a first guiding rail **303** and a second guiding rail **304** concentrically disposed on a supporting frame **302**. The supporting frame **302** is configured to be attached to the system frame. The circular track assembly **301** further comprises a circular stator **305** disposed on the supporting frame **302**. The circular stator **305** is concentric to both the first guiding rail **303** and the second guiding rail **304**.

One or more carriages **306** are configured to slide along the both the first guiding rail **303** and the second guiding rail **304**.



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Each of the carriages 306 is configured to carry at least one polishing head 307. Each of the carriages 306 comprises two or more guide blocks configured to mount the carriage 306 on both the first guiding rail 303 and the second guiding rail 304, and a rotor configured to react with the circular stator 305 to actuate movements of the carriage 306 along the first and second guiding rails 303, 304. In one embodiment, each of the carriages 306 may be connected to a system controller 309 configured to independently control each carriage 306 and/or polishing heads attached thereto.

The first and second guiding rails 303, 304 may be arranged as inner and outer guiding rails on the same plane, or arranged vertically. In one embodiment, the first guiding rail 303 may be disposed radially outwards the second guiding rail 304, and the circular stator 305 disposed between the first guiding rail 303 and the second guiding rail 304. The guiding rails 303, 304 are configured to retrain the path of the carriages 306 as well as provide structural support to the carriage 306 and the polishing head 307. Different designs of a double rail track assembly are described with FIGS. 5-8 below.

FIG. 5 is a schematic sectional side view of a track assembly 400 in accordance with one embodiment described herein. The track assembly 400 may be used in any track polishing systems, for example, a circular track system similar to the circular track system 300 of FIG. 4.

The track assembly 400 comprises a stationary portion having a supporting frame 401, which may be mounted on a system frame of a polishing system. The stationary portion further comprises a first guiding rail 402, a second guiding rail 403, a stator strip 404, and an encoder scale 405 mounted on the supporting frame 401. The guiding rails 402, 403, stator strip 404, and encoder scale 405 define a path along which polishing heads are configured to travel. The guiding rails 402, 403, the stator strip 404, and the encoder scale 405 may be parallel, concentric, or locally parallel depending on the shape of the path. For example, the guiding rails 402, 403, the stator strip 404, and the encoder scale 405 are substantially concentric for a circular track, parallel overall for a linear track, or parallel portion by portion for a curved track.

The track assembly 400 further comprises a mobile portion comprising one or more carriage assemblies 415. The carriage assemblies 415 comprise a carriage body 407 on which a guide block 408 and a guide block 409 are mounted. The guide block 408 has an inner channel 408a configured to receive the guiding rail 403, and the guide block 409 has an inner channel 409a configured to receive the guiding rail 402. The inner channels 408a, 409a allow the carriage assembly 415 to slide along the stationary portion of the track assembly 400. In one embodiment, the guide blocks 408, 409 may comprise two or more sections configured to provide secured attachment between the guiding rails 402, 403.

The carriage assembly 415 further comprises a rotor 410 positioned facing the stator strip 404. The rotor 410 is configured to push the carriage assembly 415 along the guiding rails 402, 403 or to station the carriage assembly 415 on the guiding rails 402, 403 by reacting with the stator strip 404. In one embodiment, the stator strip 404 and the rotor 410 do not contact one another. In one embodiment, the stator strip 404 comprises a plurality of permanent magnets and the rotor 410 comprises a segment motor.

The carriage assembly 415 further comprises a sensor assembly 414 positioned opposite the encoder scale 405 on the supporting frame 401. The sensor assembly 414 is configured to read the encoder scale 405 and provide position, and/or velocity of the carriage assembly 415 in relative to the encoder scale 405, and the guiding rails 402, 403.

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The carriage assembly 415 further comprises a mounting component 411 attached to the carriage body 407. The mounting component 411 has a "C" shape and is configured to provide an interface with any devices to be carried by the carriage assembly 415. In one embodiment, a polishing head 416 having a polishing motor 412 and a substrate carrier 413 is mounted on the mounting component 411.

In this embodiment, the two guiding rails 402, 403 are used to define a path of the track and to bear the weight of the carriage assemblies 415 and anything mounted on the carriage assemblies 415.

FIG. 6 is a schematic sectional side view of a track assembly 500 in accordance with another embodiment described herein. The track assembly 500 may be used in any track polishing systems, for example, a circular track system similar to the circular track system 300 of FIG. 4.

The track assembly 500 comprises a stationary portion having a supporting frame 501, which is mounted on a system frame of a polishing system. The stationary portion further comprises a first guiding rail 502, a second guiding rail 503, a stator strip 504, and an encoder scale 505 mounted on the supporting frame 501. The guiding rails 502, 503, stator strip 504, and encoder scale 505 define a path along which polishing heads are configured to travel. The guiding rails 502, 503, stator strip 504, and encoder scale 505 may be parallel, concentric, or locally parallel depending on the shape of the path. For example, the guiding rails 502, 503, stator strip 504, and encoder scale 505 are substantially concentric for a circular track, parallel overall for a linear track, or parallel portion by portion for a curved track.

The track assembly 500 further comprises a mobile portion comprising one or more carriage assemblies 515 hanging on the guiding rails 502, 503. The carriage assemblies 515 comprise a carriage body 507 on which a guide block 508 and a guide block 509 are mounted. The guide block 508 has an inner channel 508a configured to receive the guiding rail 503, and the guide block 509 has an inner channel 509a configured to receive the guiding rail 502. The inner channels 508a, 509a allow the carriage assembly 515 to slide along the stationary portion of the track assembly 500. In one embodiment, the guide blocks 508, 509 may comprise two or more sections configured to provide secured attachment between the guiding rails 502, 503.

The carriage assembly 515 further comprises a rotor 510 positioned facing the stator strip 504. The rotor 510 is configured to push the carriage assembly 515 along the guiding rails 502, 503 or to station the carriage assembly 515 on the guiding rails 502, 503 by reacting with the stator strip 504. In one embodiment, the stator strip 504 and the rotor 510 do not contact one another. In one embodiment, the stator strip 504 comprises a plurality of permanent magnets and the rotor 510 comprises a segment motor.

The carriage assembly 515 further comprises a sensor assembly 514 positioned opposite the encoder scale 505 on the supporting frame 501. The sensor assembly 514 is configured to read the encoder 505 and provide position, and/or velocity of the carriage assembly 515 in relative to the encoder scale 505, and the guiding rails 502, 503.

The carriage assembly 515 further comprises a mounting component 511 attached to the carriage body 507. The mounting component 511 is configured to provide interface to any devices to be carried by the carriage assembly 515. In one embodiment, a polishing head 516 having a polishing motor 512 and a substrate carrier 513 is mounted on the mounting component 511.

FIG. 7 is a schematic sectional side view of a track assembly 600 in accordance with another embodiment described

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herein. The track assembly 600 may be used in any track polishing systems, for example, a circular track system similar to the circular track system 300 of FIG. 4.

The track assembly 600 comprises a stationary portion having a supporting frame 601, and a first guiding rail 602, a second guiding rail 603, a stator strip 604, and an encoder scale 605 mounted on the supporting frame 601. The guiding rails 602, 603, the stator strip 604, and the encoder scale 605 define a path along which polishing heads are configured to travel. The guiding rails 602, 603, the stator strip 604, and the encoder scale 605 may be parallel, concentric, or locally parallel depending on the shape of the path. For example, the guiding rails 602, 603, the stator strip 604, and the encoder scale 605 are substantially concentric for a circular track, parallel overall for a linear track, or parallel portion by portion for a curved track.

The track assembly 600 further comprises a mobile portion comprising one or more carriage assemblies 615 hanging on the guiding rails 602, 603. The carriage assemblies 615 comprise a carriage body 607 on which a guide block 608 and a guide block 609 are mounted. The guide block 608 has an inner channel 608a configured to receive the guiding rail 603, and the guide block 609 has an inner channel 609a configured to receive the guiding rail 602. The inner channels 608a, 609a allow the carriage assembly 615 to slide along the stationary portion of the track assembly 600. In one embodiment, the guide blocks 608, 609 may comprise two or more sections configured to provide secured attachment between the guiding rails 602, 603. In one embodiment, the carriage body 607 may be designed to assert the weight of the carriage assemblies 615 is evenly distributed between the guiding rails 602, 603.

The carriage assembly 615 further comprises a rotor 610 positioned facing the stator strip 604. The rotor 610 is configured to push the carriage assembly 615 along the guiding rails 602, 603 or to station the carriage assembly 615 on the guiding rails 602, 603 by reacting with the stator strip 604. In one embodiment, the stator strip 604 and the rotor 610 do not contact one another. In one embodiment, the stator strip 604 comprises a plurality of permanent magnets and the rotor 610 comprises a segment motor.

The carriage assembly 615 further comprises a sensor assembly 614 positioned opposite the encoder scale 605 on the supporting frame 601. The sensor assembly 614 is configured to read the encoder 605 and provide position, and/or velocity of the carriage assembly 615 relative to the encoder scale 605, and the guiding rails 602, 603.

The carriage assembly 615 further comprises a mounting component 611 attached to the carriage body 607. The mounting component 611 is configured to provide an interface with any devices to be carried by the carriage assembly 615. In one embodiment, a polishing head 616 having a polishing motor 612 and a substrate carrier 613 is mounted on the mounting component 611.

FIG. 8 is a schematic sectional side view of a track assembly 700 in accordance with another embodiment described herein. The track assembly 700 may be used in any track polishing systems, for example, a circular track system similar to the circular track system 300 of FIG. 4.

The track assembly 700 comprises a stationary portion having a supporting frame 701. In one embodiment, the supporting frame 701 comprises an upper frame 701a and a lower frame 701b connected by a plurality of supporting columns 701c. The stationary portion further comprises a first guiding rail 702 mounted on a bottom side of the lower frame 701b, a second guiding rail 703 mounted on a top side of the upper frame 701a. The stationary portion further comprises a stator

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strip 704 disposed on a top side of the lower frame 701b and a stator strip 706 disposed on a bottom side of the upper frame 701a. The stator strips 704, 706 provide more interaction with the moving portion of the track assembly 700.

The stationary portion further comprises an encoder scale 705 mounted on the supporting frame 701. The guiding rails 702, 703, stator strips 704, 706, and encoder scale 705 define a path along which polishing heads are configured to travel. The guiding rails 702, 703, stator strips 704, 706, and encoder scale 705 may be parallel, concentric, or locally parallel depending on the shape of the path. For example, the guiding rails 702, 703, the stator strips 704, 706, and the encoder scale 705 are substantially concentric for a circular track, parallel overall for a linear track, or parallel portion by portion for a curved track.

The track assembly 700 further comprises a mobile portion comprising one or more carriage assemblies 715 hanging on the guiding rails 702, 703. The carriage assemblies 715 comprise a carriage body 707 on which a guide block 708 and a guide block 709 are mounted. The guide block 708 has an inner channel 708a configured to receive the guiding rail 703, and the guide block 709 has an inner channel 709a configured to receive the guiding rail 702. The inner channels 708a, 709a allow the carriage assembly 715 to slide along the stationary portion of the track assembly 700. In one embodiment, the guide blocks 708, 709 may comprise two or more sections configured to provide secured attachment between the guiding rails 702, 703. In one embodiment, the carriage body 707 may be designed to assure that the weight of the carriage assemblies 715 is evenly distributed between the guiding rails 702, 703.

The carriage assembly 715 further comprises a rotor 710 positioned facing the stator strip 704. The rotor 710 is configured to push the carriage assembly 715 along the guiding rails 702, 703 or to station the carriage assembly 715 on the guiding rails 702, 703 by reacting with the stator strips 704, 706. The rotor 710 is disposed between the stator strips 704, 706. In one embodiment, each of the stator strips 704, 706 comprises a plurality of permanent magnets and the rotor 710 comprises one or more segment motors.

The carriage assembly 715 further comprises a sensor assembly 714 positioned opposite the encoder scale 705 on the supporting frame 701. The sensor assembly 714 is configured to read the encoder scale 705 and provide position, and/or velocity of the carriage assembly 715 relative to the encoder scale 705, and the guiding rails 702, 703.

The carriage assembly 715 further comprises a mounting component 711 attached to the carriage body 707. The mounting component 711 is configured to provide an interface with any devices to be carried by the carriage assembly 715. In one embodiment, a polishing head 716 having a polishing motor 712 and a substrate carrier 713 is mounted on the mounting component 711. The carriage body 707 is substantially a cantilever structure with one end secured to the guiding rails 702, 703, and an opposite end bearing the weight of the polishing head 716.

FIG. 9 is a schematic top view of a track polishing system 300a described herein in a maintenance state. The track polishing system 300a is similar to the track polishing system 300 of FIG. 4. As shown in FIG. 9, the polishing heads 307 may be gathered at a dedicated maintenance corner 310 during maintaining, thus, saving space and time.

Even though a polishing process is described with the track system described herein, a person skilled in the art can apply the track in any suitable processes that require movement of substrates between different workstations.

Polishing Head:

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FIG. 10A is a schematic perspective view of a polishing head 1000 in accordance with one embodiment described herein. FIG. 10B is a schematic sectional side view of the polishing head 1000 of FIG. 10A. The polishing head 1000 is configured to transfer and process substrates along a track assembly 1004 (shown FIG. 10B) having two guiding rails 1006, 1007.

The polishing head 1000 comprises a carriage body 1001, and guide blocks 1002, 1003 configured to receive the guiding rails 1006, 1007 of the track assembly 1004. The guide blocks 1002, 1003 have sliding channels 1002a, 1003a formed therein to receive guiding rails. In one embodiment, each of the guide blocks 1002, 1003 may comprise two or more segments configured to provide enhanced support to the carriage body 1001 and devices attached thereto.

In one embodiment, the polishing head 1000 is configured to move along a circular track system having two concentric guiding rails. As shown in FIG. 10A, the guide blocks 1002, 1003 are configured to receive an inner circular guiding rail and an outer circular guiding rail respectively. In one embodiment, the sliding channels 1002a, 1003a are curved to match the guiding rails. In one embodiment, each of the guide blocks 1002, 1003 comprises two curved segments positioned on opposite ends of the carriage body 1001.

An actuator assembly 1010 is attached to the carriage body 1001. The actuator assembly 1010 comprises a rotor 1011 configured to transport the polishing head 1000 along a track assembly by reacting with a stator strip of the track assembly. For example, as shown in FIG. 10B, the rotor 1011 is configured to react with a stator strip 1008 attached to a supporting frame 1005 of the track assembly 1004. In one embodiment, the actuator assembly 1010 comprises a second rotor 1012 disposed on opposite side of the rotor 1011. The actuator assembly 1010 is configured to transport the polishing head 1000 by reacting with a second stator strip of the track assembly. As shown in FIG. 10B, the rotor 1012 is configured to react with a stator strip 1009 of the track assembly 1004.

The rotors 1011 and 1012 may be used alone or in combination to achieve different functions during processing, for example, transportation and sweeping.

In one embodiment, the rotors 1011, 1012 are segment motors configured to react with stator strips comprises a plurality of permanent magnets. The rotors 1011, 1012 are connected to power supplies 1011a, 1012a which may be controlled by a system controller 1017.

The polishing head 1000 further comprises a sensor assembly 1016 disposed in a location to read an encoder scale in a track assembly, for example an encoder scale 1018 of the track assembly 1004. The sensor assembly 1016 is configured to detect position and/or velocity of the polishing head 1000 relative to the track assembly. In one embodiment, the sensor assembly 1016 is connected to the system controller 1017 which may use measurements from the sensor assembly 1016 to control the rotors 1011, 1012.

The polishing head 1000 further comprises a polishing assembly 1013 connected to the carriage body 1001. In one embodiment, the polishing assembly 1013 comprises at least one polishing motor 1014 connected to a substrate carrier 1015. The polishing motor 1014 is configured to rotate the substrate carrier 1015 during polishing. In one embodiment, the polishing assembly 1013 may comprise a second polishing motor connected to a second substrate carrier configured to process a second substrate at the same polishing station simultaneously.

FIG. 11A is a schematic sectional side view of a polishing head 1100 in accordance with one embodiment described herein. FIG. 11B is a schematic top view of the polishing head

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1100 of FIG. 11A. The polishing head 1100 is configured to transfer and process substrates along a track assembly 1104 (shown in dashed lines in FIGS. 11A-11B) having two guiding rails 1106, 1107.

The polishing head 1100 comprises a carriage body 1101, and guide blocks 1102, 1103 configured to receive the guiding rails 1106, 1107 of the track assembly 1104. The guide blocks 1102, 1103 have sliding channels 1102a, 1103a formed therein to receive guiding rails. In one embodiment, each of the guide blocks 1102, 1103 may comprises two or more segments configured to provide enhanced support to the carriage body 1101 and devices attached thereto.

In one embodiment, the polishing head 1100 is configured to move along a circular track system having two concentric guiding rails. As shown in FIG. 11A, each of the guide blocks 1102, 1103 comprises two curved segments positioned on opposite ends of the carriage body 1101.

A rotor 1111 is attached to the carriage body 1101. The rotor 1111 is configured to transport the polishing head 1100 along the track assembly 1104 by reacting with a stator strip 1108 disposed on a supporting frame 1105 of the track assembly 1104.

In one embodiment, the rotor 1111 is a segment motor configured to react with a plurality of permanent magnets of the stator strip 1108. The rotor 1111 is connected to a power supply which may be controlled by a system controller.

The polishing head 1100 further comprises a sensor assembly 1116 disposed in a location to read an encoder scale in a track assembly, for example an encoder scale 1118 of the track assembly 1104. The sensor assembly 1116 is configured to detect position and/or velocity of the polishing head 1100 relative to the track assembly. In one embodiment, the sensor assembly 1116 is connected to the system controller which may use measurements from the sensor assembly 1116 to control the rotor 1111.

The polishing head 1100 further comprises a mounting frame 1109 coupled to the carriage body 1101. A polishing assembly 1113 is mounted on the mounting frame 1109 and connected to the carriage body 1101. The mounting frame 1109 has a "C" shape and is configured to position the polishing assembly 1113 directly under the track assembly 1104.

In one embodiment, the polishing assembly 1113 comprises at least one polishing motor 1114 connected to a substrate carrier 1115. The polishing motor 1114 is configured to rotate the substrate carrier 1115 during polishing. In one embodiment, the polishing assembly 1113 may comprise a second polishing motor connected to a second substrate carrier configured to process a second substrate at the same polishing station simultaneously.

FIG. 12 is a schematic sectional side view of a polishing head 1100a in accordance with one embodiment described herein. The polishing head 1100a is similar to the polishing head 1100 shown in FIG. 11A, except the polishing head 1100a comprises a mounting frame 1119 which is substantially a cantilever. The mounting frame 1119 has a first end 1119a coupled to the carriage body 1101, and a second end 1119b opposing the first end 1119a. The polishing assembly 1113 may be mounted on the second end 1119b. The mounting frame 1119 allows the polishing head 1100a to position the polishing assembly 1113 away from the track assembly 1104. The polishing head 1100a may be used in suitable system designs, for example in designs where polishing stations are spread in an area larger than an area covered by the track assembly 1104.

FIG. 13 is a schematic sectional side view of a polishing head 1300 and a track assembly 1315 in accordance with

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another embodiment described herein. The track assembly **1315** may be linear, curved, or circular.

The track assembly **1315** comprises a stationary portion having a supporting frame **1301**, a first guiding rail **1302**, a second guiding rail **1303**, a stator strip **1304**, and an encoder scale **1305** mounted on the supporting frame **1301**. The guiding rails **1302**, **1303**, the stator strip **1304**, and the encoder scale **1305** define a path along which the polishing head **1300** is configured to travel. The guiding rails **1302**, **1303**, the stator strip **1304**, and the encoder scale **1305** may be parallel, concentric, or locally parallel depending on the shape of the path.

The guiding rails **1302**, **1303** are attached to the supporting frame **1301** on a bottom side. The polishing head **1300** hangs on the guiding rails **1302**, **1303**. The polishing head **1300** comprises a carriage body **1307** on which a guide block **1308** and a guide block **1309** are mounted. The guide block **1308** has an inner channel **1308a** configured to receive the guiding rail **1303**, and the guide block **1309** has an inner channel **1309a** configured to receive the guiding rail **1302**. The inner channels **1308a**, **1309a** allow the polishing head **1300** to slide along the stationary portion of the track assembly **1315**. In one embodiment, the guide blocks **1308**, **1309** may comprise two or more sections configured to provide secured attachment between the guiding rails **1302**, **1303**.

The polishing head **1300** further comprises a rotor **1310** positioned facing the stator strip **1304**. The rotor **1310** is configured to push the polishing head **1300** along the guiding rails **1302**, **1303** or to station the polishing head **1300** on the guiding rails **1302**, **1303** by reacting with the stator strip **1304**. In one embodiment, the stator strip **1304** comprises a plurality of permanent magnets and the rotor **1310** comprises a segment motor.

The polishing head **1300** further comprises a sensor assembly **1314** positioned opposite the encoder scale **1305** on the supporting frame **1301**. The sensor assembly **1314** is configured to read the encoder **1305** and provide position, and/or velocity of the polishing head **1300** relative to the encoder scale **1305**, and the guiding rails **1302**, **1303**.

The polishing head **1300** further comprises a mounting component **1311** attached to the carriage body **1307**. The mounting component **1311** is configured to provide an interface with any devices to be carried by the polishing head **1300**. In one embodiment, a polishing motor **1312** and a substrate carrier **1313** is mounted on the mounting component **1311**.

FIG. 14 is a schematic sectional side view of a polishing head **1400** and a track assembly **1415** in accordance with another embodiment described herein. The track assembly **1415** may be linear, curved, or circular.

The track assembly **1415** comprises a stationary portion having a supporting frame **1401**, a first guiding rail **1402**, a second guiding rail **1403**, a stator strip **1404**, and an encoder scale **1405** mounted on the supporting frame **1401**. The guiding rails **1402**, **1403**, stator strip **1404**, and encoder scale **1405** define a path along which the polishing head **1400** is configured to travel. The guiding rails **1402**, **1403**, stator strip **1404**, and encoder scale **1405** may be parallel, concentric, or locally parallel depending on the shape of the path.

The guiding rails **1402**, **1403** are attached to the supporting frame **1401** on a top side and the stator strip **1404** disposed on a bottom side of the supporting frame **1401**. The polishing head **1400** comprises a carriage body **1407** on which a guide block **1408** and a guide block **1409** are mounted. The carriage body **1407** wraps around the track assembly **1415** with the guide blocks **1408**, **1409** sitting on the guiding rails **1402**, **1403**. The guide block **1408** has an inner channel **1408a** configured to receive the guiding rail **1403**, and the guide

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block **1409** has an inner channel **1409a** configured to receive the guiding rail **1402**. The inner channels **1408a**, **1409a** allow the polishing head **1400** to slide along the stationary portion of the track assembly **1415**. In one embodiment, the guide blocks **1408**, **1409** may comprise two or more sections configured to provide secured attachment between the guiding rails **1402**, **1403**.

The polishing head **1400** further comprises a rotor **1410** positioned facing the stator strip **1404**. The rotor **1410** is configured to push the polishing head **1400** along the guiding rails **1402**, **1403** or to station the polishing head **1400** on the guiding rails **1402**, **1403** by reacting with the stator strip **1404**. In one embodiment, the stator strip **1404** comprises a plurality of permanent magnets and the rotor **1410** comprises a segment motor.

The polishing head **1400** further comprises a sensor assembly **1414** positioned opposite the encoder scale **1405** on the supporting frame **1401**. The sensor assembly **1414** is configured to read the encoder **1405** and provide position, and/or velocity of the polishing head **1400** relative to the encoder scale **1405**, and the guiding rails **1402**, **1403**.

The polishing head **1400** further comprises a mounting component **1411** attached to the carriage body **1407**. The mounting component **1411** is configured to provide interface to any devices to be carried by the polishing head **1400**. In one embodiment, a polishing motor **1412** and a substrate carrier **1413** is mounted on the mounting component **1411**.

FIG. 15 is a schematic sectional side view of a polishing head **1500** and a track assembly **1515** in accordance with another embodiment described herein. The track assembly **1515** may be linear, curved, or circular.

The track assembly **1515** comprises a stationary portion having a supporting frame **1501**. The supporting frame **1501** comprises an upper frame **1501a** and a lower frame **1501b** connected by a plurality of supporting columns **1501c**. The stationary portion further comprises a first guiding rail **1502** mounted on a bottom side of the lower frame **1501b**, a second guiding rail **1503** mounted on a top side of the upper frame **1501a**. The stationary portion further comprises a stator strip **1504** disposed on a top side of the lower frame **1501b** and a stator strip **1506** disposed on a bottom side of the upper frame **1501a**. The stator strips **1504**, **1506** provide more interaction with the polishing head **1500**.

The guiding rails **1502**, **1503**, the stator strips **1504**, **1506**, and the encoder scale **1505** define a path along which the polishing head **1500** is configured to travel. The guiding rails **1502**, **1503**, the stator strip **1504**, **1506**, and the encoder scale **1505** may be parallel, concentric, or locally parallel depending on the shape of the path.

The polishing head **1500** is attached to the guiding rails **1502**, **1503**. The polishing head **1500** comprises a carriage body **1507** on which a guide block **1508** and a guide block **1509** are mounted. The guide block **1508** has an inner channel **1508a** configured to receive the guiding rail **1503**, and the guide block **1509** has an inner channel **1509a** configured to receive the guiding rail **1502**. The inner channels **1508a**, **1509a** allow the carriage assembly **1515** to slide along the stationary portion of the track assembly **1515**. In one embodiment, the guide blocks **1508**, **1509** may comprise two or more sections configured to provide secured attachment between the guiding rails **1502**, **1503**. In one embodiment, the carriage body **1507** may be designed to assert the weight of the carriage assemblies **1515** is evenly distributed between the guiding rails **1502**, **1503**.

The polishing head **1500** further comprises a rotor **1510** positioned facing the stator strip **1504**. The rotor **1510** is configured to push the polishing head **1500** along the guiding

rails **1502**, **1503** or to station the polishing head **1500** on the guiding rails **1502**, **1503** by reacting with the stator strips **1504**, **1506**. The rotor **1510** is disposed between the stator strips **1504**, **1506**. In one embodiment, each of the stator strips **1504**, **1506** comprises a plurality of permanent magnets and the rotor **1510** comprises one or more segment motors.

The polishing head **1500** further comprises a sensor assembly **1514** positioned opposite the encoder scale **1505** on the supporting frame **1501**. The sensor assembly **1514** is configured to read the encoder **1505** and provide position, and/or velocity of the polishing head **1500** relative to the encoder scale **1505**, and the guiding rails **1502**, **1503**.

The polishing head **1500** further comprises a mounting component **1511** attached to the carriage body **1507**. The mounting component **1511** is configured to provide an interface with any devices to be carried by the polishing head **1500**. In one embodiment, a polishing head **1516** having a polishing motor **1512** and a substrate carrier **1513** is mounted on the mounting component **1511**. The carriage body **1507** is substantially a cantilever structure with one end secured to the guiding rails **1502**, **1503**, and an opposite end bearing the weight of the polishing head **1516**.

FIG. **16** is a schematic perspective view of a polishing head **1600** having two substrate carriers **1608**, **1609** in accordance with one embodiment described herein. As discussed above, polishing heads in accordance with embodiments described herein, may comprise multiple substrate carriers for processing multiple substrates simultaneously.

The polishing head **1600** comprises a carriage body **1601** having guide blocks **1603**, **1604**, rotors **1605**, **1606**, a sensor **1607** attached thereto, and configured to facilitate movement of the polishing head along a track assembly.

A mounting frame **1602** is attached to the carriage body **1601** and configured to connect two substrate carriers **1608**, **1609** each configured to carry and process one substrate. The substrate carriers **1608**, **1609** are transported and oscillated along the track assembly together by the carriage body **1601**. In one embodiment, the transportation of the substrate carriers **1608**, **1609** may be performed by the rotor **1606**, and the oscillation may be performed by the rotor **1605**.

The arrangement of actuators for transportation and oscillation may be determined by process requirements. FIG. **17** schematically illustrates different configurations of actuators for transportation and sweeping in accordance with embodiments described herein.

Polishing head **1751** comprises one actuator **1751a** and one carrier head **1751h**. The actuator **1751a** is configured to conduct both transportation and oscillation of the carrier head **1751h**. This embodiment is efficient with only one actuator, structurally robust. The single actuator configuration also reduces chances of cross talk among actuators.

Polishing head **1752** comprises a carrier head **1752h**, a transport actuator **1752a** and a sweeping actuator **1752b** configured to conduct transportation and oscillation the carrier head **1752h** respectively. The configuration allows choosing suitable actuators for sweeping and transportation.

Polishing head **1753** comprises two carrier heads **1753h**, **1753i**, a transport actuator **1753a** configured to transfer the carrier heads **1753h**, **1753i**, and two oscillate actuators **1753b**, **1753c** configured to oscillate the carrier heads **1753h**, **1753i** respectively. This configuration provides flexibility between the two carrier heads **1753h**, **1753i**. The carrier heads **1753h**, **1753i** may be mounted on separate carrier bodies to allow independent sweeping motion.

Polishing head **1754** comprises two carrier heads **1754h**, **1754i**, a transport actuator **1754a** configured to transfer the carrier heads **1754h**, **1754i**, and an oscillate actuator **1754b**

configured to oscillate the carrier heads **1754h**, **1754i** together. The configuration allows choosing suitable actuators for sweeping and transportation.

Even though a planarization process is described with the non-contact substrate holder described herein, a person skilled in the art can apply the non-contact substrate holder for holding and transferring substrates in any suitable processes, including but not limited to wet cleaning, electroplating, and electroless plating.

Shield Assembly:

Embodiments described herein further provide a shield for isolating a substrate processing environment from substrate transferring mechanisms in an overhead circular track system which advantageously reduces system maintenance and increases system uptime.

FIG. **18A** is a perspective view of a track system **1800** with a shield assembly **1810** in accordance with one embodiment described herein. FIG. **18B** is a bottom view of the track system **1800** with the shield assembly **1810** of FIG. **18A**. The shield assembly **1810** comprises an outer stationary shield **1812**, an inner stationary shield **1814**, and a plurality of movable shields **1816a-1816f**. The outer stationary shield **1812**, the inner stationary shield **1814**, and the movable shields **1816a-1816f** work in conjunction to isolate the substrate transfer mechanisms and electronic components of the track system **1800** from the processing environment. In one embodiment, the isolated area containing the substrate transfer mechanisms and electronic components has suction ports to further isolate the process environment from the substrate transfer mechanisms and electronic components. In one embodiment, the isolated area may be pressurized to further isolate the process environment from the substrate transfer mechanisms and electronic components.

The outer stationary shield **1812** is coupled with the supporting frame **1005**. The outer stationary shield **1812** is of unitary construction and comprises a cylindrical band **1818** dimensioned to encircle the two guide rails **1006**, **1007** (not shown in this view). A rim **1820** extends radially outward from the top of the cylindrical band **1818** of the outer stationary shield **1812**. The rim **1820** may have a plurality of holes for securing the outer stationary shield **1812** to the supporting frame **1005**. The outer stationary shield **1812** may be coupled with the supporting frame **1005** using, for example, rivets, screws, or any other attachment means known in the art. An inner lip **1822** extends radially inward from the bottom of the cylindrical band **1818** of the outer stationary shield **1812**. In one embodiment, the outer stationary shield **1812** comprises four separate crescent shaped pieces which are welded together to form the outer stationary shield **1812**.

The inner stationary shield **1814** is also coupled with the supporting frame **1005**. The inner stationary shield **1814** is of unitary construction and comprises a cylindrical band **1824** dimensioned to fit within the inner diameter of the two guide rails **1006**, **1007**. A lip **1826** extends radially inward from the top of the cylindrical band **1824** of the inner stationary shield **1814**. The lip **1826** may have a plurality of holes for securing the inner stationary shield **1814** with the supporting frame **1005** using, for example, rivets, screws, or any other attachment means known in the art. An outer lip **1828** extends radially outward from the bottom of the cylindrical band **1824** of the inner stationary shield **1814**. In one embodiment, the outer stationary shield **1812** comprises four separate pieces which are welded together to form the outer stationary shield **1814**.

The movable shields **1816a-1816f** may be coupled with the carriage body **1001**. In one embodiment, each movable shield **1816a-1816f** is coupled with a corresponding adapter plate

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**1817a-1817f** of the carriage body **1001**. Although only one moveable shield **1816a-1816f** is shown coupled with each corresponding adapter plate **1817a-1817f**, it should be understood that multiple movable shields may be coupled with each adapter plate **1817a-1817f**; for example, one shield may be coupled on opposing sides of each adapter plate **1817a-1817f** for a total of two movable shields coupled with each adapter plate **1817a-1817f** as shown in FIG. 19. It should also be understood that the track system **1800** may be configured to have more or less than six adapter plates depending upon the users needs. The movable shields may be coupled with each adapter plate **1817a-1817f**.

Each movable shield **1816a-1816f** comprises a wedge-shaped plate. Each movable shield **1816a-1816f** is dimensioned so that the outer periphery of each movable shield overlaps the inner lip **1822** of the cylindrical band **1818** of the outer stationary shield **1812**. Each movable shield **1816a-1816f** is further designed so that the inner periphery of the movable shield overlaps with the outer lip **1828** of the inner stationary shield **1814**. Each movable shield **1816a-1816f** may have a plurality of holes for securing the movable shield **1816a-1816f** to a corresponding adapter plate **1817a-1817f** using, for example, rivets, screws, or any other attachment means known in the art.

In embodiments, where the number of adapter plates and corresponding movable shields do not sufficiently isolate the substrate processing environment from substrate transferring mechanisms any number of additional movable shields **1830** which may be uncoupled from the adapter plates may be added. The additional movable shield **1830** comprises a crescent shaped piece. The additional movable shield may be coupled with the guide rails **1006**, **1007** using guide blocks **1002**, **1003**.

FIG. 19 is a bottom view of a track system **1900** with a shield assembly **1910** in accordance with one embodiment described herein. Like the shield assembly **1810** shown in FIGS. 18A and 18B, the shield assembly **1910** comprises an outer stationary shield **1812**, an inner stationary shield **1814**, and a plurality of movable shields **1916a-1916k**. However, in the embodiment of FIG. 19, each adapter plate **1817a-1817f** is coupled with two shields. For example, the adapter plate **1817a** is coupled with movable shield **1916a** and movable shield **1916b**. Also, as shown in FIG. 19, adjacent movable shields may overlap. For example, movable shield **1916b** is located in a z-plane slightly above the plane of movable shield **1916c** such that the movable shield **1916b** may overlap and/or telescope with the movable shield **1916c**. A portion of the movable shield in FIG. 19 has been removed to show the inner guide rail **1006** and the outer guide rail **1007**.

In operation, the adapter plates move in pairs. For example, adapter plates **1817a** and **1817b** may move either clockwise or counterclockwise in unison. As the adapter plates **1817a** and **1817b** move in unison, movable shield **1916b** and movable shield **1916c** maintain there overlapping positions thus maintaining isolation of the substrate processing environment from the substrate transferring mechanisms.

FIG. 20 is a schematic partial cross-sectional view of a track system **2000** with a shield assembly **2002** in accordance with one embodiment described herein. The shield assembly **2002** comprises a movable u-shaped shield **2004**. The u-shaped shield **2004** comprises an annular band **2006**. An outer cylindrical band **2008** and an inner cylindrical band **2010** are coupled with and extend upward from the annular band **2006**. The u-shaped shield **2004** is coupled with the carriage body **1001** such that the u-shaped shield moves with the carriage body **1001** as the carriage assembly travels along the guide rails **1006**, **1007**. In one embodiment, the u-shaped

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shield **2004** is coupled between the adapter plate **1817d** and the carriage body **1001**. Each u-shaped shield telescopes with an adjacent u-shaped shield such that the substrate transferring mechanisms remain isolated from the processing environment.

FIG. 21 is a schematic partial cross-sectional view of a track system **2100** with a shield assembly **2102** in accordance with another embodiment described herein. The shield assembly **2102** is a 3-piece shield assembly comprising an outer L-shaped stationary shield **2104** and an inner L-shaped stationary shield **2106** coupled with the supporting frame **1005** and a donut or toroidal shaped shield **2108** suspended from the adapter plate **1817d** in a recess **2107** formed between the adapter plate **1817d** and the carriage body **1001**. In one embodiment, the outer L-shaped stationary shield **2104** and the inner L-shaped stationary shield **2106** are coupled with a top plate of the supporting frame **1005**.

The outer L-shaped stationary shield **2104** is of unitary construction and comprises a cylindrical band **2110** dimensioned to encircle the outer guide rail **1007**. A rim **2112** extends radially outward from the top of the cylindrical band **2110** of the outer L-shaped stationary shield **2104**. The rim **2112** may have a plurality of holes for securing the outer L-shaped stationary shield **2104** to the supporting frame **1005**. The outer L-shaped stationary shield **2104** may be coupled with the supporting frame **1005** using, for example, rivets, screws, or any other attachment means known in the art. An inner lip **2114** extends radially inward from the bottom of the cylindrical band **2110** of the outer L-shaped stationary shield **2104**. The inner lip **2114** extends radially inward into a recess **2116** formed in the carriage body **1001**.

The inner L-shaped stationary shield **2106** is also of unitary construction and comprises a cylindrical band **2120** dimensioned to fit within the inner diameter of the inner guide rail **1006**. A lip **2122** extends radially inward from the top of the cylindrical band **2120** of the inner L-shaped stationary shield **2106**. The lip **2122** may have a plurality of holes for securing the inner L-shaped stationary shield **2106** with the supporting frame **1005** using, for example, rivets, screws, or any other attachment means known in the art. An outer lip **2124** extends radially outward from the bottom of the cylindrical band **2120** of the inner L-shaped stationary shield **2106**. The outer lip **2124** extends radially outward into the recess **2126** formed in the carriage body **1001**.

The donut shaped shield **2108** is of unitary construction and comprises an annular band **2130** having a hole in the center. The donut shaped shield **2108** is suspended from the adapter plate **1817d** in the recess **2107** formed between the adapter plate **1817d** and the carriage body **1001**. The donut shaped shield **2108** is dimensioned to cover the entire circular area of the inner guide rail **1006** and the outer guide rail **1007**. Each carriage assembly comprises support such as rollers or guides **2132** for the donut shaped shield **2108**. Advantageously, this shield assembly **2102** can be used with all platen and polishing head configurations and in each configuration the angles between each carriage assembly may be variable.

FIG. 22 is a schematic partial cross-sectional view of a track system **2200** with a shield assembly **2202** in accordance with yet another embodiment described herein. The shield assembly **2202** is a four piece shield assembly **2202** comprising an outer L-shaped stationary shield **2204** and an inner L-shaped stationary shield **2206** coupled with the supporting frame **1005**. The shield assembly **2202** further comprises a first u-shaped shield **2208** and a second u-shaped shield **2210** located in between the outer L-shaped stationary shield **2204** and the inner L-shaped stationary shield and coupled with the supporting frame **1005**. In one embodiment, the outer

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L-shaped stationary shield **2204** and the inner L-shaped stationary shield **2206** are coupled with a top plate of the supporting frame **1005**.

The outer L-shaped stationary shield **2204** is of unitary construction and comprises a cylindrical band **2212** dimensioned to encircle the outer guide rail **1007**. A rim **2214** extends radially outward from the top of the cylindrical band **2212** of the outer L-shaped stationary shield **2204**. The rim **2214** may have a plurality of holes for securing the outer L-shaped stationary shield **2204** to the supporting frame **1005**. The outer L-shaped stationary shield **2204** may be coupled with the supporting frame **1005** using, for example, rivets, screws, or any other attachment means known in the art. An inner lip **2216** extends radially inward from the bottom of the cylindrical band **2212** of the outer L-shaped stationary shield **2204**. The inner lip **2216** extends radially inward extending under an edge of the adapter plate **1817d** forming a labyrinth gap between the edge of the adapter plate **1817d** and the outer L-shaped stationary shield **2204**.

The inner L-shaped stationary shield **2206** is of unitary construction and comprises a cylindrical band **2220** dimensioned to fit within the inner diameter of the inner guide rail **1006**. A lip **2222** extends radially inward from the top of the cylindrical band **2220** of the inner L-shaped stationary shield **2206**. The lip **2222** may have a plurality of holes for securing the inner L-shaped stationary shield **2206** with the supporting frame **1005** using, for example, rivets, screws, or any other attachment means known in the art. An outer lip **2224** extends radially outward from the bottom of the cylindrical band **2220** of the inner L-shaped stationary shield **2206**. The outer lip **2224** extends radially outward extending under an edge of the adapter plate **1817d** forming a labyrinth gap between the edge of the adapter plate **1817d** and the inner L-shaped stationary shield **2206**.

The first u-shaped shield **2208** comprises an inner cylindrical band **2226**, an outer cylindrical band **2228**, and an annular band **2230**. The inner cylindrical band **2226** surrounds an outer periphery of the actuator assembly **1010**. The annular band **2230** extends radially outward from the bottom of the inner cylindrical band **2226**. The outer cylindrical band **2228** extends upward from the annular band **2230** to form the u-shaped channel. A lip **2232** extends radially inward from the top of the inner cylindrical band **2226** of the first u-shaped shield **2208**. The lip **2232** may have a plurality of holes for securing the first u-shaped shield **2208** with the supporting frame **1005** using, for example, rivets, screws, or any other attachment means known in the art.

The second u-shaped shield **2210** mirrors the first u-shaped shield **2208**. The second u-shaped shield **2210** comprises an outer cylindrical band **2234**, an inner cylindrical band **2236**, and an annular band **2238**. The outer cylindrical band **2234** surrounds an inner periphery of the actuator assembly **1010**. The annular band **2238** extends radially inward from the bottom of the outer cylindrical band **2234**. The inner cylindrical band **2236** extends upward from the annular band **2238** to form the u-shaped channel. A lip **2240** extends radially outward from the top of the outer cylindrical band **2234** of the second u-shaped shield **2210**. The lip **2240** may have a plurality of holes for securing the second u-shaped shield **2210** with the supporting frame **1005** using, for example, rivets, screws, or any other attachment means known in the art.

FIG. **23** is a schematic cross-sectional view of a track system **2300** with a shield assembly **2302** in accordance with yet another embodiment described herein. The shield assembly **2302** is a four piece shield assembly comprising the outer L-shaped stationary shield **2104** and the inner L-shaped stationary shield **2106** coupled with the supporting frame **1005**.

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The shield assembly **2302** further comprises a first shield **2308** and a second shield **2310** located in between the outer L-shaped stationary shield **2104** and the inner L-shaped stationary shield **2106** and coupled with the supporting frame **1005**. In one embodiment, the outer L-shaped stationary shield **2104** and the inner stationary L-shaped shield **2106** are coupled with a top plate of the support frame **1005**.

The outer L-shaped stationary shield **2104** and the inner L-shaped stationary shield **2106** are described above. The first shield **2308** comprises a cylindrical band **2312** that surrounds the outer periphery of the actuator assembly **1010**. A lip **2315** extends radially inward from the top of the cylindrical band **2312**. The second shield **2310** comprises a cylindrical band **2312** that is positioned in between an inner periphery of the actuator assembly **1010** and the inner guide rail **1006**. A lip **2316** extends radially outward from the cylindrical band **2314**.

Replaceable Seal for Guide Rails:

FIG. **24** is a perspective view of a guide block **1002** with a replaceable seal **2406** according to one embodiment described herein. The guide block **1002** has a sliding channel **1002a** shaped to straddle and slide over a guide rail **1007**. The guide block **1002** is movable in a longitudinal direction along the rail. The guide block **1002** comprises a block **2402** and end plates **2404**. The replaceable seal **2406** is arranged outside the end plates **2404** which are coupled with both ends of the block **2402**. The replaceable seal **2406** prevents foreign objects from the processing environment such as dirt and dust from entering the guide block **1002**. Further, the seal **2406** contains particles generated within the guide block **1002** thereby reducing any adverse impact on the process due to the sliding motion of the guide block **1002** along the guide rail **1007**.

FIG. **25A** is a perspective view of a replaceable seal **2406** according to one embodiment described herein. FIG. **25B** is a perspective rear view of the replaceable seal **2406** of FIG. **25A** according to one embodiment described herein. The replaceable seal comprises a backing plate **2510** and a seal member **2520**. The backing plate **2510** has an inner circumferential face **2512** forming a recessed portion **2514** to accommodate a guide rail **1007**. In one embodiment, the backing plate **2510** couples the seal member **2520** to the guide block **2402** while providing rigidity to the seal member **2520**. The seal member **2520** has an inner circumferential face **2522** forming a recessed portion **2524** which accommodates the guide rail **1007**. A stepped portion **2526** is formed at the intersection of the inner circumferential face **2512** of the backing plate **2510** and a first surface **2528** of the seal member **2520**. In one embodiment, the inner circumferential face **2522** of the seal member **2520** is offset from the inner circumferential face **2512** of the backing plate **2510** such that a distance between opposing sides of the inner circumferential face **2522** of the seal member **2520** is smaller than the distance between opposing sides of the inner circumferential face **2512** of the backing plate **2510**. In one embodiment, the seal member **2520** is compressible around the rail thus preventing dirt and debris along the guide rail **1007** from entering the guide block **2402**.

A second surface **2530** of the seal member **2520** opposing the first surface **2528** of the seal member **2520** has a series of holes **2532a**, **2532b**, and **2532c**. Coupling pins **2534a**, **2534b** extend through the holes **2532a** and **2532b** to couple the replaceable seal **2406** with the guide block **1002**. In one embodiment, the backing plate **2510** has holes **2533a**, **2533b**, and **2533c** corresponding to holes **2532a**, **2532b**, and **2532c** and the pins **2534a**, **2534b** also extend through the corresponding holes of the backing plate **2510** securing the seal



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member 2520 with the guide block 2402. Although only one seal member is shown, it should be understood that a plurality of seal members of varying thicknesses may be used. Other components such as isolator plates may also be used, for example, in embodiments comprising a plurality of seal members, isolator plates may be placed between each of the seal members.

In operation, the replaceable seal 2406 is uncoupled from the guide block 1002. Due to the proximity of the outer surface of the guide rail 1007 with the inner circumferential face of the 2512 of the backing plate 2510 and the inner circumferential face 2522 of the seal member, while coupled together, the backing plate 2510 and the seal member 2520 cannot be removed from the guide rail 1007. However, the two-piece design of the replaceable seal 2406 allows the uncoupling of the backing plate 2510 from the seal member 2520. After uncoupling the seal member 2520 from the backing plate 2510, the flexible seal member 2520 may be removed from the guide rail 1007 while the rigid backing plate 2510 remains on the guide rail 1007. The flexibility of the seal member 2520 allows removal of the seal member 2520 from the guide rail 1007. A new seal member may then be positioned to straddle the guide rail 1007. The new seal member is coupled with the backing plate 2510 to re-form the replaceable seal 2406 and the replaceable seal may be reattached to the guide block 1002.

FIG. 26 is a perspective view of another replaceable seal 2406 according to one embodiment described herein. The replaceable seal 2406 comprises a seal member 2520 coupled with two backing plates 2510a, 2510b. The backing plates 2510a, 2510b each have an inner circumferential face 2512a, 2512b forming a recessed portion 2514a, 2514b to accommodate the guide rail 1007. In one embodiment, the backing plates 2510a, 2510b are spaced apart. The backing plates 2510a, 2510b may each be individually coupled with the seal member 2520.

In operation, the seal member 2520 and backing plates 2510a, 2510b may be uncoupled from the guide rail 1007 while coupled together. In one embodiment, the backing plates 2510a, 2510b may be uncoupled from the seal member 2520 prior to uncoupling the seal member 2520 from the guide rail 1007.

In one embodiment, the replaceable seal 2406 comprises a seal member 2520 coupled with one or more backing plates 2510. In one embodiment, the replaceable seal 2406 is formed by forming the seal member 2520 around the backing plate 2510, for example, by molding the seal member 2520 on the backing plate 2510 using adhesives to form a unitary replaceable seal.

FIG. 27A is a perspective view of one embodiment of a backing plate 2510 according to one embodiment described herein. In this embodiment, the backing plate 2510 comprises a first support member 2710 and a second support member 2720 which are coupled together to form the backing plate 2510. The two piece backing plate 2510 may be easily removed from the guide rail 1007 and guide block 1002 of the circular track without disassembling the circular track assembly.

In the embodiment shown, the first support member 2710 and the second support member 2720 are coupled together with a hinge assembly 2730 and a plurality of locking clips 2740a, 2740b positioned on the first support member 2710 that are received by a plurality of clip catching ends (not shown) on the second support member 2720 locking the first support member 2710 and the second support member 2720 together to form the backing plate 2510. It should also be understood that any other means known for coupling the first

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support member 2710 with the second support member 2720 may also be used. The hinge assembly 2730 allows the first support member 2710 and the second support member 2720 to open as shown by arrow 2750.

FIG. 27B is a perspective view of another embodiment of a backing plate 2510 according to one embodiment described herein. In the embodiment shown, the first support member 2710 may be completely decoupled from the second support member 2720 as shown by arrow 2760. The first support member 2710 and the second support member 2720 are coupled together with a plurality of locking clips 2740a, 2740b, 2740c, 2740d positioned on the first support member 2710 that are received by a plurality of clip catching ends (not shown) on the second support member 2720 locking the first support member 2710 and the second support member 2720 together to form the backing plate 2510.

In one embodiment, the first support member 2710 and the second support member 2720 of the backing plate 2510 are not coupled together. In one embodiment, the first support member 2710 and the second support member 2720 are each individually coupled with the guide block 1002, effectively sandwiching the seal member between each support member 2710, 2720 and the guide block 1002.

FIG. 28 is an exploded perspective view of a replaceable seal 2406 according to another embodiment described herein. The backing plate 2510 fits within the seal member 2520 providing additional rigidity to the seal member 2520. In this embodiment, the backing plate 2510 has holes 2533a, 2533b, and 2533c to accommodate holes 2532a, 2532b, and 2532c of the seal member 2520.

In operation, the replaceable seal 2406 is uncoupled from the guide block 1002. Due to the proximity of the outer surface of the guide rail 1007 with the inner circumferential face of the 2512 of the backing plate 2510 and the inner circumferential face 2522 of the seal member 2520, while coupled together, the backing plate 2510 and the seal member 2520 cannot be removed from the guide rail 1007. However, the two-piece design of the replaceable seal 2406 allows the uncoupling of the backing plate 2510 from the seal member 2520. After uncoupling the seal member 2520 from the backing plate 2510, the flexible seal member 2520 may be removed from the guide rail 1007 and the two piece backing plate 2510 may also be removed from the guide rail 1007. A new seal member and a new backing plate may then be positioned to straddle the guide rail 1007. The new seal member is coupled with new the backing plate to re-form the replaceable seal 2406 and the replaceable seal may be reattached to the guide block 1002.

In one embodiment, the seal member 2520 may also comprise multiple pieces. For example, the seal member 2520 may be two pieces. However, the pieces of the seal member 2520 are compressed together such that there is no gap in the seal member after installation. In one embodiment, the multiple piece seal member is used with the multi-piece backing plate. In another embodiment, the multi-piece seal member is used with the unitary backing plate.

The backing plate 2510 may comprise metals compatible with process chemistries such as aluminum or stainless steel. The seal member 2520 may comprise rubber or any other elastic material, for example, synthetic rubber and fluoropolymer elastomer. In one embodiment, the seal member 2520 comprises a rubber material coated on a plate-shaped metal.

One way to increase system uptime is to develop hardware that is easily removed and replaced without significant modifications to the substrate fabrication system. Embodiments described herein increase system uptime by providing a



replaceable seal device that is easily removed from and easily installed on a circular track system with minimal system downtime. Advantageously, the replaceable seal or a portion of the replaceable seal may be removed from the guide rail of a circular track without disassembling the circular track itself. Circular Track Installation:

FIG. 29 is a schematic side view of a track polishing system 2900 with a guide assembly 2902 in accordance with one embodiment described herein. The track polishing system 2900 comprises a system frame 101 configured to provide support for an apparatus used in a polishing process.

The guide assembly 2902 is coupled with an upper portion of the system frame 101 and a processing platform 104 is installed on a lower portion of the system frame 101. In one embodiment, the upper system of the support frame 101 comprises a top plate 2912 and the guide assembly 2902 is coupled with the top plate 2912. In one embodiment, a number of components (not shown), such as electronic components are mounted on the top plate 2912. In another embodiment, the guide assembly 2902 may be coupled directly with the support frame 101. In one embodiment, the processing platform 104 may comprise a combination of modulated tools, such as polishing stations, load cups, and cleaning stations according to process requirement. Similar to FIG. 1, the processing platform 104 comprises one or more polishing stations 105.

In one embodiment, the guide assembly 2902 comprises a plate 2911 coupled with a track body 2910 defining a path along which the polishing heads 103 may move. The guide assembly 2902 further comprises one or more carriages 2909 movably connected to the track body 2910. Each of the one or more carriages 2909 is configured to carry at least one polishing head 103.

FIG. 30A illustrates a schematic bottom view of a guide assembly 3000 in accordance with one embodiment described herein. FIGS. 30B-30E illustrate schematic partial cross-sectional views of the guide assembly 3000 in accordance with embodiments described herein. FIG. 30C is a partial cross-sectional view taken along line 30C of FIG. 30A. Line 3020 represents the center axis of the guide assembly 3000. The guide assembly 3000 comprises a plate 3002 and a pair of concentric guide rails including an inner circular guide rail 3004, and an outer circular guide rail 3006 coupled with the plate 3002. In one embodiment, a plurality of pins 3024 may be used to secure the inner 3004 and outer guide rails 3006 to the plate 3002 for preventing the lateral movement of the inner and outer guide rails. In one embodiment the plate 3002 is an annular shaped plate. In one embodiment, the plate 3002 is an annular band shaped band. In one embodiment, the inner circular guide rail 3004 and the outer circular guide rail 3006 are concentric. A plurality of guide blocks 3008 may be coupled with both the inner circular guide rail 3004 and the outer circular guide rail 3006. The plate 3002 also has a plurality of holes 3010 for coupling the guide assembly with the system frame 101. In one embodiment the plate 3002 comprises a process compatible material such as aluminum, stainless steel or combinations thereof.

Referring to FIGS. 30B-30D, the guide assembly 3000 may also comprise an inner circular shoulder 3012 and an outer circular shoulder 3014 that provide a fixed reference for alignment of the inner circular guide rail 3004 and the outer circular guide rail 3006. The inner circular shoulder 3012 forms a step 3016 with a surface of the plate 3002. The step 3016 provides a fixed reference for the inner circular guide rail 3004. The outer circular shoulder 3014 forms a step 3018 with a surface of the plate 3002. The step 3018 provides a fixed reference for the outer circular guide rail 3006. The inner circular shoulder 3012 and outer circular shoulder 3014 may also help the inner circular guide rail 3004 and the outer circular guide rail 3006 withstand lateral forces.

Referring to FIG. 30E, in another embodiment, the guide assembly 3000 may further comprise a shoulder plate 3022 coupled with the plate 3002. The shoulder plate 3022 comprises an annular body defined by an inner circular shoulder 3028 and an outer circular shoulder 3030 that provide a fixed reference for alignment of the inner circular guide rail 3004 and the outer circular guide rail 3006. The inner circular shoulder 3028 forms a step 3032 with a surface of the plate 3002. The step 3032 provides a fixed reference for the inner circular guide rail 3004. The outer circular shoulder 3030 forms a step 3034 with a surface of the plate 3002. The step 3034 provides a fixed reference for the outer circular guide rail 3006. The inner circular shoulder 3028 and the outer circular shoulder 3030 may also help the inner circular guide rail 3004 and the outer circular guide rail 3006 withstand lateral forces.

Referring to FIG. 30F, in another embodiment, the plate 3002 has a raised portion 3040 that provides a fixed reference for alignment of the inner circular guide rail 3004 and the outer circular rail 3006. The raised portion 3040 is defined by inner circular shoulder 3042 and an outer circular shoulder 3044 that provide a fixed reference for alignment of the inner circular guide rail 3004 and the outer circular rail 3006.

In certain embodiments, the inner circular shoulder 3012 and the outer circular shoulder 3014 form a unitary body with the plate 3002. In certain embodiments, the inner circular shoulder 3012 and the outer circular shoulder 3014 are separate pieces that may be coupled with the plate 3002.

FIG. 30G illustrates a schematic cross-sectional view of a guide assembly 3000 in accordance with another embodiment described herein. The guide assembly 3000 depicted in FIG. 30G uses a two-piece wedge 3300 coupled with the plate 3002. The two-piece wedge 3300 may be positioned along the inner diameter of the outer circular guide rail 3006. When positioned along the inner diameter of the outer circular guide rail 3006 the two-piece wedge 3300 reduces lateral movement of the guide rail 3006. The two-piece wedge 3300 comprises a fixed wedge piece 3032 coupled with the body of the guide assembly 3002 and an adjustable wedge piece 3034 that may be adjustably coupled with the guide assembly 3002. The fixed wedge piece 3032 has a slanted mating surface that fits with a corresponding slanted mating surface 3036 of the adjustable wedge piece 3034. In one embodiment, a second two-piece wedge assembly may be positioned along the inner diameter of the inner circular guide rail 3004 with an inner circular shoulder positioned along the outer diameter of the inner circular guide rail 3004. In another embodiment, a first two-piece wedge assembly may be positioned along the outer diameter of the inner circular guide rail 3004 and a second two-piece wedge assembly may be positioned along the outer diameter of the outer circular with fixed circular shoulder positioned on the opposite side of each guide rail. In yet another embodiment, a two-piece wedge assembly may be positioned along either the outer diameter of the inner circular guide rail 3004 and a second two-piece wedge assembly may be positioned along the inner diameter of the outer circular with fixed circular shoulder positioned on the opposite side of each guide rail.

In one embodiment, as shown in FIG. 30B, the inner circular shoulder 3012 is positioned along the inner diameter of the inner circular guide rail 3004 and the outer circular shoulder is positioned along the inner diameter of the outer circular guide rail 3006. In another embodiment, as shown in FIG. 30C, the inner circular shoulder 3012 is positioned along the inner diameter of the inner circular guide rail 3004 and the outer circular shoulder is positioned along the outer diameter of the outer circular guide rail 3006. In yet another embodiment, the inner circular shoulder 3012 is positioned along the outer diameter of the inner circular guide rail 3004 and the

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outer circular shoulder **3014** is positioned along the inner diameter of the outer circular guide rail **3006**.

FIG. **31** illustrates a perspective view a guide assembly coupled with a top plate **2912** in accordance with one embodiment described herein. The top plate **2912** and guide assembly **3000** may be coupled with an upper portion of a system frame such as system frame **101** and a processing platform **104**. Two concentric guiding rails **3004**, **3006**, are coupled with the guide assembly **3000**. A linear motor magnet track **3104** is coupled with the guide assembly. In one embodiment, the linear motor magnet track is dimensioned to have a width such that the linear motor magnet track **3104** functions as a fixed reference for placement of the inner circular guide rail **3004** and the outer circular guide rail **3006**. In one embodiment, an encoder scale **3106** may be coupled with the guide assembly **3000**. In another embodiment, the encoder scale **3106** may be coupled with the top plate. An adapter assembly **3108** comprising guide blocks **3008** and an adapter plate **3110** may be coupled with the inner circular guide rail **3004** and the outer circular guide rail **3006**.

Typically, the installation of a circular track assembly into a track polishing system comprises several steps. Six inner guide segments with guide blocks are coupled directly with a top plate of the track polishing system. Six outer guide segments with guide blocks are then coupled directly with the top plate of the track polishing system. Alignment blocks are installed on the inner and outer sides of the inner and outer guide segments. The inner guide segments are aligned with each other using set screws on the alignment blocks. The outer guide segments are aligned with each other and the with the inner guide segment using set screws on the alignment blocks. An adapter assembly and an encoder scale are installed on the track polishing system. The encoder scale is aligned with the encoder read head. A linear motor magnet track is installed and aligned with the linear motor coil.

FIG. **32** illustrates a process sequence **3200** for the installation of a guide assembly into a track polishing system. A top plate **2912** coupled with a supporting frame is provided (block **3202**). A guide assembly **300** comprising inner **304** and outer circular guide rails **306** is coupled with the top plate **2912** (block **3204**). An adapter assembly **3108** is coupled with the guide assembly **3000** (block **3206**). An encoder scale **3106** is coupled with the guide assembly **2902** (block **3208**). In one embodiment the encoder scale is coupled with the top plate **2912**. The encoder scale **3106** is aligned with a sensor assembly (block **3210**). In one embodiment, the sensor assembly comprises an encoder reader head to read the encoder scale. A linear motor magnet track is aligned with a linear motor magnet coil (block **3212**). The linear motor magnet track is coupled with the guide assembly **3000** (block **3214**).

One way to increase system uptime is to develop hardware that is easily removed and replaced without significant modifications to the substrate fabrication system. Embodiments described herein increase system uptime by providing a guide assembly that is easily removed from a circular track system with minimal system downtime. Advantageously, the guide assembly and the inner circular guide and/or the outer circular guide may be removed from the support frame of the circular track system without disassembling the circular track system. Further, the alignment and mounting of the inner and outer circular guide on the guide assembly may be performed by the manufacturer thus increasing the repeatability of the alignment and set up of the guides from tool to tool.

While the foregoing is directed to embodiments described herein, other and further embodiments of the invention may be devised without departing from the basic scope thereof, and the scope thereof is determined by the claims that follow.

What is claimed is:

1. A track system configured to transfer polishing heads in a polishing system, comprising:

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a supporting frame;

a track coupled to the supporting frame and defining a path along which the polishing heads are configured to move; and

one or more carriages configured to carry at least one polishing head along the path defined by the track, wherein the one or more carriages are coupled to the track and independently movable along the track, wherein the track comprises a stator strip disposed along the path, and each of the one or more carriages comprises a rotor configured to move and stop the respective carriage by reacting with the stator strip.

2. The track system of claim 1, wherein the stator strip comprises a plurality of permanent magnetic segments, and the rotor of each carriage comprises a segment motor facing the plurality of permanent magnetic segments.

3. The track system of claim 1, wherein the track further comprises a guiding rail disposed along the stator strip, and each of the one or more carriages comprises one or more guiding blocks which movably couple the respective carriage to the guiding rail and restrict movements of the respective carriage within the path.

4. The track system of claim 3, wherein each of the guiding rail and the stator strip form a closed loop.

5. The track system of claim 1, wherein the stator strip is circular, and the track further comprises:

a first circular guiding rail disposed concentric to the stator strip; and

a second circular guiding rail disposed concentric to the stator strip, and each of the one or more carriages comprises four guiding blocks which movably couple the respective carriage to the first and second guiding rails and restrict movements of the respective carriage within the path.

6. The track system of claim 5, wherein the first circular guiding rail has a diameter larger than a diameter of the stator strip, the second circular guiding rail has a diameter smaller than the diameter of the stator strip, and each of the one or more carriages is configured to carry one or more polishing head between the first and second circular guiding rails.

7. The track system of claim 1, wherein the track further comprises an encoder scale disposed along the path, and each of the one or more carriages comprises an encoder sensor facing the encoder scale and configured to sense a position of the respective carriage in the path.

8. The track system of claim 7, further comprising a carriage controller connected with the encoder sensor and configured to independently control movements of the respective carriage according to measurements from the encoder sensor.

9. A track system configured to transfer polishing heads in a polishing system, comprising:

a supporting frame;

a track coupled to the supporting frame and defining a path along which the polishing heads are configured to move; one or more carriages configured to carry at least one polishing head along the path defined by the track, wherein the one or more carriages are coupled to the track and independently movable along the track; and a shield assembly coupled with the supporting frame and isolating the track from a processing environment.

10. A method for polishing semiconductor substrates, comprising:

loading a substrate onto a polishing head configured to transfer the substrate among loading, unloading and polishing stations;

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moving the polishing head along a track system to a first polishing station, wherein the system comprises:

a supporting frame;

a track coupled to the supporting frame and defining a circular path along which the polishing heads have access to the loading, unloading and polishing stations; and

one or more carriages configured to carry at least one polishing head along the path defined by the track, wherein the one or more carriages are coupled to the track and independently movable along the track; and

polishing the substrate at the first polishing station, wherein the track comprises a circular stator strip comprising a plurality of magnetic segments disposed along the circular path, and each of the one or more carriages comprises a segment motor configured to move and stop the respective carriage by reacting with the plurality of permanent magnetic segments.

11. The method of claim 10, wherein polishing the substrate comprises oscillating the polishing head along the track.

12. A polishing head for a polishing system having a track, comprising:

a carriage body;

one or more guide blocks mounted on the carriage body, wherein the one or more guide blocks are configured to couple with a track and restrict movements of the carriage body to along the track;

a sliding actuator connected to the carriage body and configured to move the carriage body along the track;

a first polishing motor connected with the carriage body, wherein the first polishing motor is moved with the movement of the carriage body;

a first substrate carrier configured to secure a substrate during transferring and polishing, wherein the first substrate carrier is coupled to the first polishing motor and rotated by the first polishing motor during polishing; and a sensor assembly disposed on the carriage body, wherein the sensor assembly is configured to measure a position of the polishing head on the track.

13. The polishing head of claim 12, wherein the track is a circular track and the one or more guide blocks have curved sliding channels configured to adapt to a curvature of the circular track.

14. The polishing head of claim 12, wherein the sliding actuator is a segment motor configured to move the carriage body by reacting with a plurality of permanent magnetic segments disposed along the track.

15. The polishing head of claim 14, wherein the sliding actuator is further configured to oscillate the carriage body about a position on the track to provide sweeping motion to the first substrate carrier during polishing.

16. The polishing head of claim 14, further comprising a sweeping actuator connected to the carriage body and configured to oscillate the carriage body about a position on the track to provide sweeping motion to the first substrate carrier during polishing, wherein the sweeping actuator is a segment motor that oscillates the carriage body by reacting with the plurality of permanent magnetic segments disposed along the track.

17. The polishing head of claim 12, further comprising: a second polishing motor connected with the carriage body, wherein the second polishing motor is moved with the movement of the carriage body; and

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a second substrate carrier configured to secure a substrate during transferring and polishing, wherein the second substrate carrier is coupled to the second polishing motor and rotated by the second polishing motor during polishing.

18. The polishing head of claim 17, further comprising a first sweeping actuator connected to the carriage body and configured to oscillate the carriage body about a position on the track to provide sweeping motion to the first and second substrate carriers during polishing.

19. The polishing head of claim 17, further comprising:

a first sweeping actuator connected between the carriage body and the first polishing motor, wherein the first sweeping actuator is configured to oscillate first polishing motor about a position on the track to provide sweeping motion to the first substrate carrier during polishing; and

a second sweeping actuator connected between the carriage body and the second polishing motor, wherein the second sweeping actuator is configured to oscillate the second polishing motor about a position on the track to provide sweeping motion to the second substrate carrier during polishing.

20. A polishing head for a polishing system having a track, comprising:

a carriage body;

one or more guide blocks mounted on the carriage body, wherein the one or more guide blocks are configured to couple with a track and restrict movements of the carriage body to along the track;

a sliding actuator connected to the carriage body and configured to move the carriage body along the track;

a first polishing motor connected with the carriage body, wherein the first polishing motor is moved with the movement of the carriage body; and

a first substrate carrier configured to secure a substrate during transferring and polishing, wherein the first substrate carrier is coupled to the first polishing motor and rotated by the first polishing motor during polishing, the carriage body comprises a C shape body wrapping around a section of the track, the one or more guide blocks are mounted on an upper portion of the C shape body, and the first polishing motor is mounted on a lower portion of the C shape body.

21. A polishing head for a polishing system having a track, comprising:

a carriage body;

one or more guide blocks mounted on the carriage body, wherein the one or more guide blocks are configured to couple with a track and restrict movements of the carriage body to along the track;

a sliding actuator connected to the carriage body and configured to move the carriage body along the track;

a first polishing motor connected with the carriage body, wherein the first polishing motor is moved with the movement of the carriage body; and

a first substrate carrier configured to secure a substrate during transferring and polishing, wherein the first substrate carrier is coupled to the first polishing motor and rotated by the first polishing motor during polishing, the carriage body comprises a cantilever body, the one or more guide blocks are mounted on one end of the cantilever body, and the first polishing motor is mounted on an opposite end of the cantilever body.

\* \* \* \* \*

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

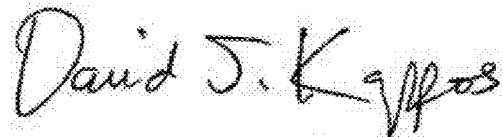
PATENT NO. : 8,172,643 B2  
APPLICATION NO. : 12/420996  
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INVENTOR(S) : Yilmaz et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 4, Line 3, delete “unshaped” and insert --u-shaped-- therefor.

Signed and Sealed this  
Twenty-eighth Day of August, 2012

A handwritten signature in black ink that reads "David J. Kappos". The signature is written in a cursive, flowing style with a large initial 'D' and a stylized 'K'.

David J. Kappos  
*Director of the United States Patent and Trademark Office*